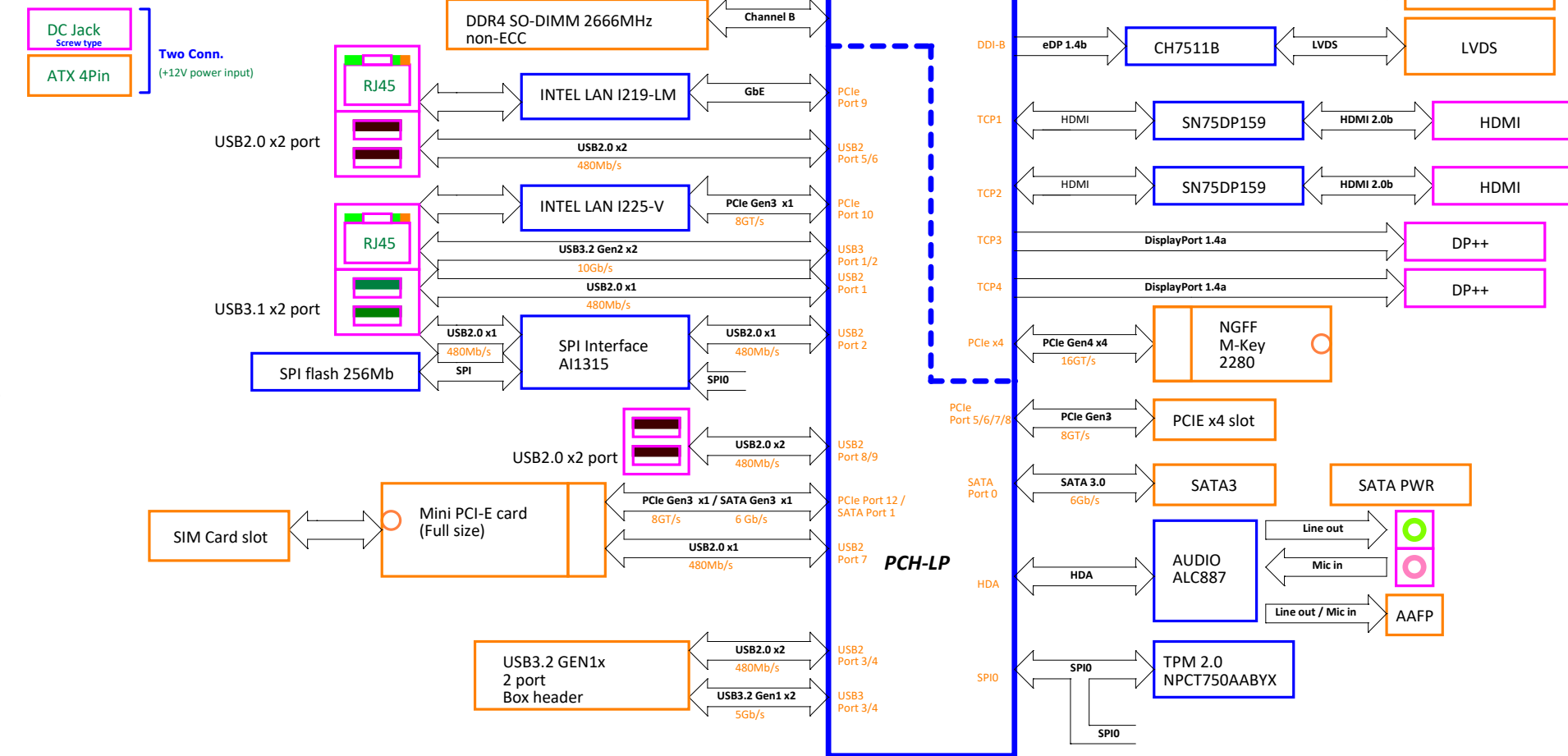


MIX-TLUD1 Rev 1.00

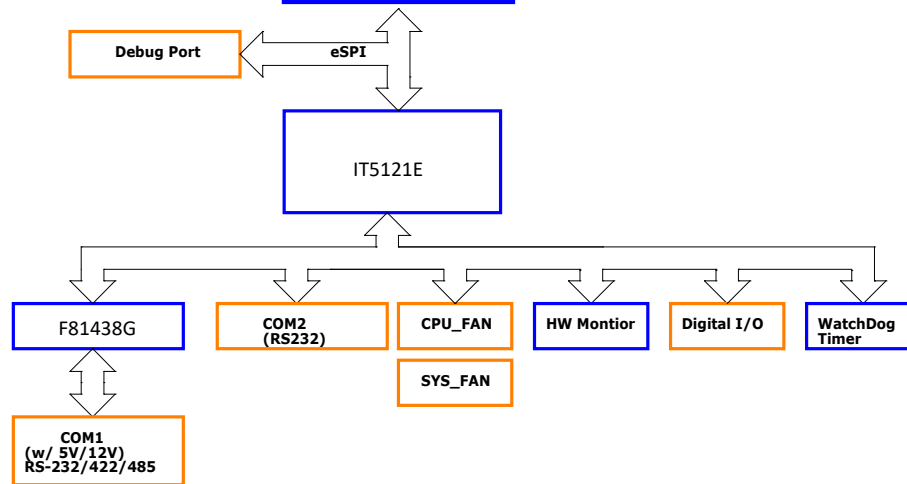


TIGER LAKE-UP3 PCH-LP HSIO LANE ASSIGNMENTS

0	1	2	3	4	5	6	7	8	9	10	11
PCIe 3.0 x1	PCIe 3.0 x2	PCIe 3.0 x3	PCIe 3.0 x4	PCIe 3.0 x5	PCIe 3.0 x6	PCIe 3.0 x7	PCIe 3.0 x8	PCIe 3.0 x9	PCIe 3.0 x10	PCIe 3.0 x11	PCIe 3.0 x12
USB3 (1000) #1	USB3 (1000) #2	USB3 (1000) #3	USB3 (1000) #4	USB3 (1000) #5	USB3 (1000) #6	USB3 (1000) #7	USB3 (1000) #8	USB3 (1000) #9	USB3 (1000) #10	USB3 (1000) #11	USB3 (1000) #12
PCIe X4	PCIe X4	PCIe X4	PCIe X4	PCIe X4	PCIe X4	PCIe X4	PCIe X4	PCIe X4	PCIe X4	PCIe X4	PCIe X4
X2	X2	X2	X2	X2	X2	X2	X2	X2	X2	X2	X2

PCIe support up to 12 lanes with up to 6 PCIe root-ports (devices).

Final configuration will be based on SKU

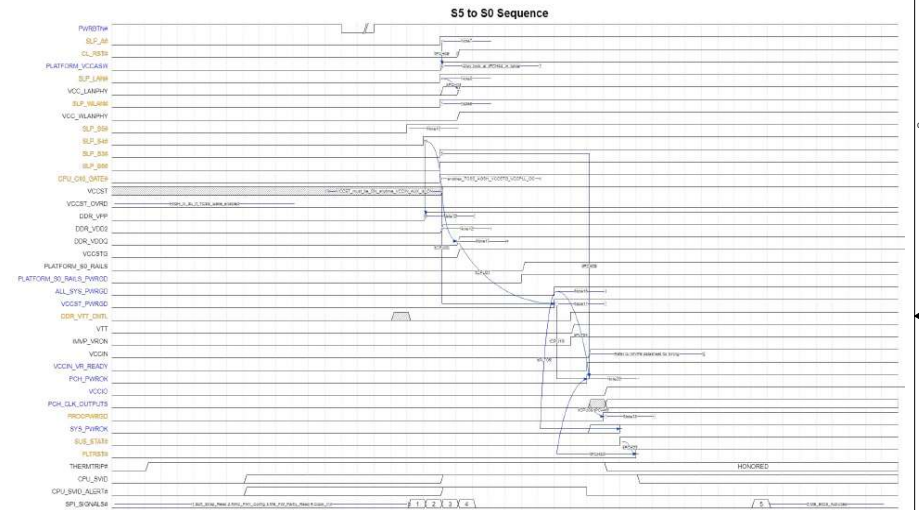
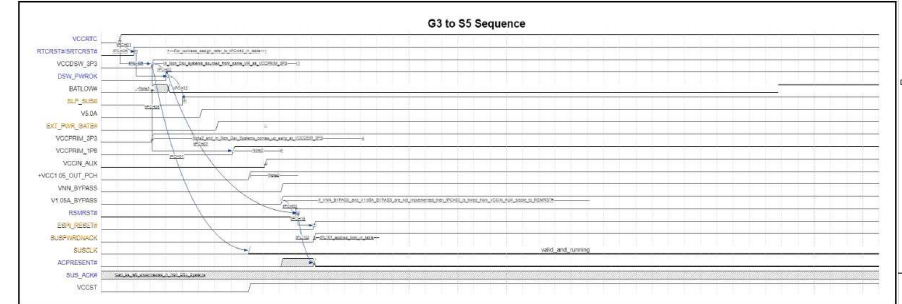
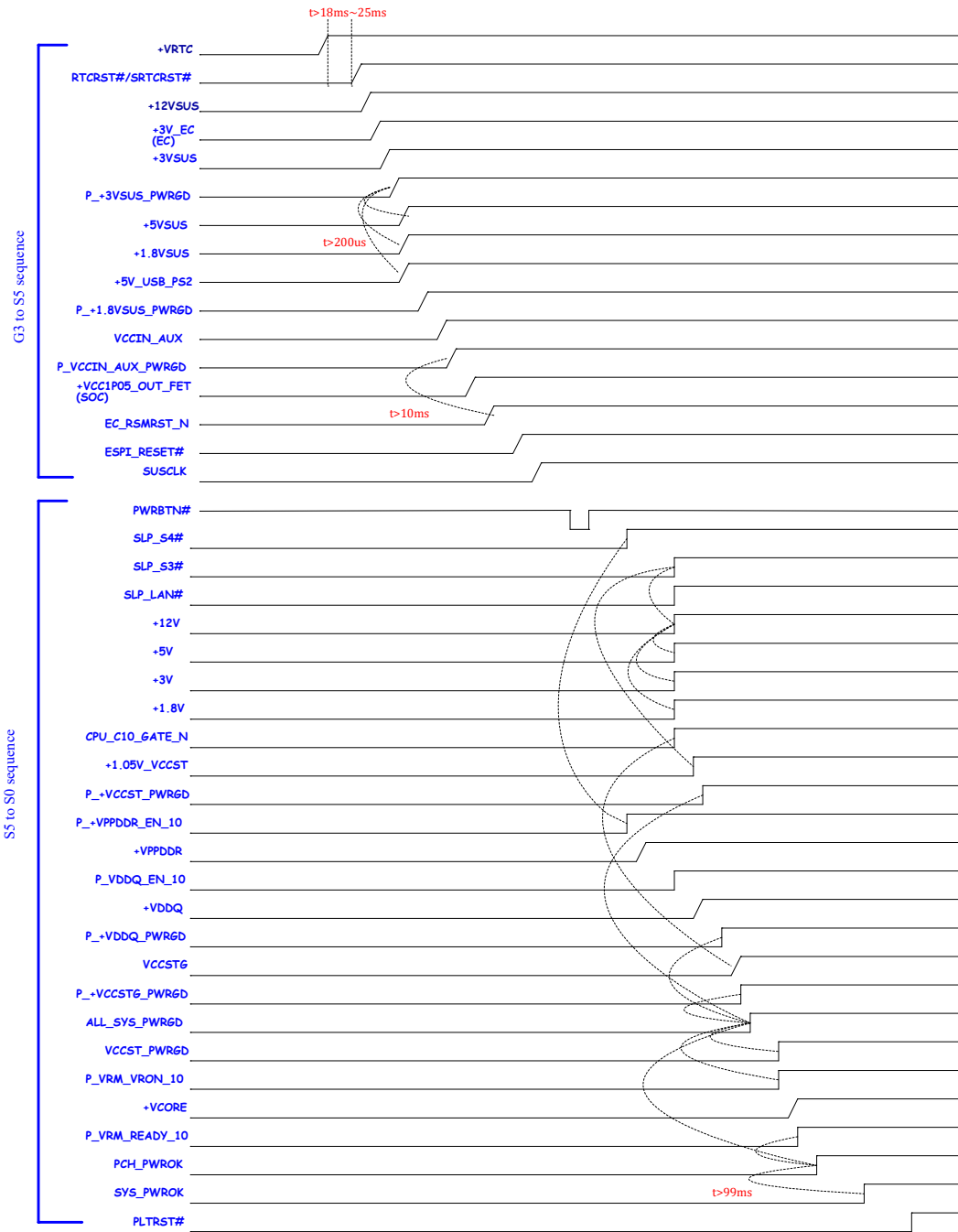


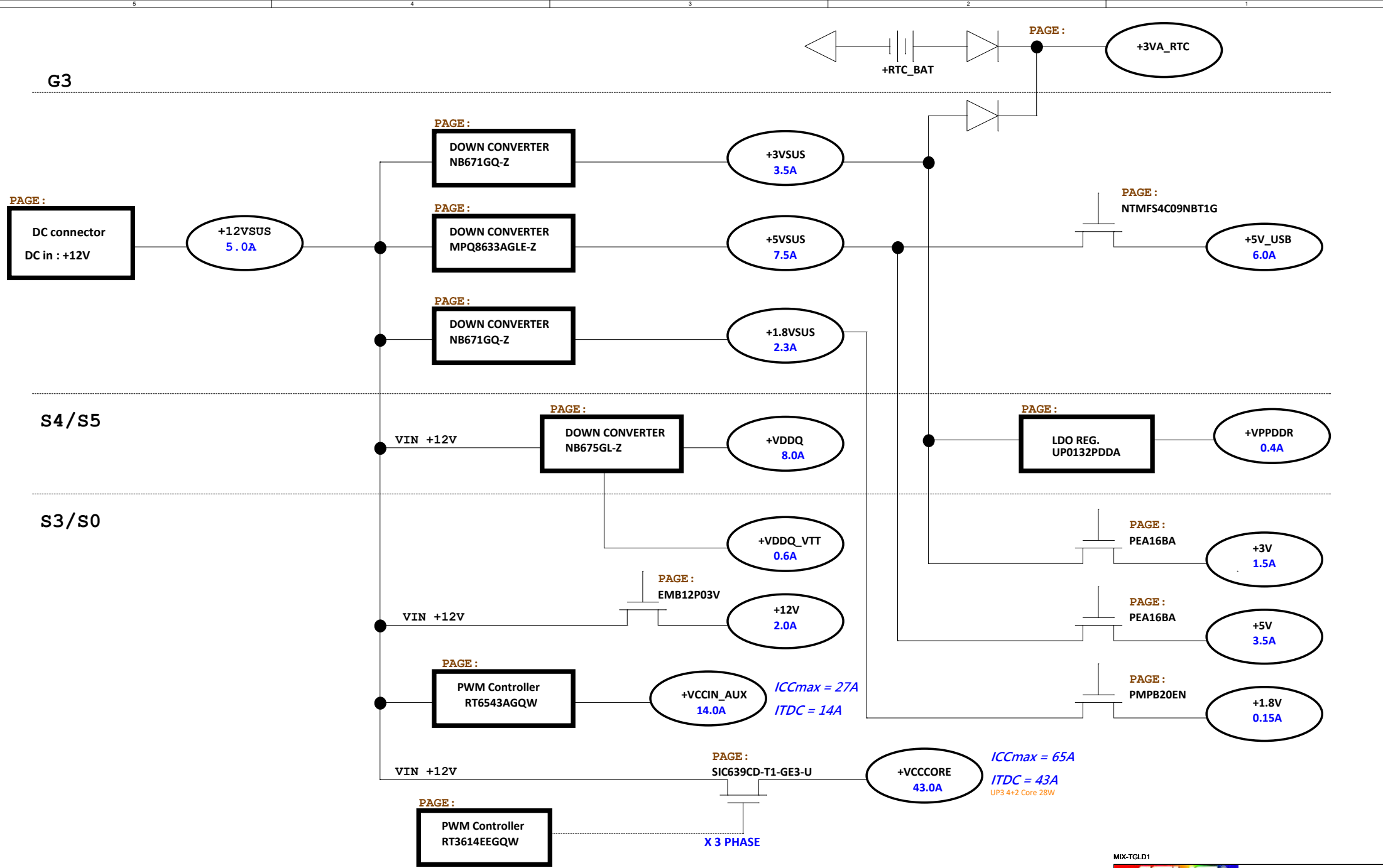
External Connector

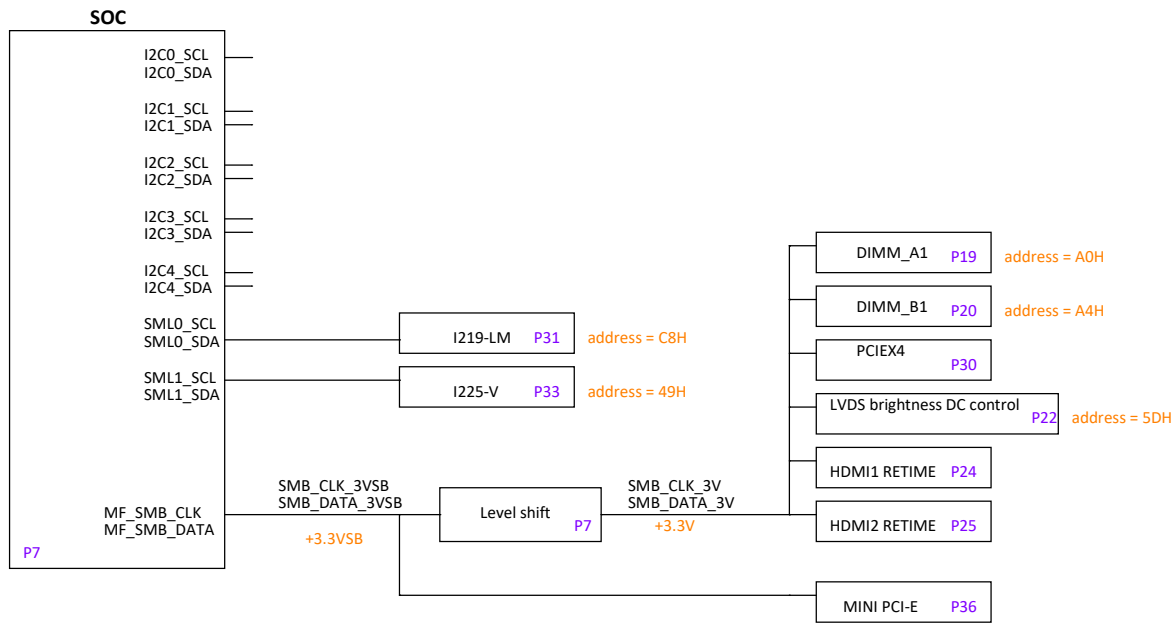
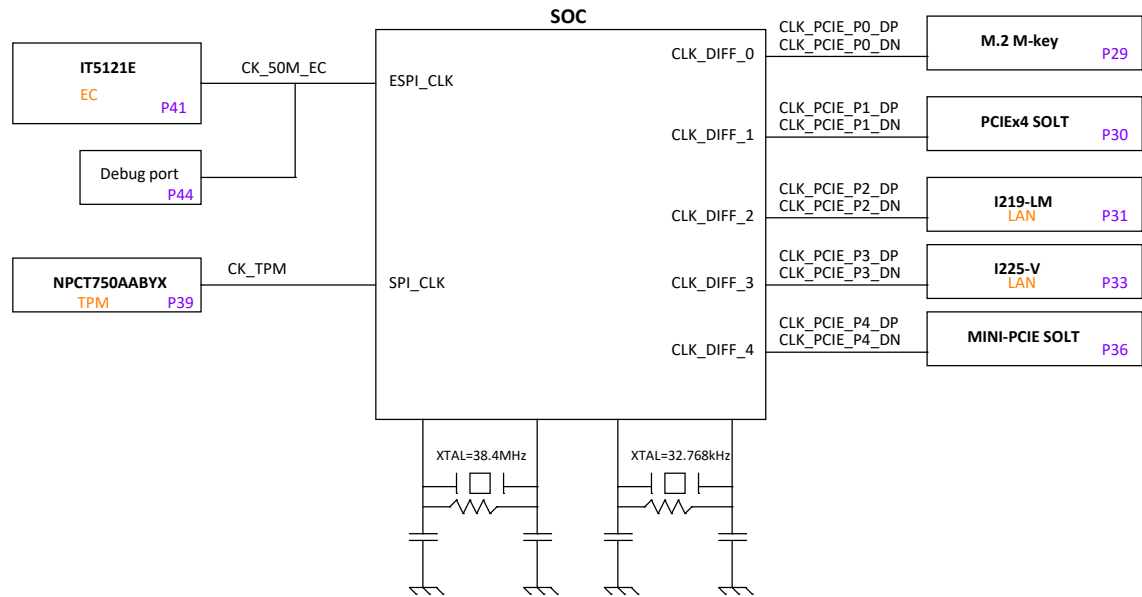
Internal Connector

MIX-TGLD1

Tiger Lake G3 to S0 power on sequence (Non-Deep Sx Platform)

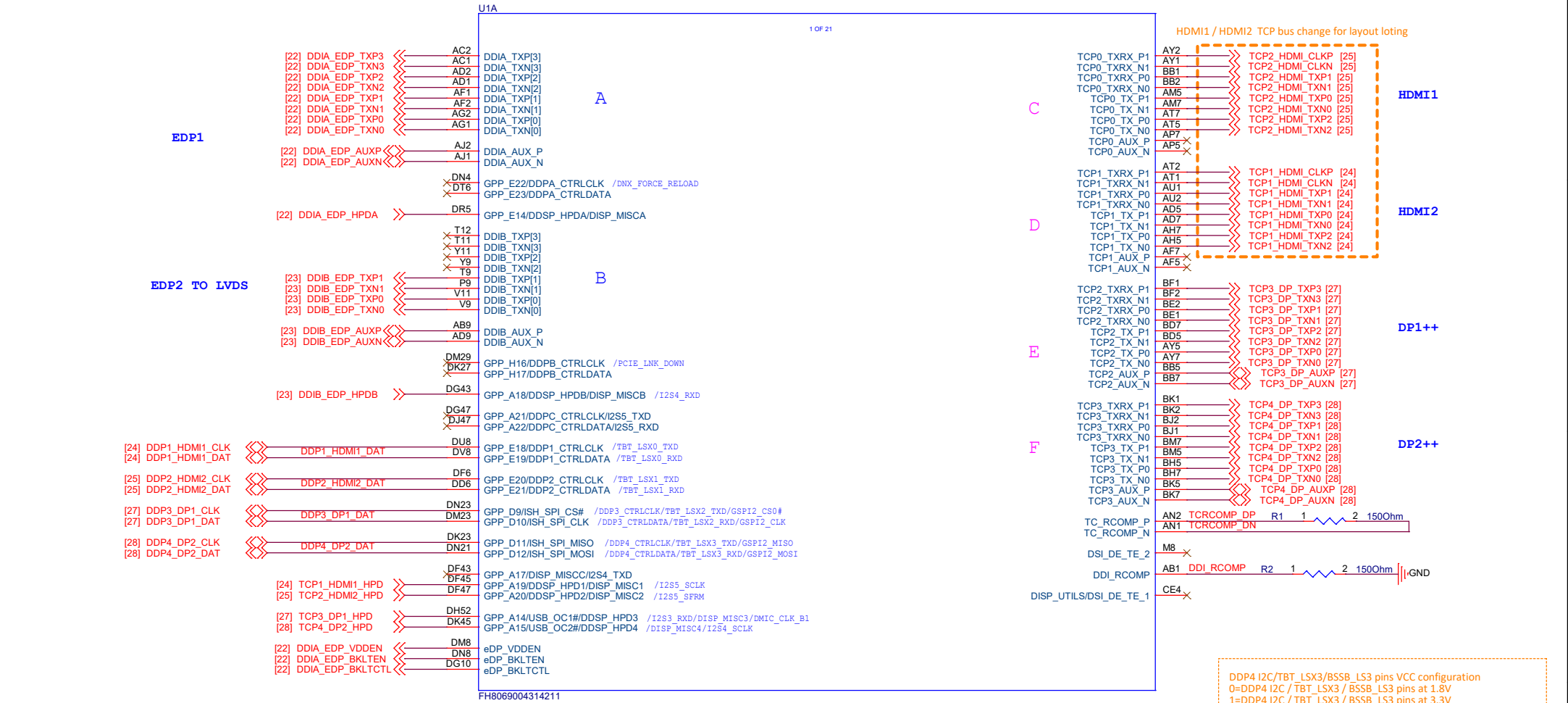




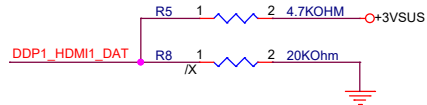


MIX-TGLD1

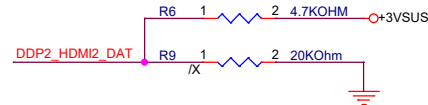
ASUS		Title : CLK DISTRIBUTION	
ASUSTek COMPUTER INC.		Engineer: <OrgAddr>	
Size	Project Name	Rev	
A3	MIX-TLUD1	R1.00	
Date: Wednesday, September 09, 2020	Sheet	4	of 59



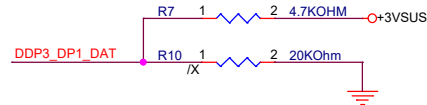
DDP1 I2C/TBT_LSX0/BSSB_L50 pins VCC configuration
0=DDP1 I2C / TBT_LSX0 / BSSB_L50 pins at 1.8V
1=DDP1 I2C / TBT_LSX0 / BSSB_L50 pins at 3.3V



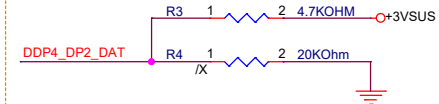
DDP2 I2C/TBT_LSX1/BSSB_L51 pins VCC configuration
0=DDP2 I2C / TBT_LSX1 / BSSB_L51 pins at 1.8V
1=DDP2 I2C / TBT_LSX1 / BSSB_L51 pins at 3.3V



DDP3 I2C/TBT_LSX2/BSSB_L52 pins VCC configuration
0=DDP3 I2C / TBT_LSX2 / BSSB_L52 pins at 1.8V
1=DDP3 I2C / TBT_LSX2 / BSSB_L52 pins at 3.3V



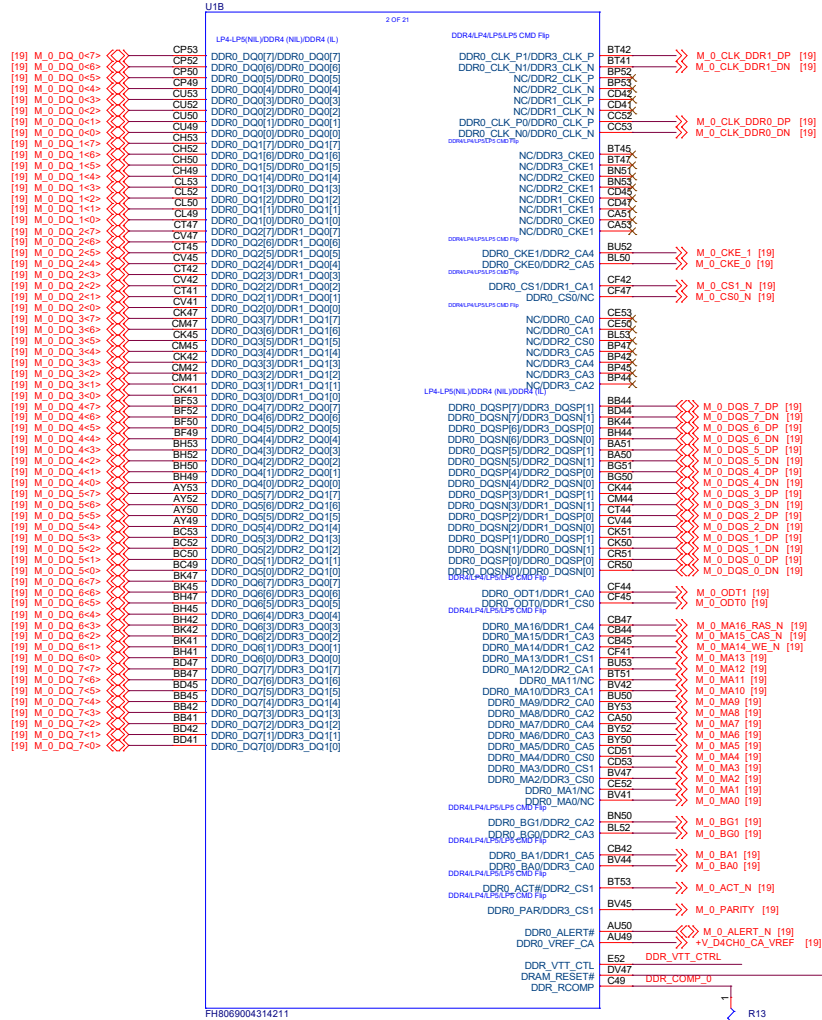
DDP4 I2C/TBT_LSX3/BSSB_L53 pins VCC configuration
0=DDP4 I2C / TBT_LSX3 / BSSB_L53 pins at 1.8V
1=DDP4 I2C / TBT_LSX3 / BSSB_L53 pins at 3.3V

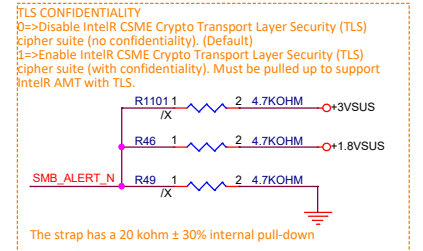
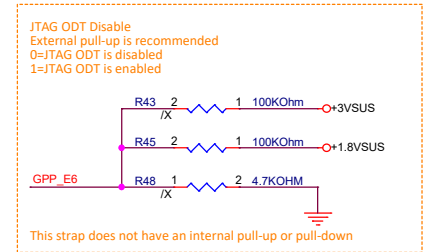
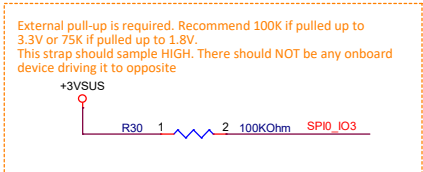
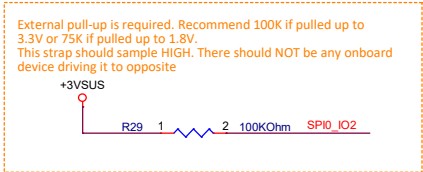
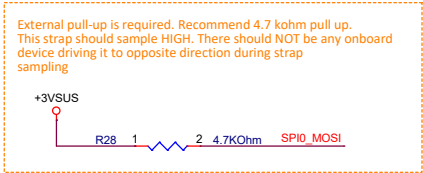


MIX-TGLD1

ASUS		Title : SOC-DISPLAY (DDI/TPC)	
ASUSTek COMPUTER INC.		Engineer:	
Size B	Project Name MIX-TLUD1	Rev R1.00	
Date: Wednesday, September 09, 2020		Sheet 5 of 59	

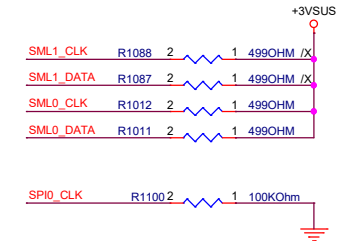
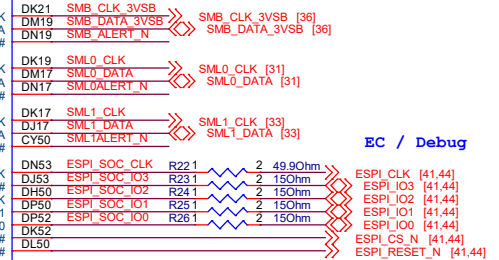
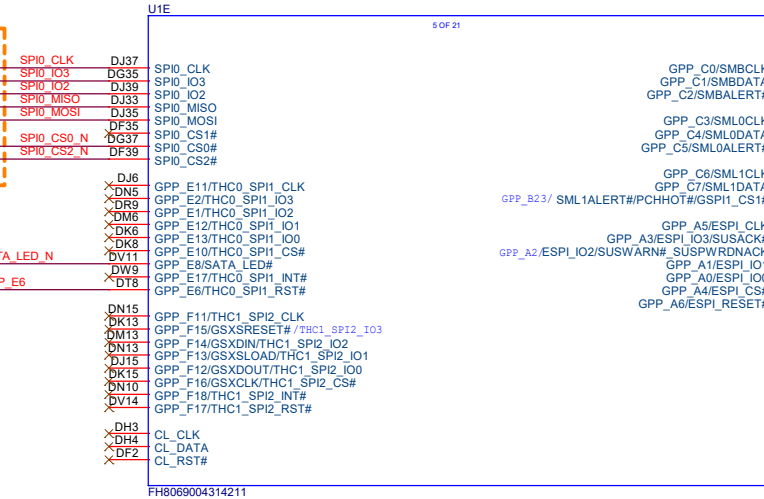
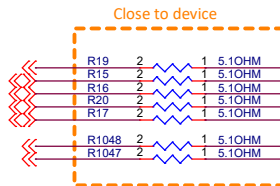
TGL-U - MEMORY CHANNEL - A



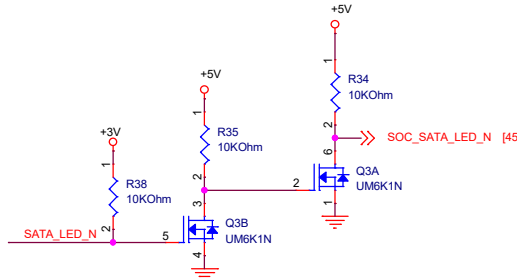
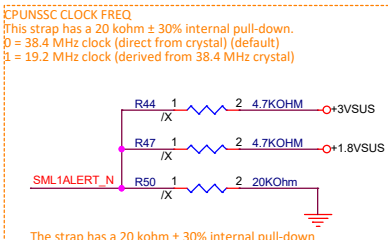
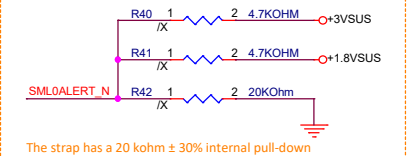


Flash/TPM

[39,44] SPI0_BIOS_TPM_CLK
[44] SPI0_BIOS_TPM_IO3
[44] SPI0_BIOS_TPM_IO2
[39,44] SPI0_BIOS_TPM_MISO
[39,44] SPI0_BIOS_TPM_MOSI
[44] SPI0_BIOS_TPM_CS0_N
[39] SPI0_BIOS_TPM_CS2_N

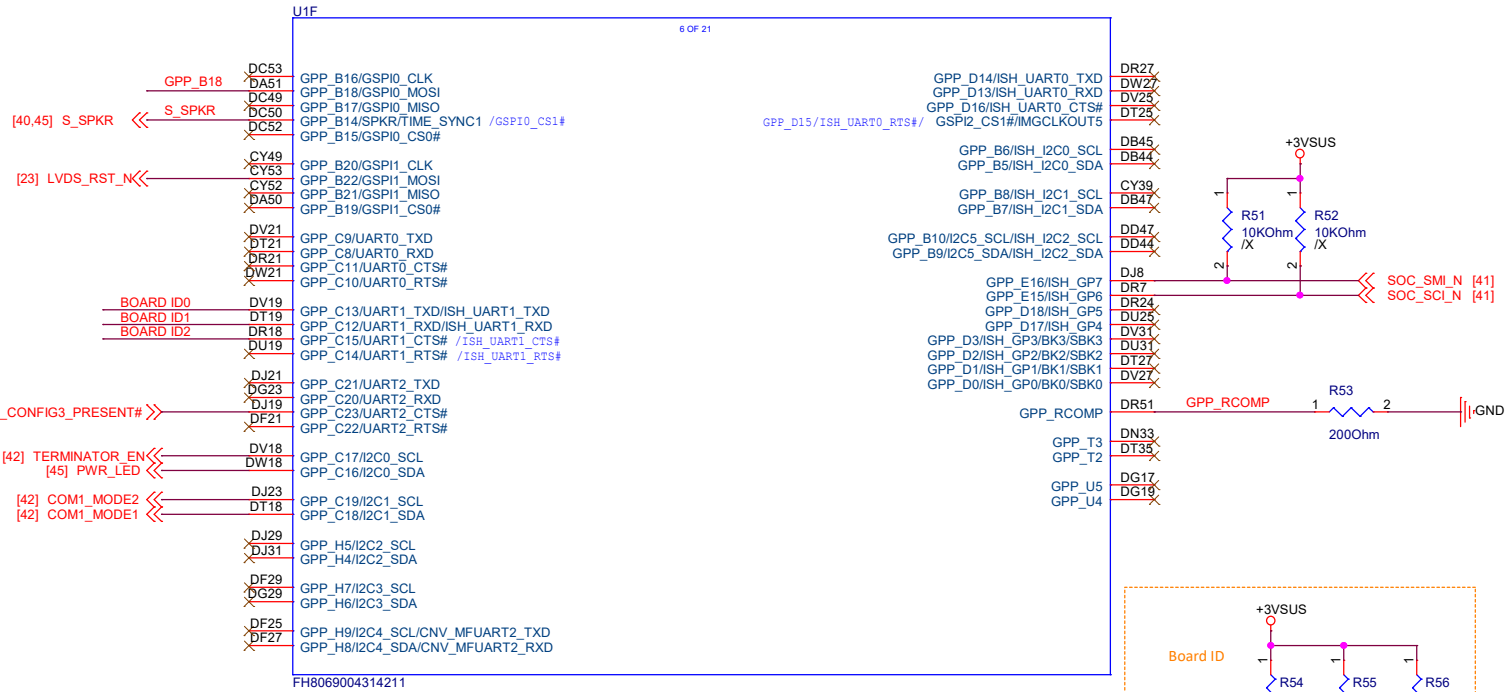


This is bit 0 (LSB) of a total of 4-bit encoded pin straps for boot configuration.
This strap is used in conjunction with Boot Strap 1,2,3, (on GPP_H0, GPP_H1, GPP_H2 respectively).
4-bit boot strap configuration encodings:
0000 = Master Attached Flash Configuration (BIOS / CSME on SPI). eSPI is enabled
0010 = Master Attached Flash Configuration (BIOS / CSME on SPI). eSPI is disabled
0100 = BIOS on eSPI Peripheral Channel; CSME on master attached SPI
1000 = Slave Attached Flash Configuration (BIOS / CSME on eSPI attached device).
1100 = BIOS on eSPI peripheral Channel; CSME on slave attached SPI.
Others: Reserved

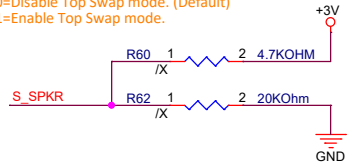


MIX-TGLD1

ASUS		Title : SOC-ESPI/SPI/SMBUS	
ASUSTek COMPUTER INC.		Engineer:	
Size	Project Name	Rev	
Custom	MIX-TLUD1	R1.00	
Date:	Wednesday, September 09, 2020	Sheet	7 of 59

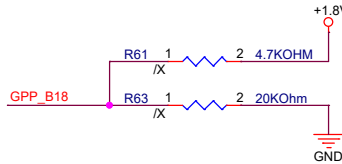


Top Swap Override
This inverts an address on access to SPI and firmware hub
0=Disable Top Swap mode. (Default)
1=Enable Top Swap mode.

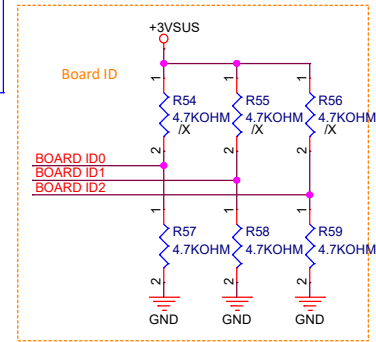


The strap has a 20 kohm ± 30% internal pull-down

NO REBOOT
0=>Disable "No Reboot" mode. (Default)
1=>Enable "No Reboot" mode (PCH will disable the TCO
Timersystem reboot feature). This function is useful when running ITP/XDP.

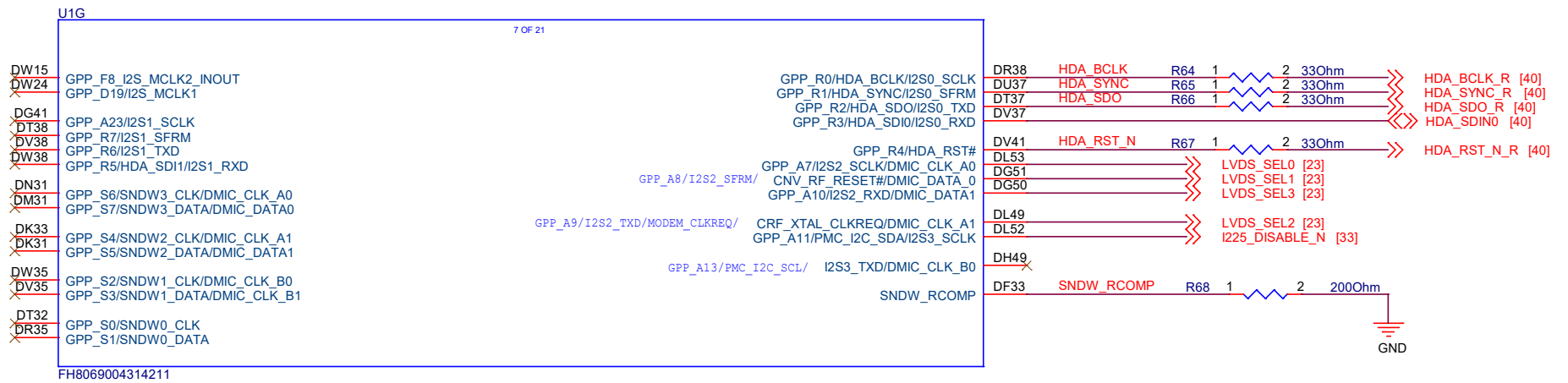


The strap has a 20 kohm ± 30% internal pull-down

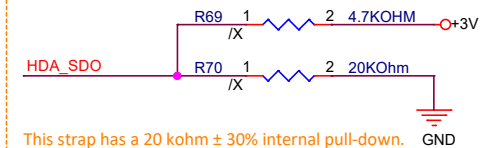


MIX-TGLD1

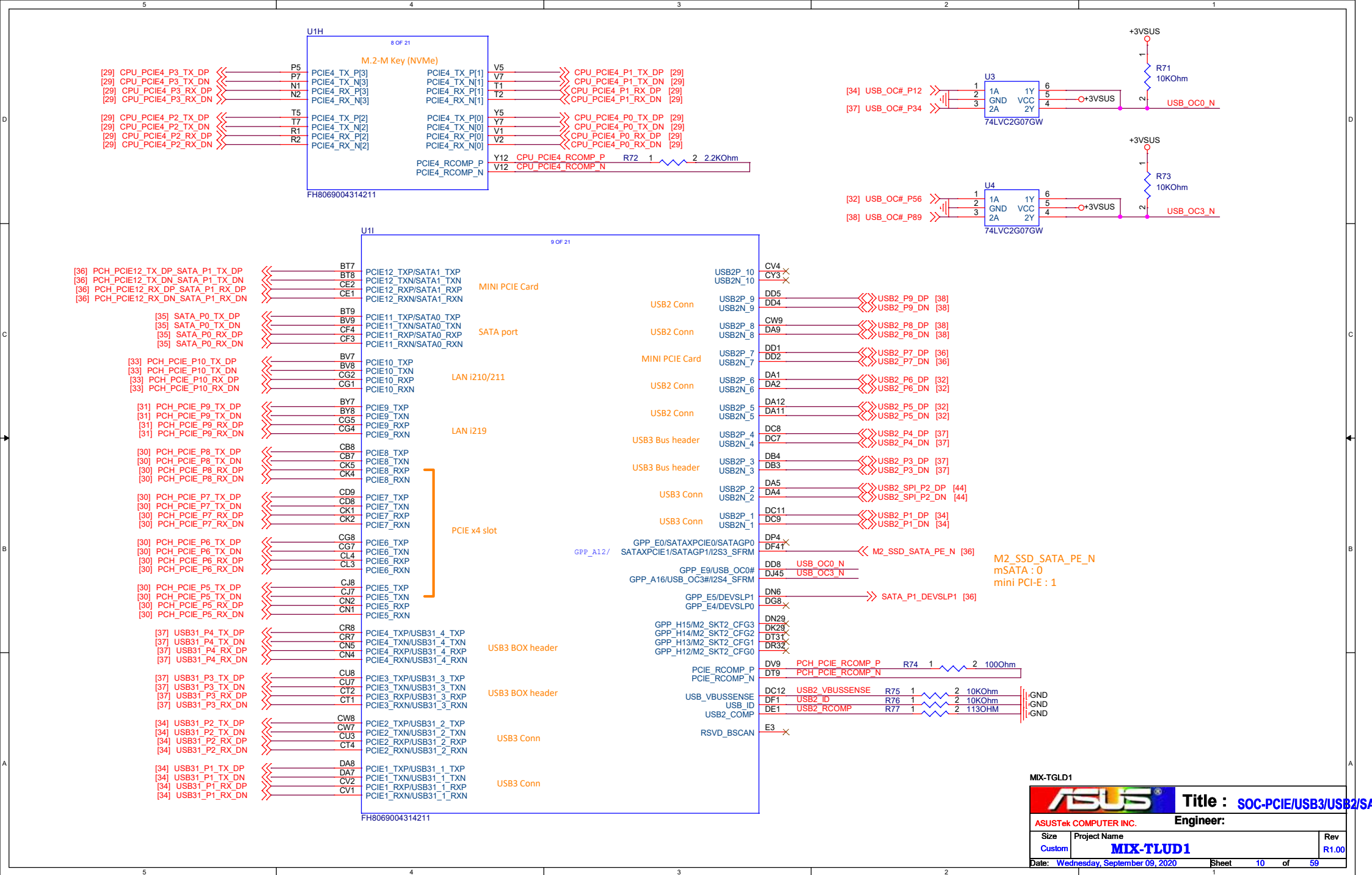
ASUS		Title : SOC-GSPI/I2C/UART	
ASUSTek COMPUTER INC.		Engineer:	
Size B	Project Name MIX-TLUD1		Rev R1.00
Date: Wednesday, September 09, 2020		Sheet 8 of 59	

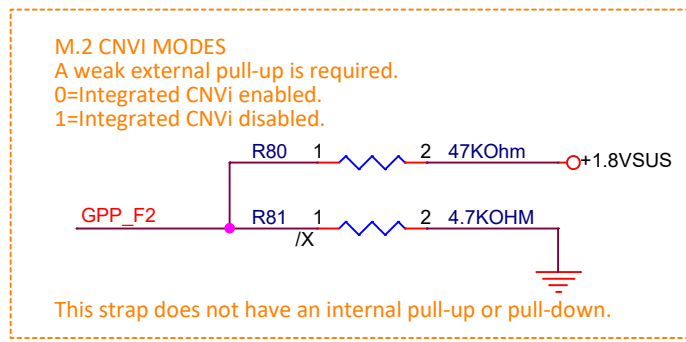
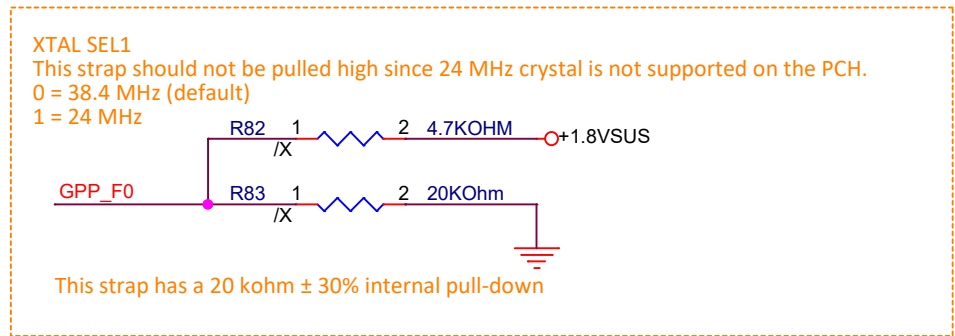
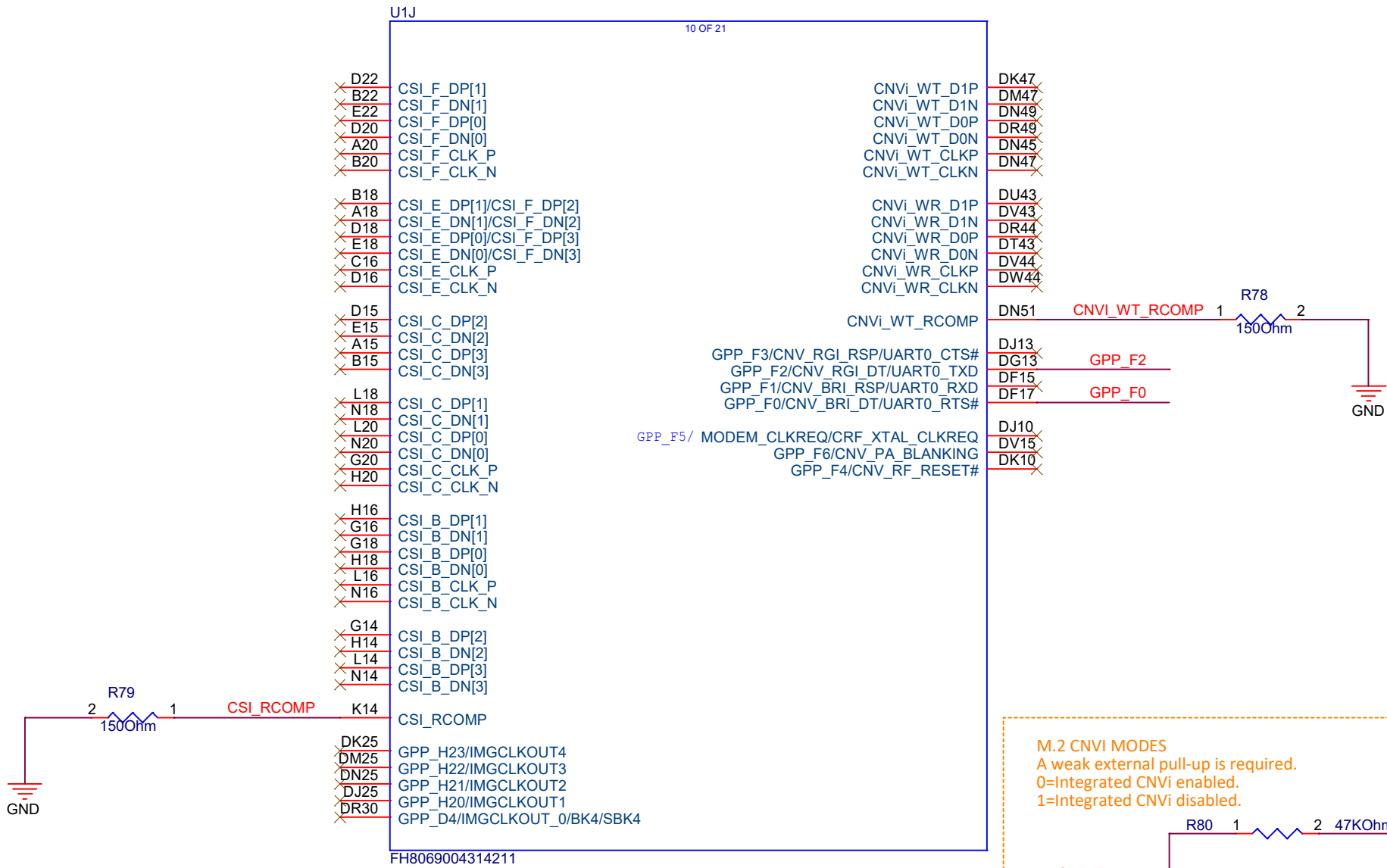


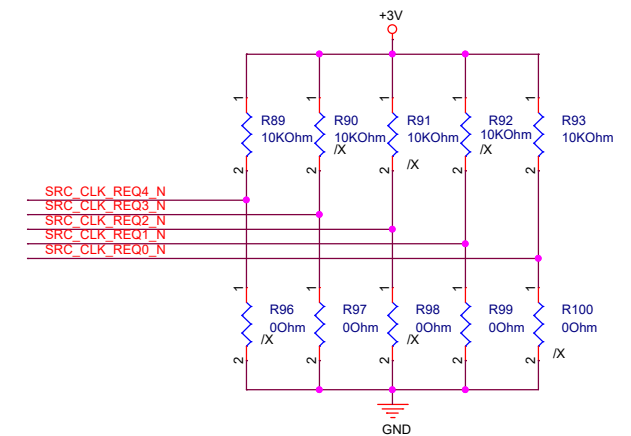
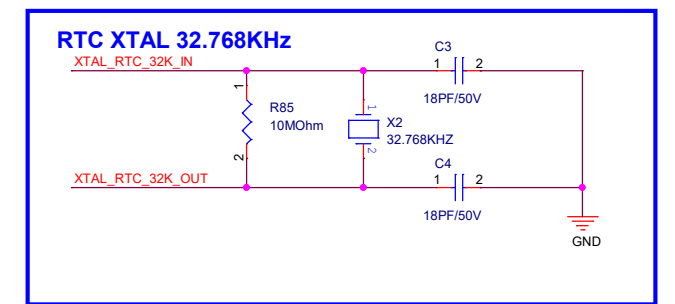
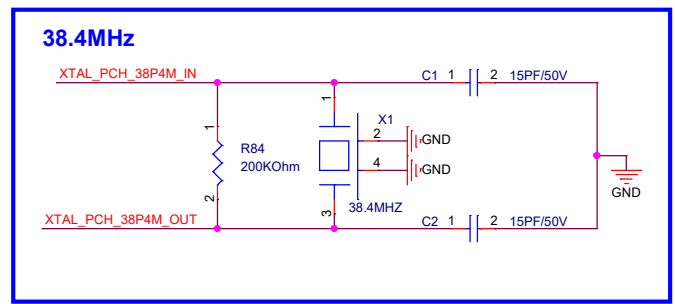
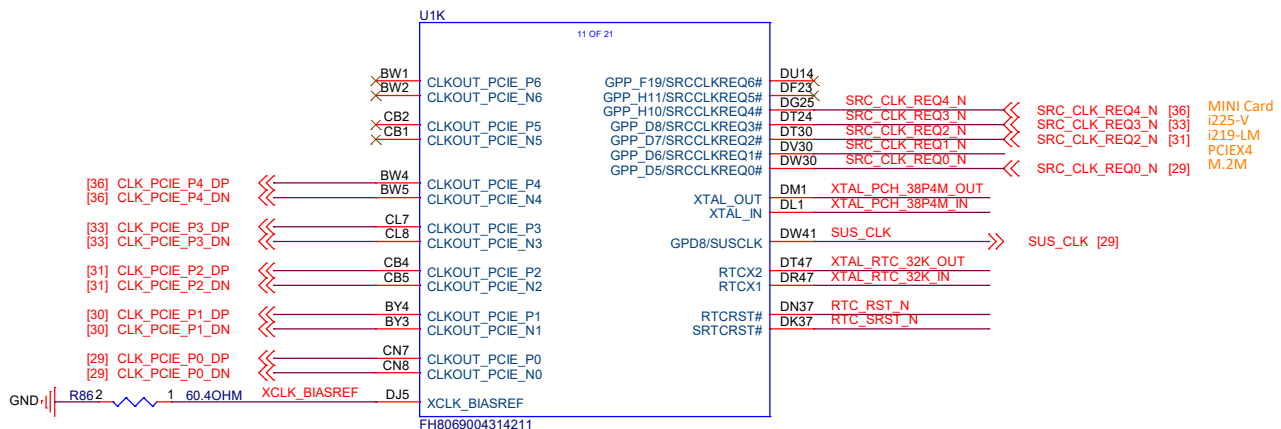
FLASH DESCRIPTOR SECURITY OVERRIDE
0=> Enable security measures defined in the Flash Descriptor.(Default)
1=> Disable Flash Descriptor Security (override). This strap
should only be asserted high using external Pull-up in
manufacturing/debug environments ONLY

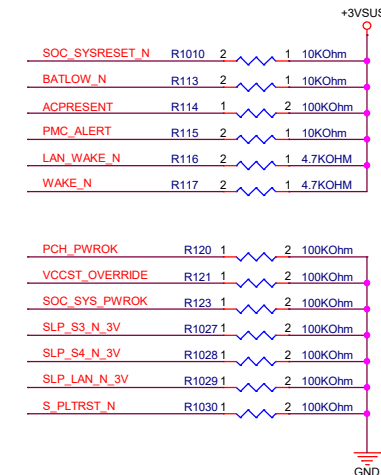
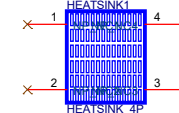
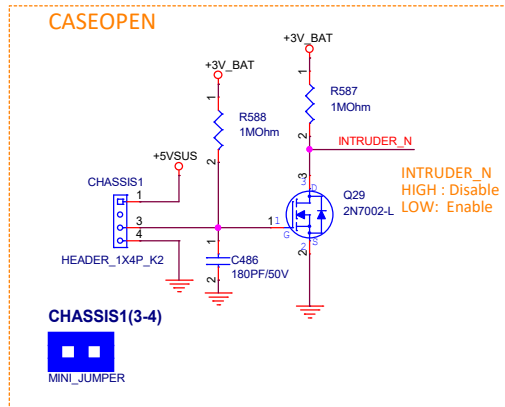
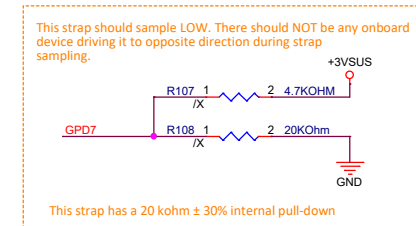
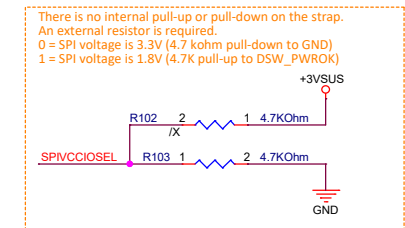


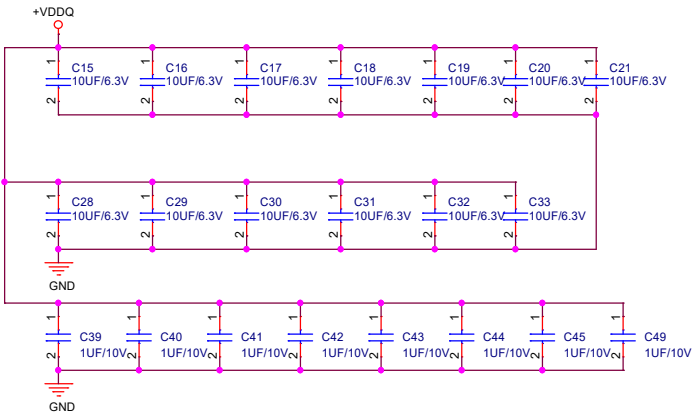
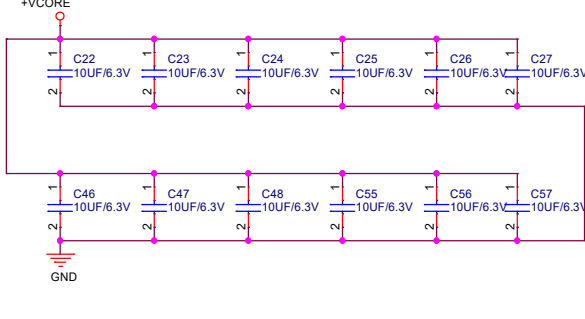
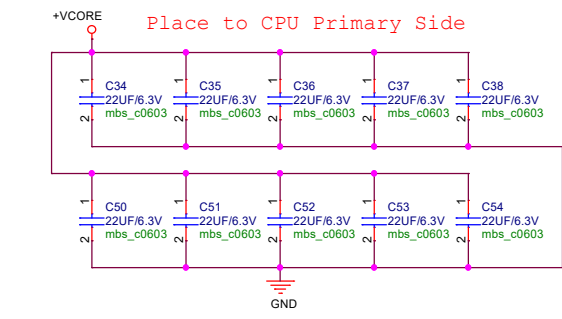
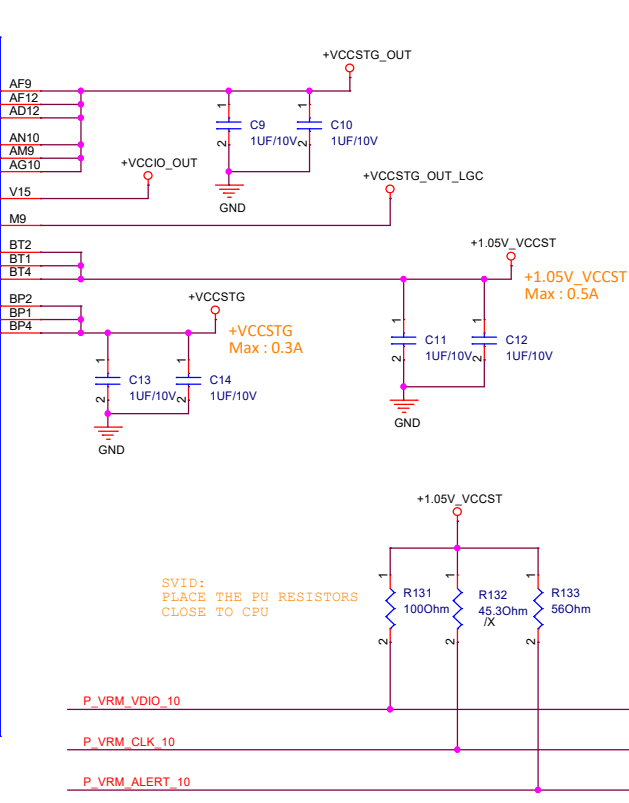
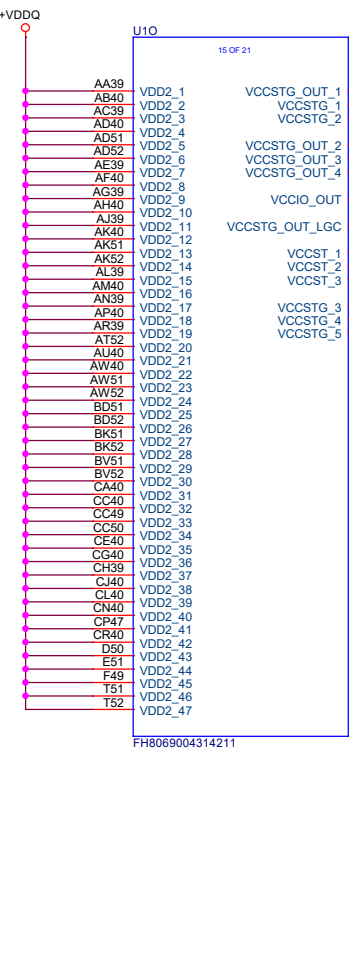
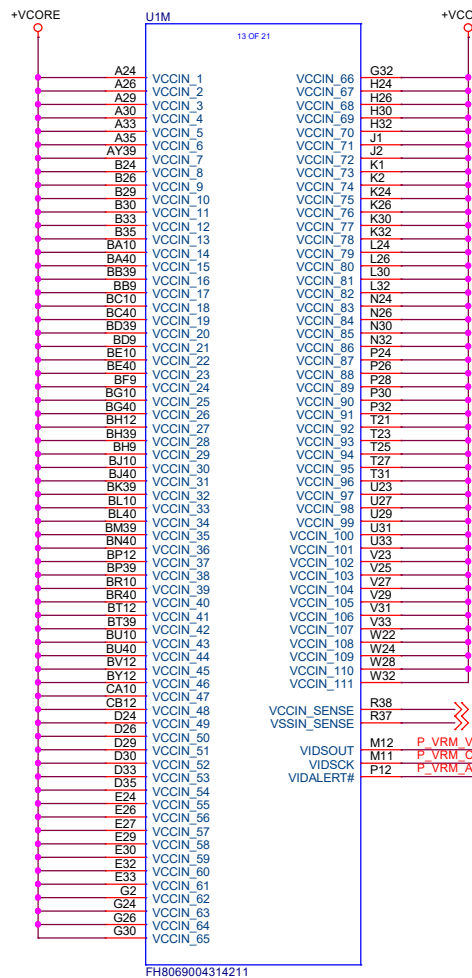
ASUS		Title : SOC-I2S/HDA	
ASUSTek COMPUTER INC.		Engineer:	
Size Custom	Project Name MIX-TLUD1		Rev R1.00
Date: Wednesday, September 09, 2020		Sheet	9 of 59



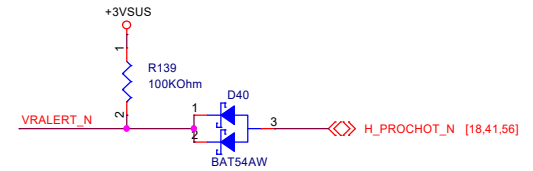
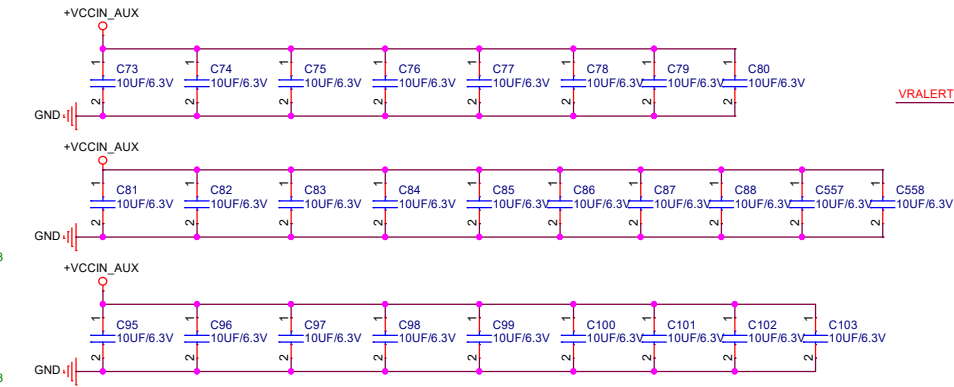
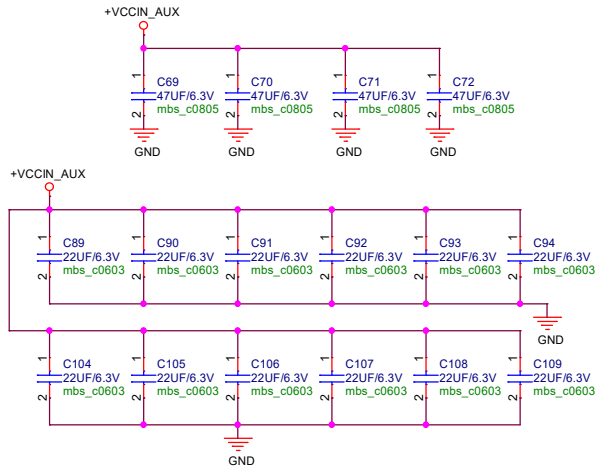


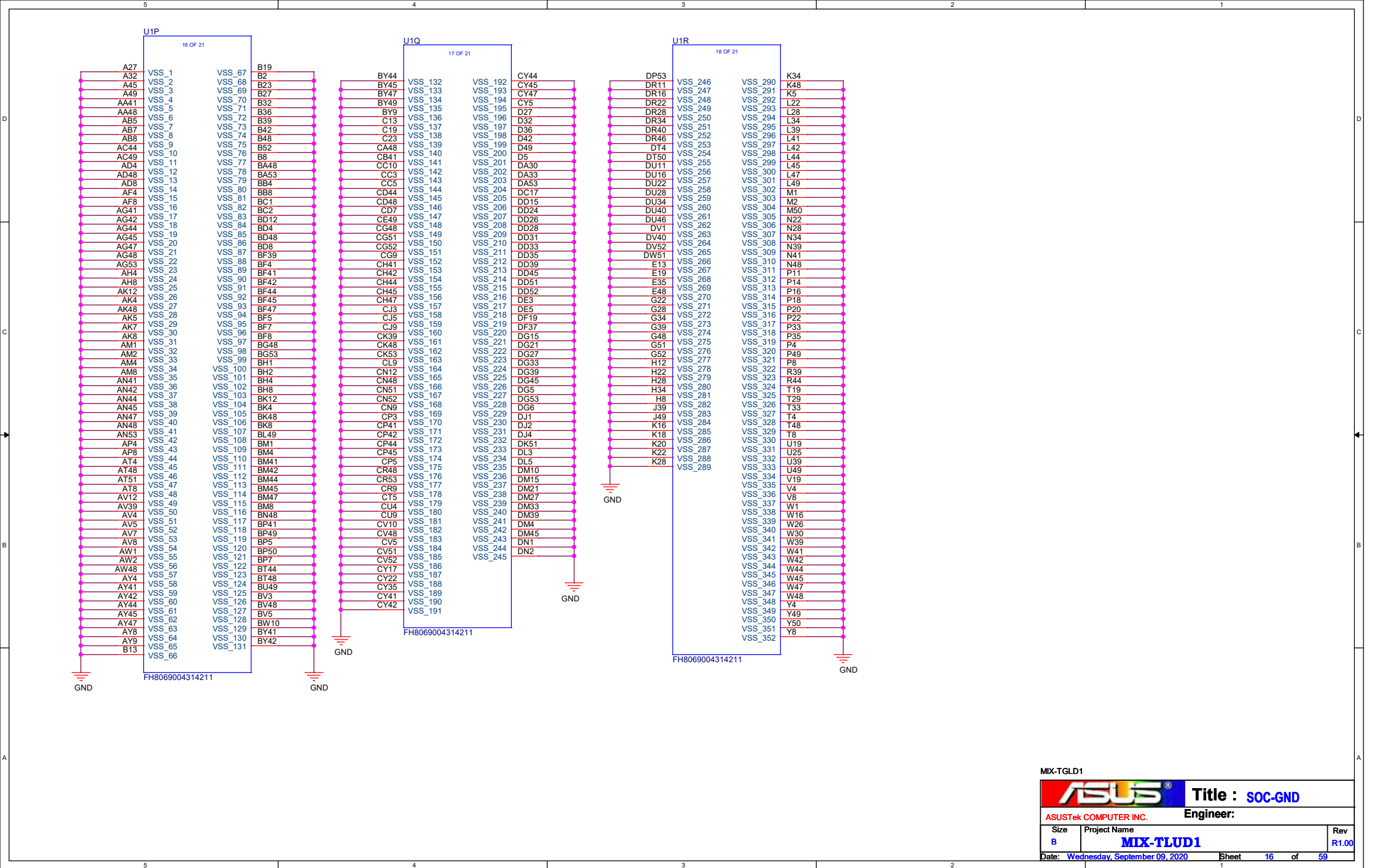


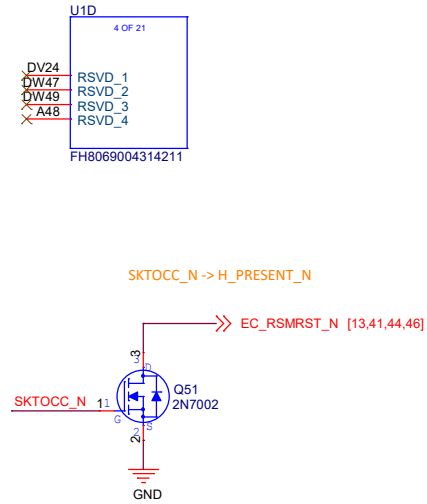
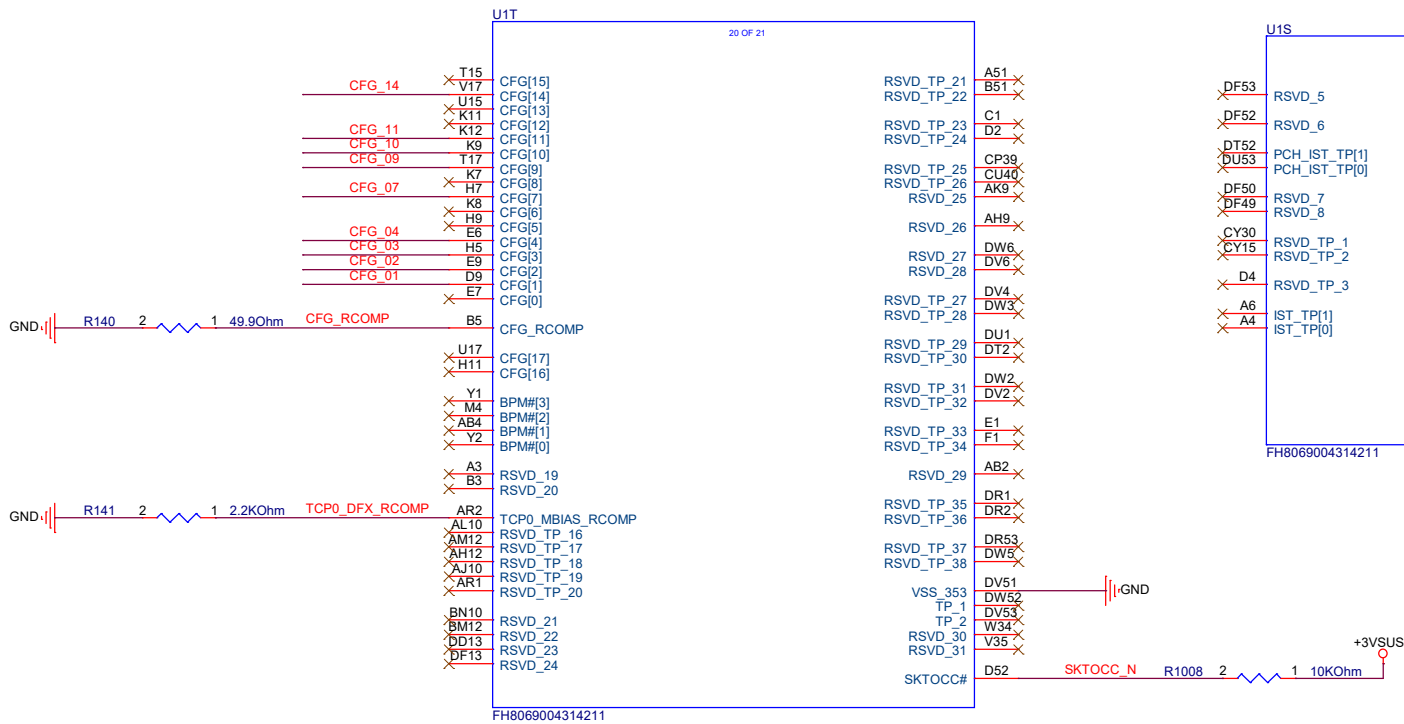




VID1	VID0	VCCIN_AUX
0	0	0V
0	1	1.1V
1	0	1.65V
1	1	1.8V





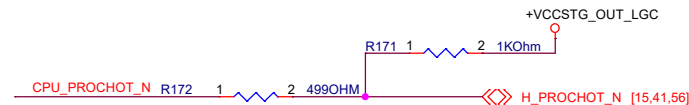
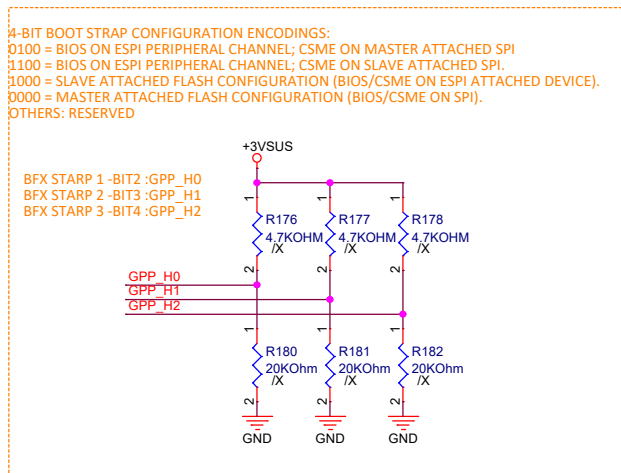
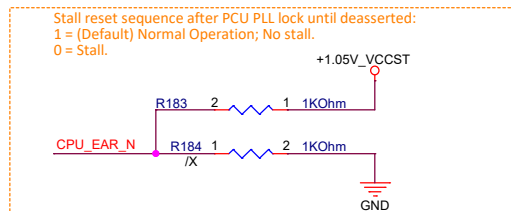
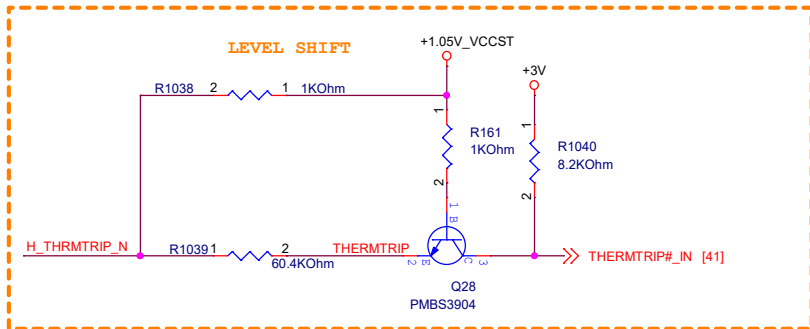
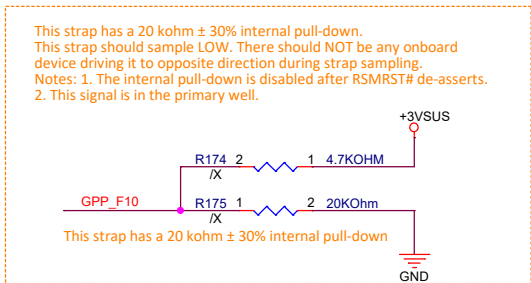
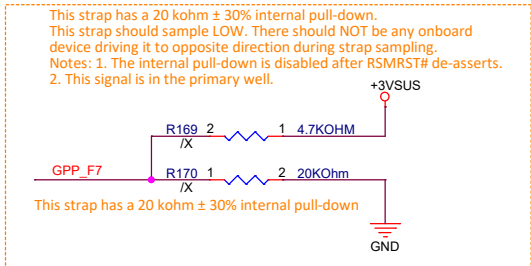
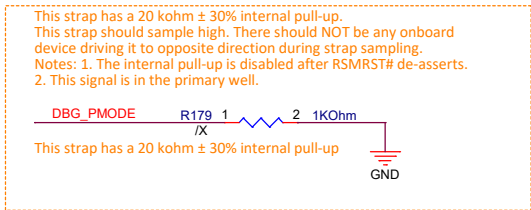
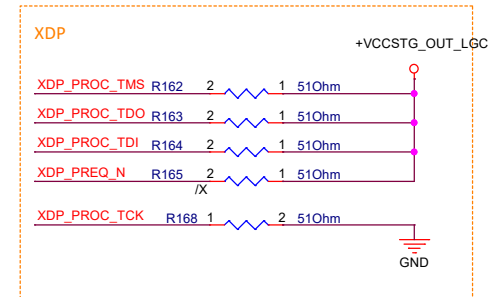
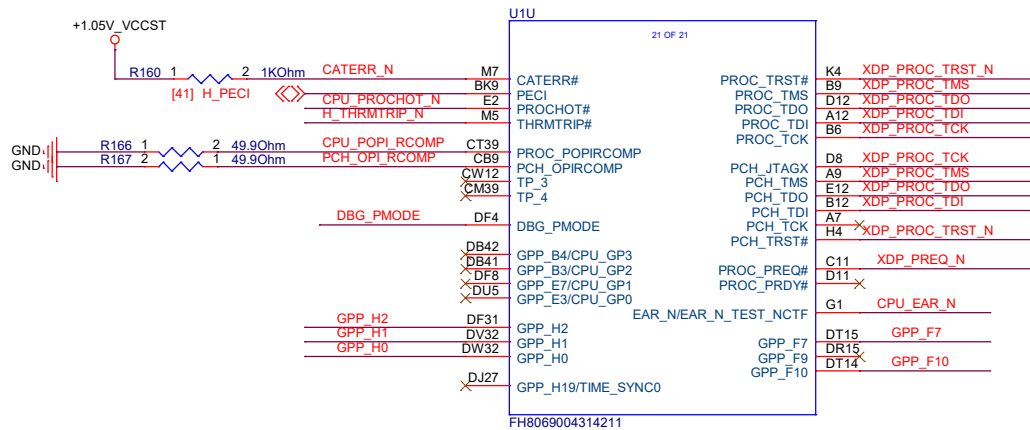


CFG Signals Functionality and Termination

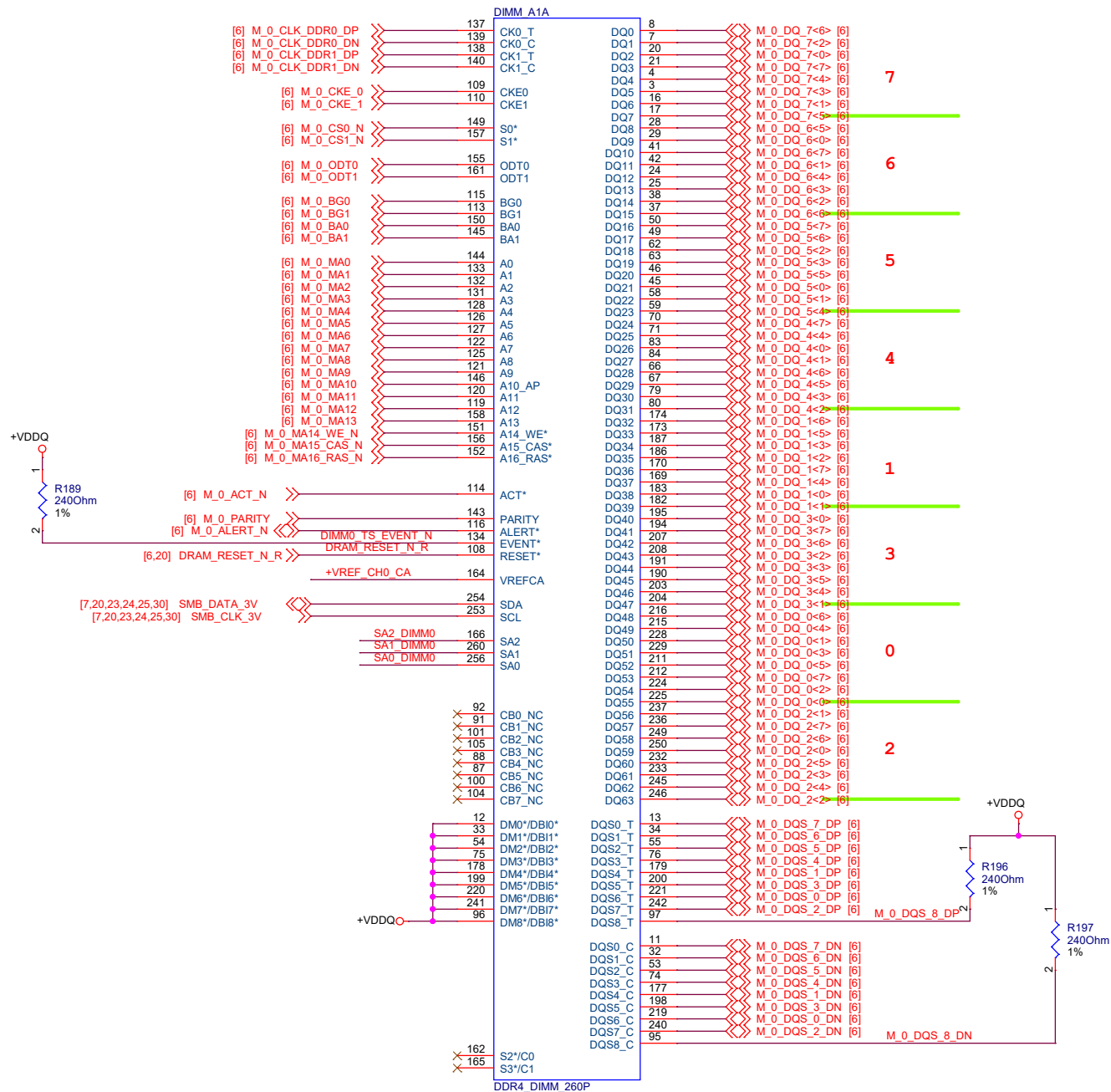
CFG	Description	Termination	Resistor
EAR	Stall CPU reset sequence until de-asserted: - 1 = (Default) Normal Operation; No stall. - 0 = Stall	Pull-up to VCCSTG	1K ohm
CFG[0]	RSVD	None	
CFG[1]	RSVD	Pull-up to VCCIO	1K ohm
CFG[2]	RSVD	Pull-up to VCCIO	1K ohm
CFG[3]	RSVD	Pull-up to VCCIO	1K ohm
CFG[4]	eDP enable Strap: - 1 = Disabled. - 0 = Enabled.	Pull-up to VCCIO / Pull-down- Platform design dependent	1K ohm
CFG[6:5]	RSVD	None	
CFG[7]	PEG deferred link training	Pull-up to VCCIO / Pull-down- Platform design dependent	1K ohm
CFG[8]	RSVD	None	
CFG[11:9]	RSVD	Pull-up to VCCIO	1K ohm
CFG[13:12]	RSVD	None	
CFG[14]	PEG60 Lane Reversal: - 1 - (Default) Normal - 0 - Reversed	Pull-up to VCCIO / Pull-down- Platform design dependent	1K ohm
CFG[17:15]	RSVD	None	

MIX-TGLD1

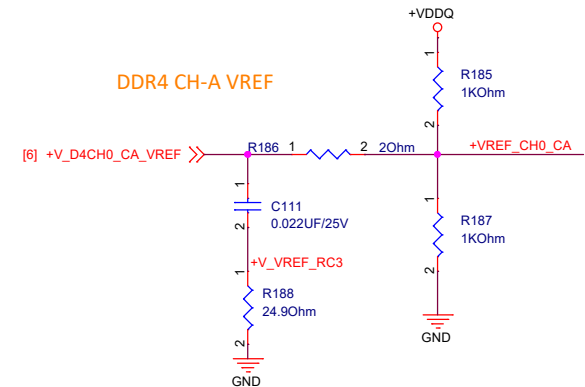
ASUS		Title : SOC-CFG/RSVD	
ASUSTek COMPUTER INC.		Engineer:	
Size B	Project Name MIX-TLUD1	Rev R1.00	
Date: Wednesday, September 09, 2020		Sheet 17 of 59	



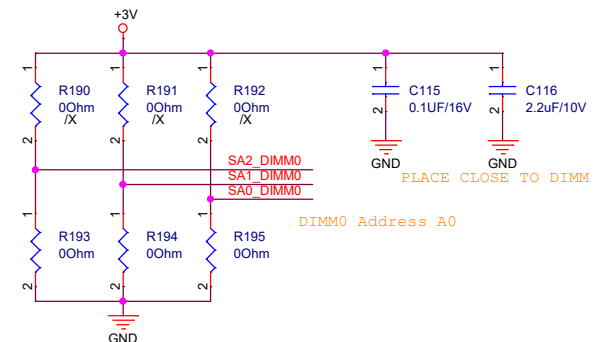
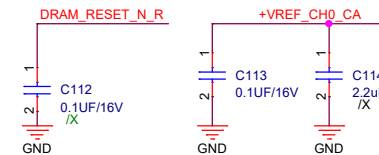
DDR4 SODIMM CHANNEL -A



DDR4 CH-A VREF



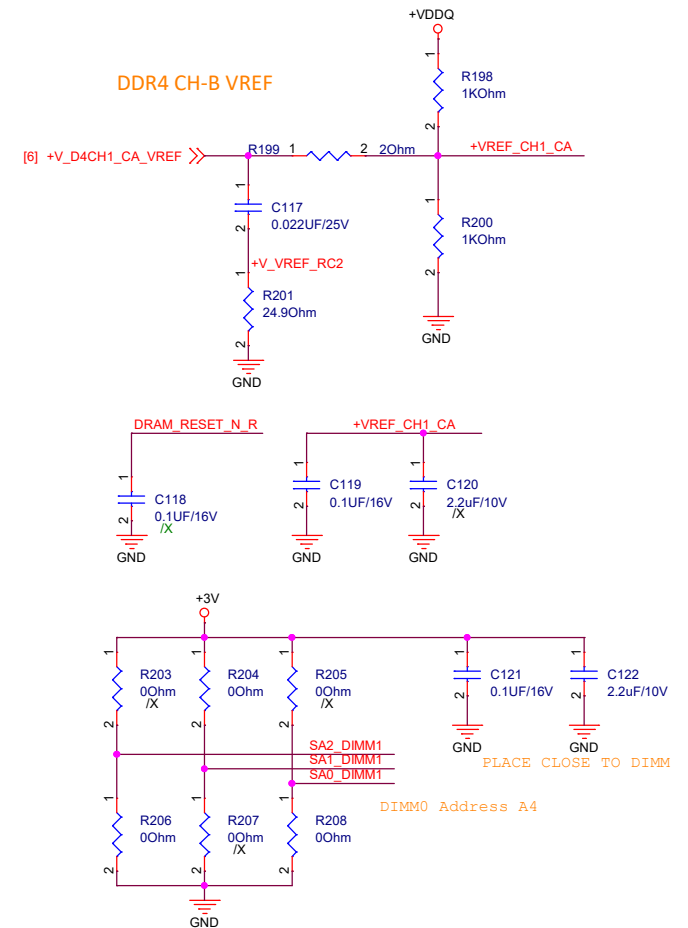
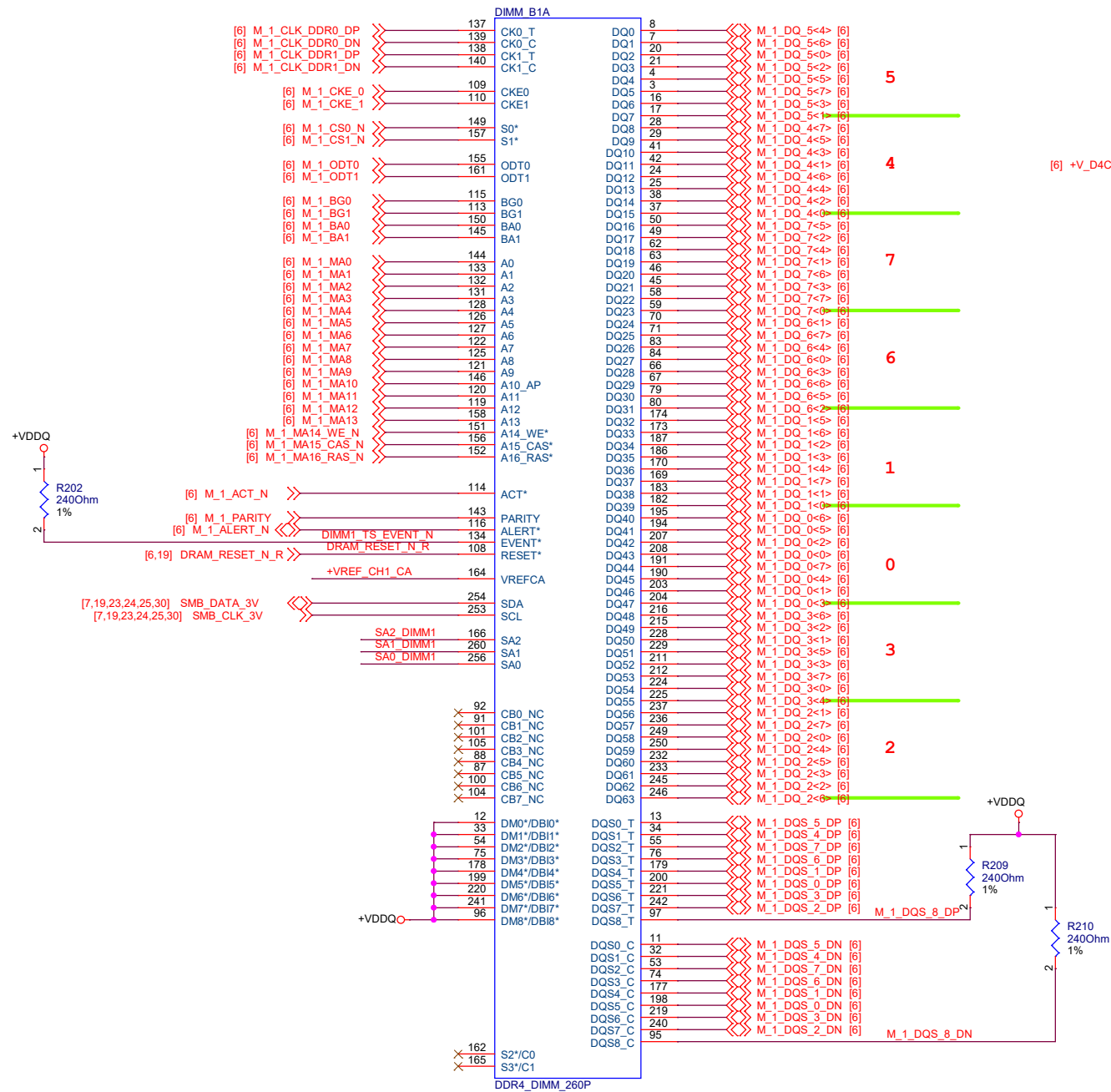
DRAM RESET_N_R

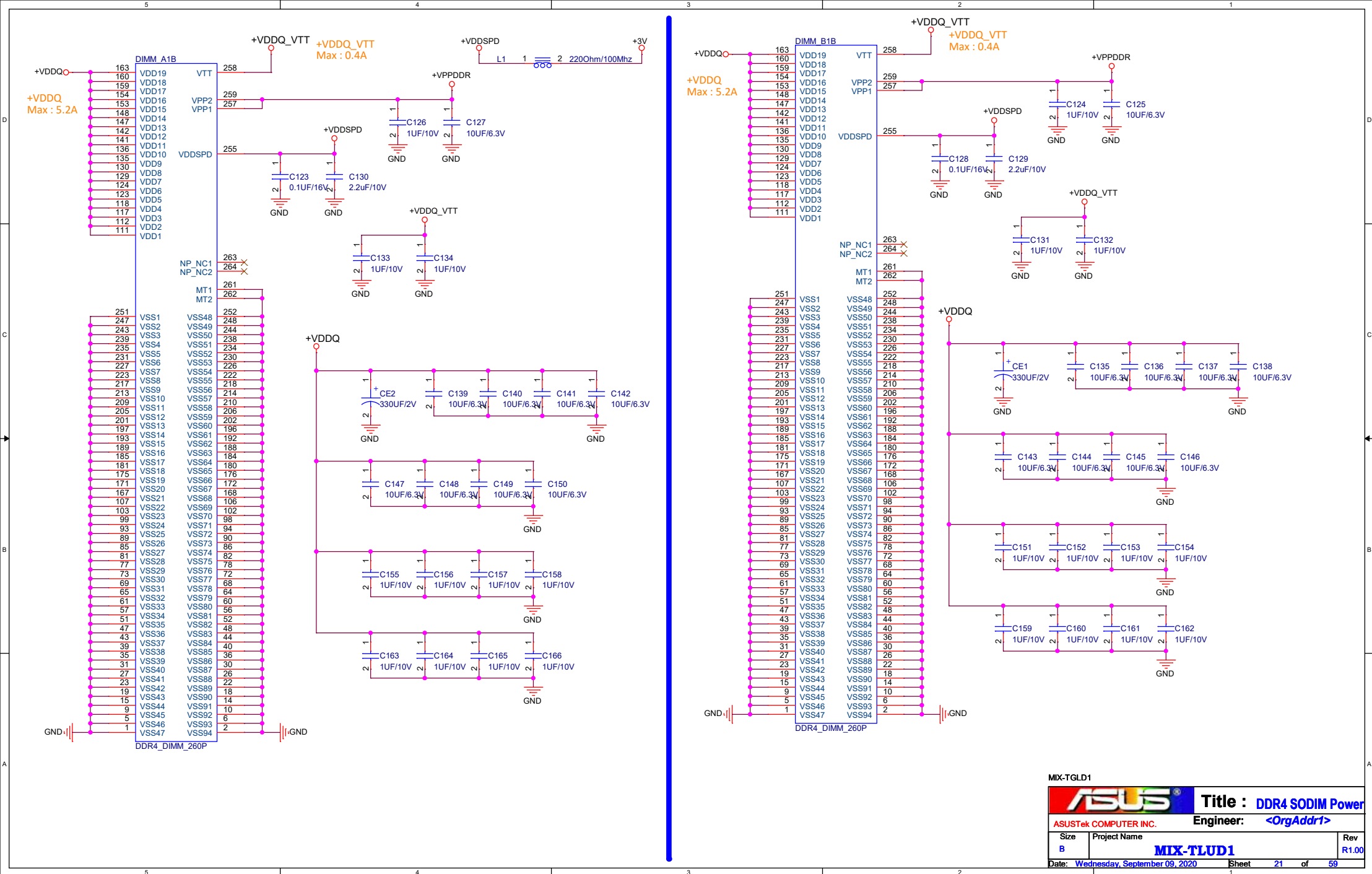


MIX-TGLD1


ASUS		Title : DDR4 SODIMM-CHA	
ASUSTek COMPUTER INC.		Engineer: <OrgAddr1>	
Size B	Project Name MIX-TLUD1	Rev R1.00	
Date: Wednesday, September 09, 2020		Sheet 19 of 59	

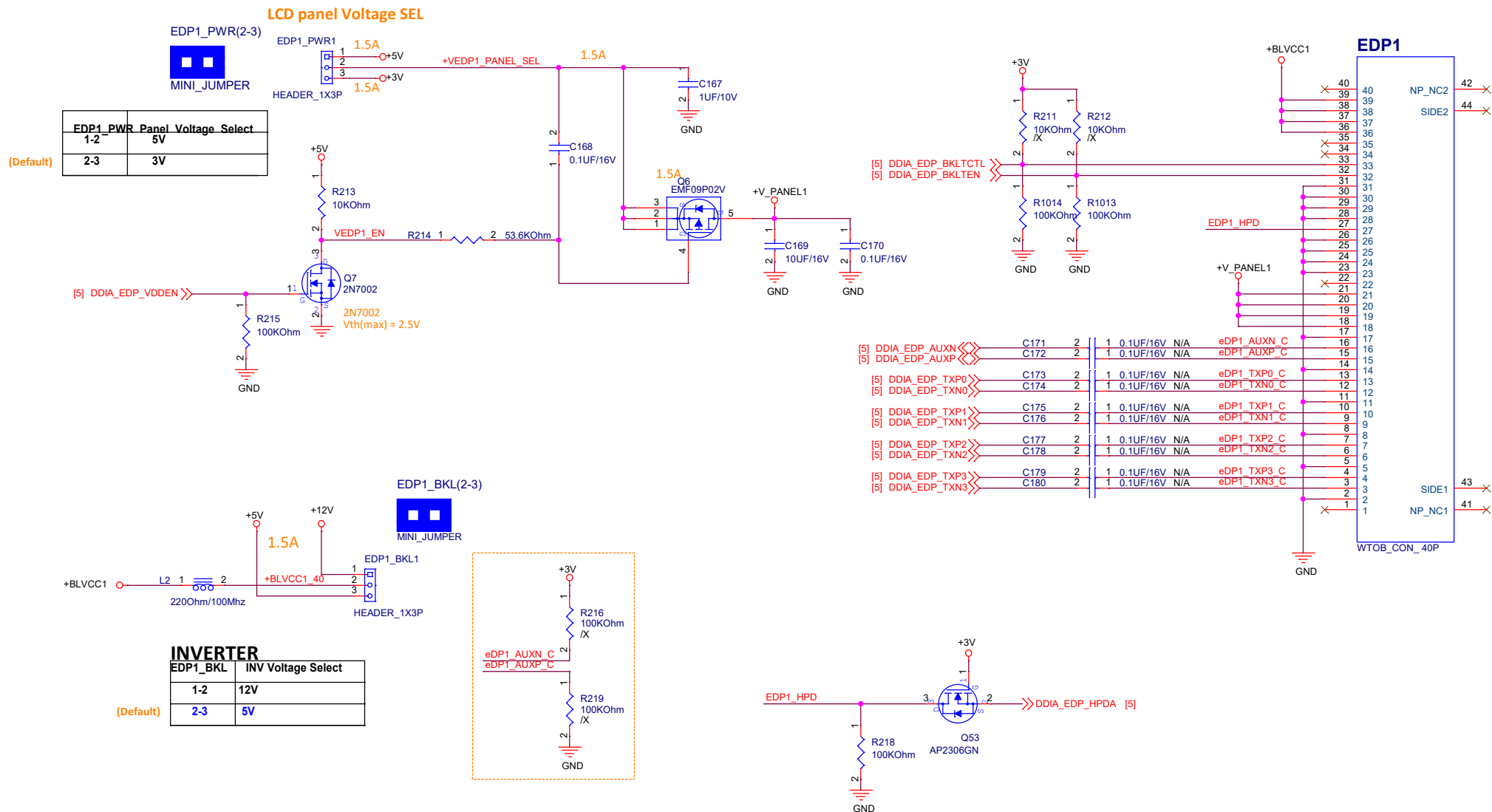
DDR4 SODIMM CHANNEL -B





MIX-TGLD1

		Title : DDR4 SODIM Power	
ASUSTek COMPUTER INC.		Engineer: <OrgAddr1>	
Size B	Project Name MIX-TLUD1		Rev R1.00
Date: Wednesday, September 09, 2020		Sheet 21	of 59



LVDS_PWR(1-2)



LVDS_PWR	Panel Voltage Select
1-2	3V
3-4	12V
5-6	5V

LCD panel Voltage SEL

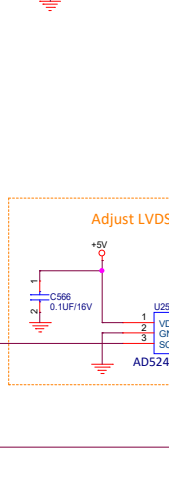
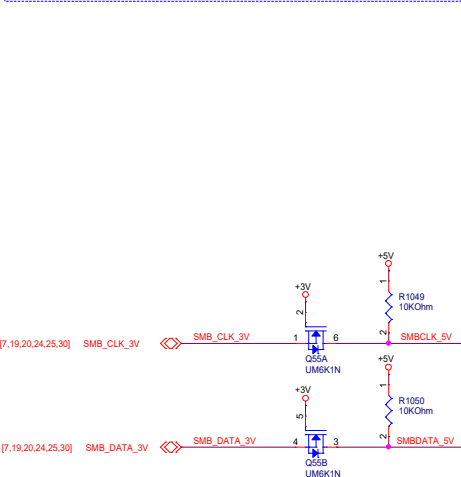
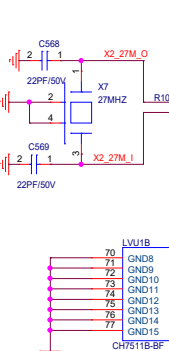
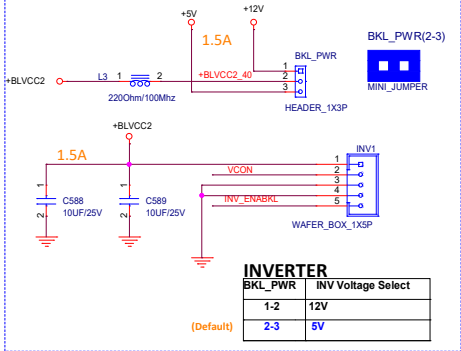


LVDS_PWR	Panel Voltage Select
1-2	3V
3-4	12V
5-6	5V

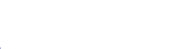
BKL_PWR(2-3)



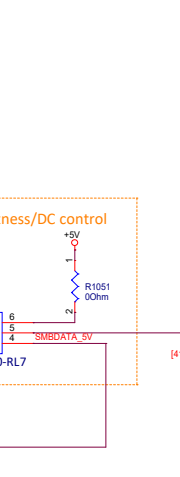
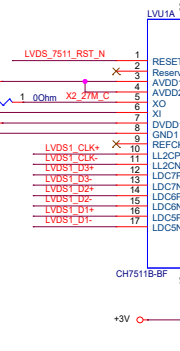
BKL_PWR	INV Voltage Select
1-2	12V
2-3	5V



Adjust LVDS brightness/DC control



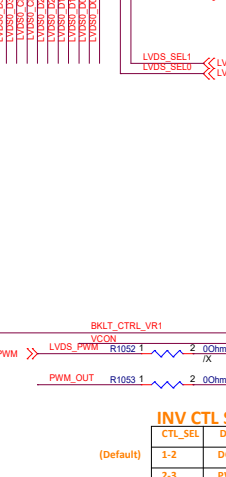
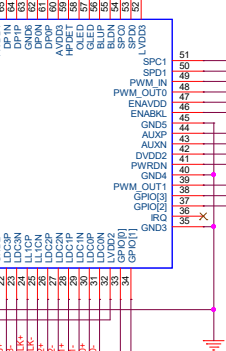
CTL_SEL	DC & PWM Sel
1-2	DC Control
2-3	PWM Control



INV CTL SEL



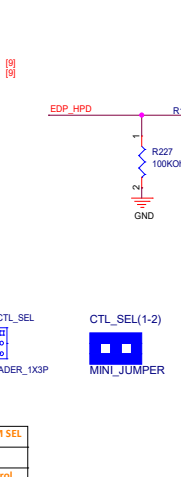
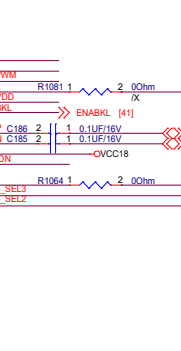
CTL_SEL	DC & PWM Sel
1-2	DC Control
2-3	PWM Control



CTL_SEL(1-2)



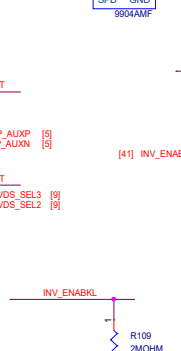
CTL_SEL	DC & PWM Sel
1-2	DC Control
2-3	PWM Control



EDP_HP



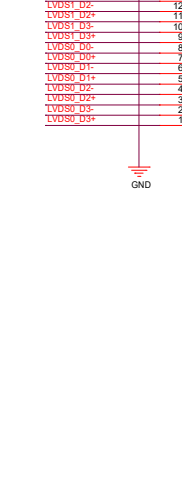
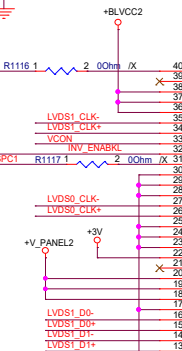
EDP_HP	EDP_HP
1-2	EDP_HP
2-3	EDP_HP



LVDS1



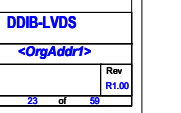
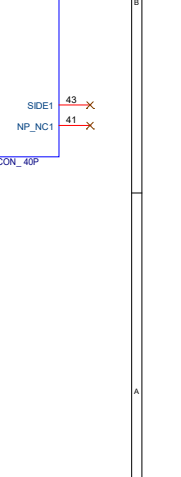
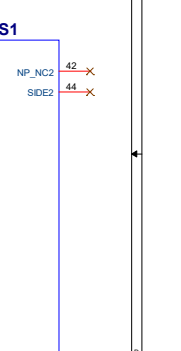
LVDS1	LVDS1
1-2	LVDS1
2-3	LVDS1

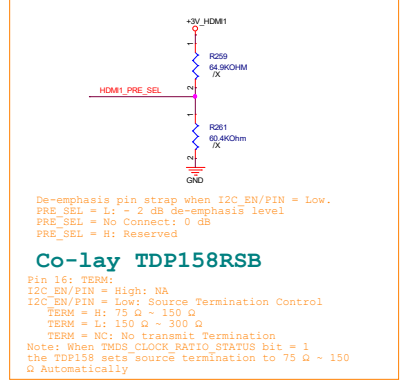
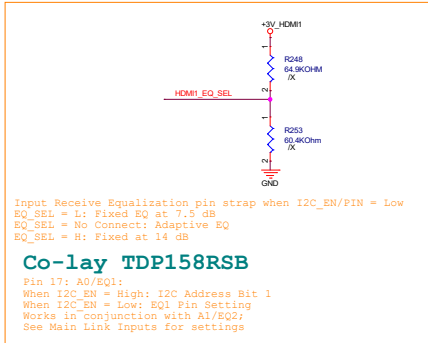
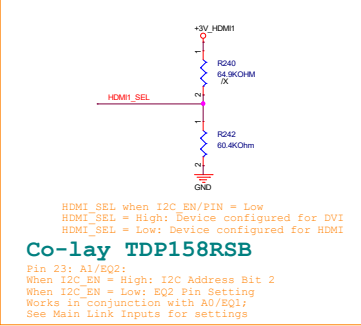
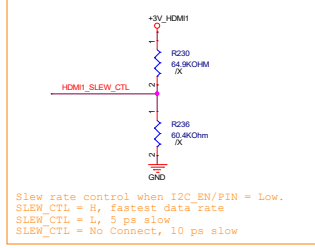
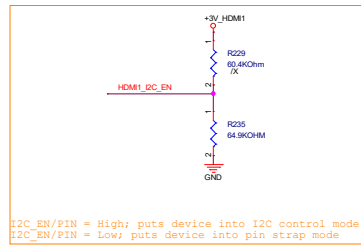
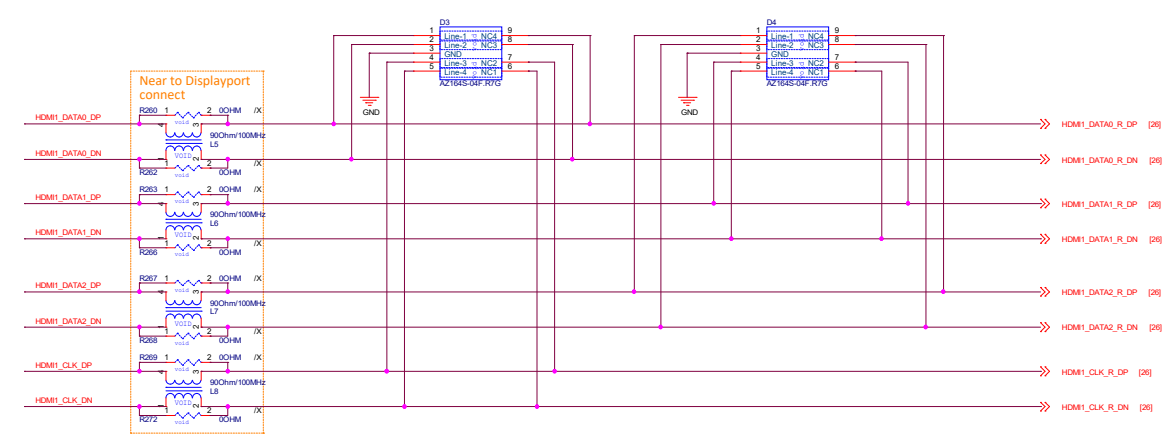
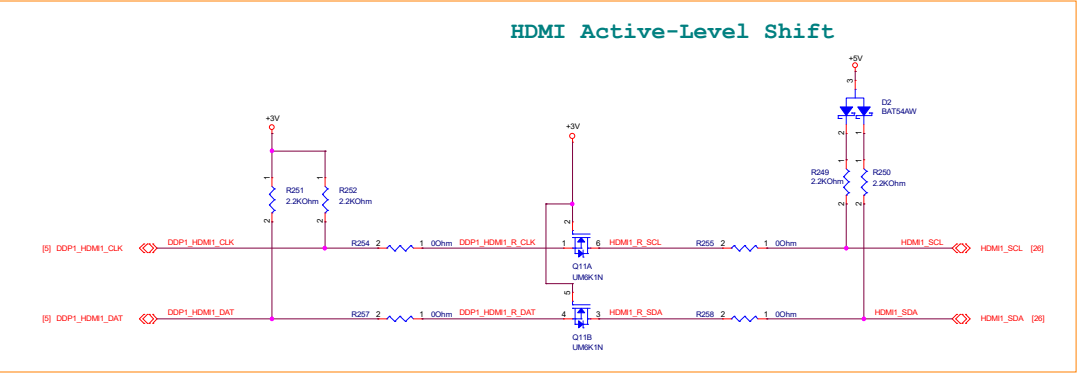
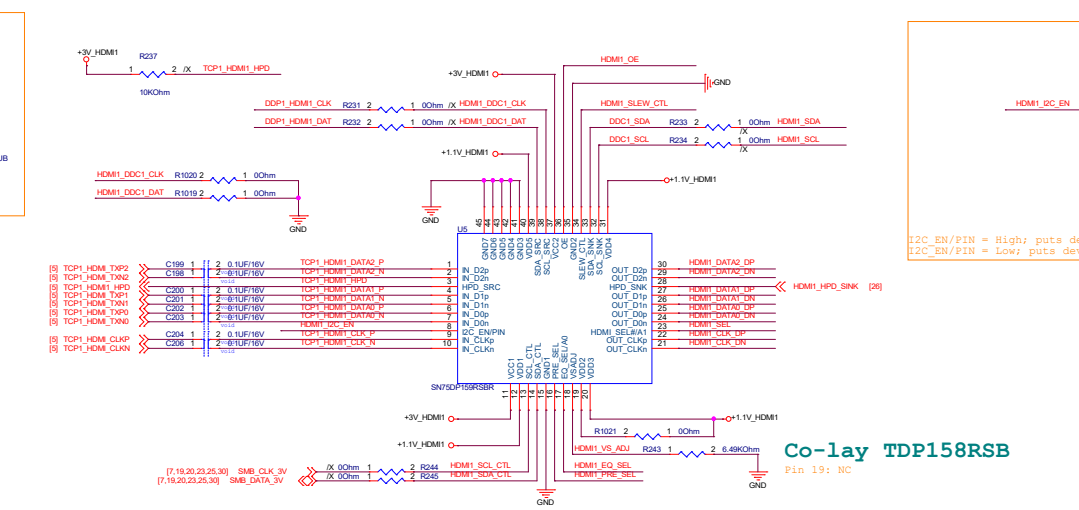
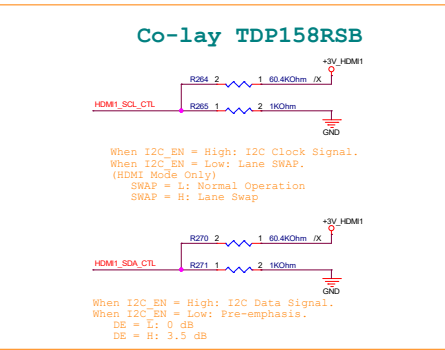
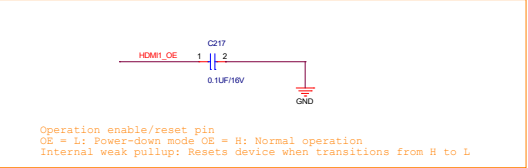
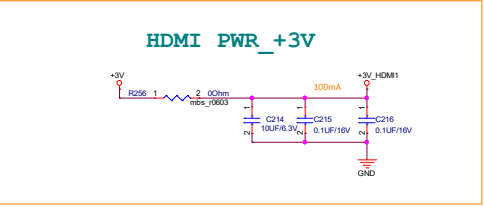
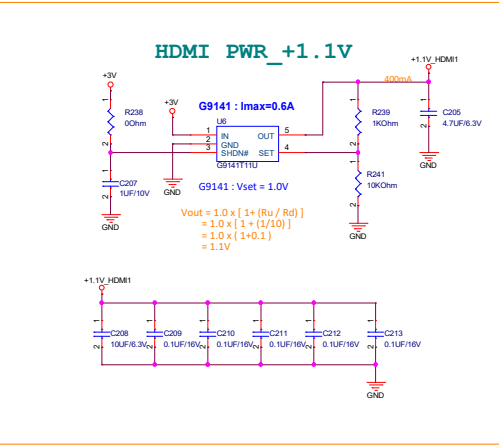
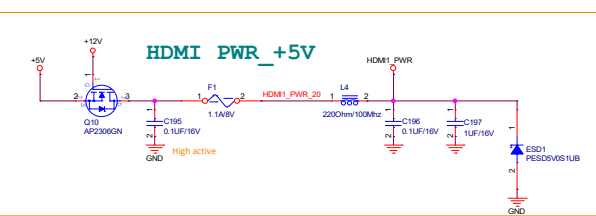


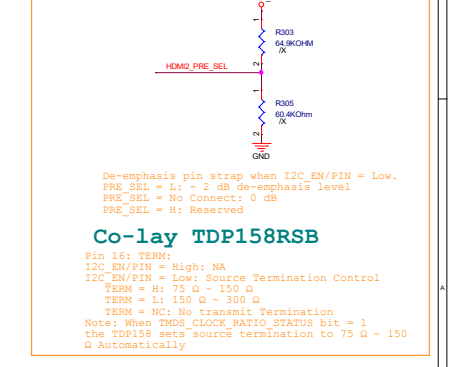
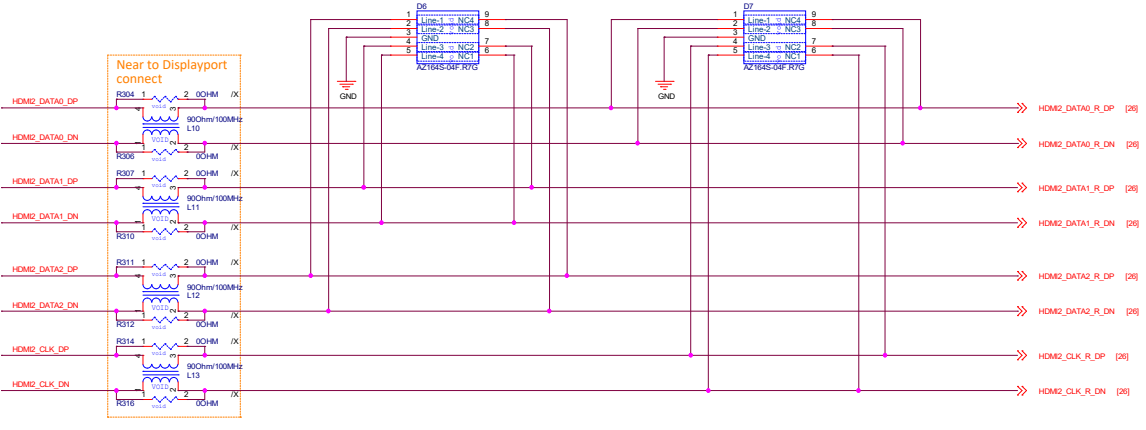
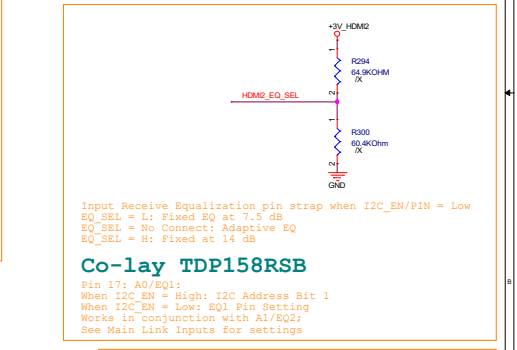
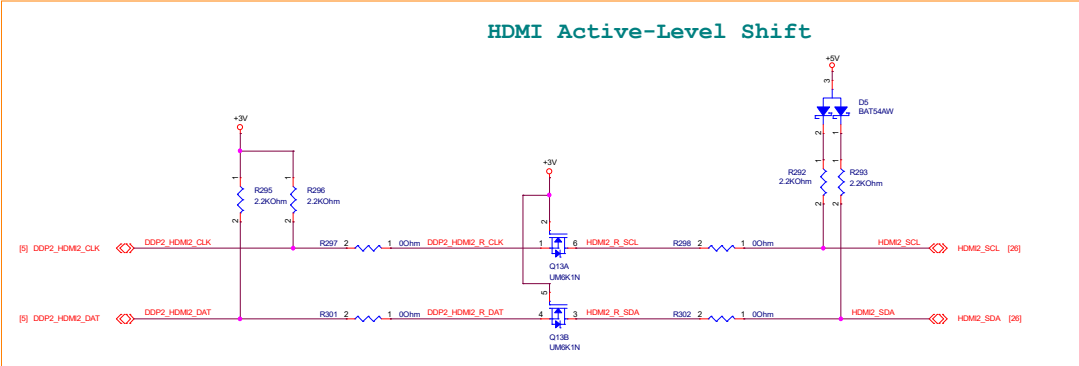
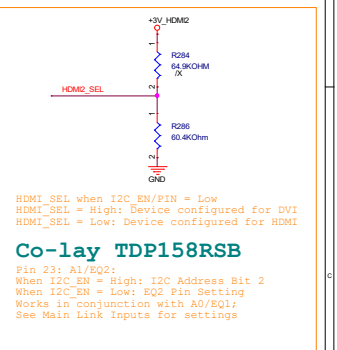
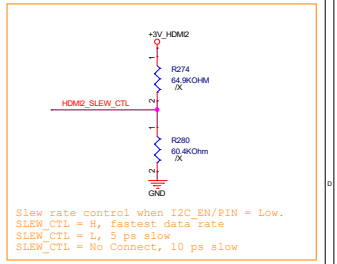
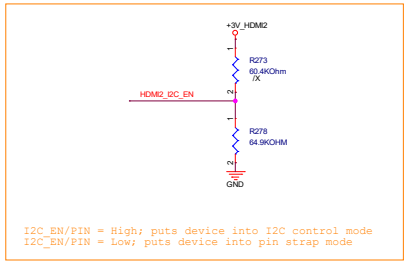
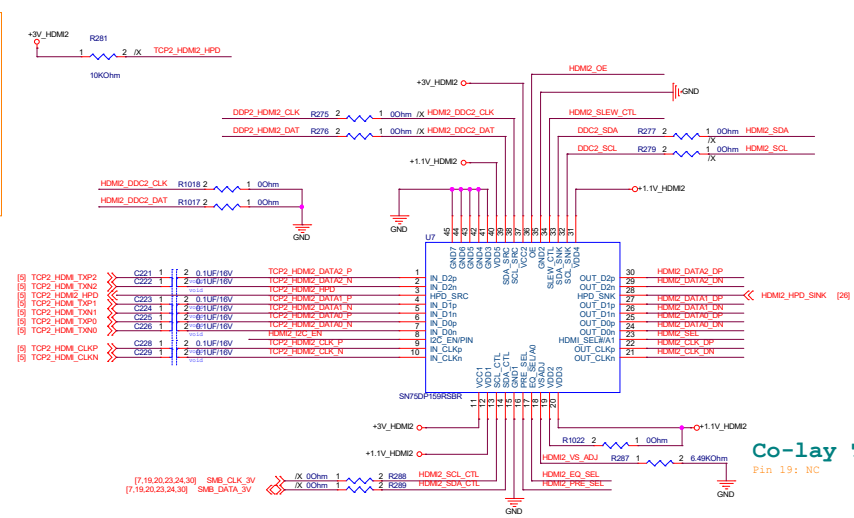
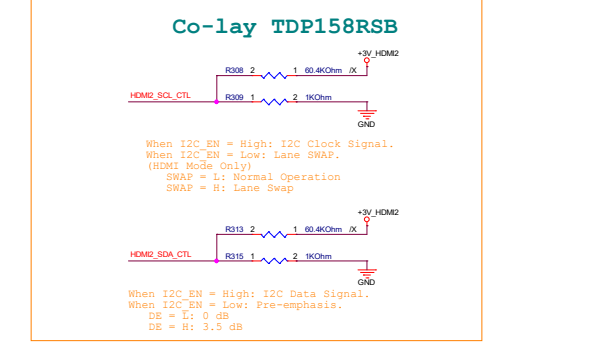
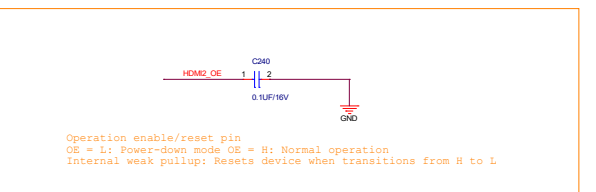
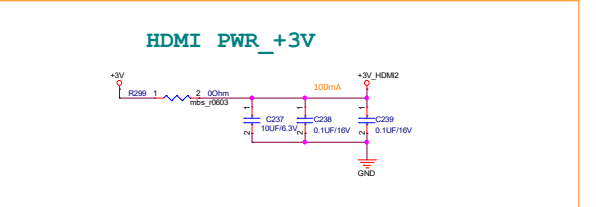
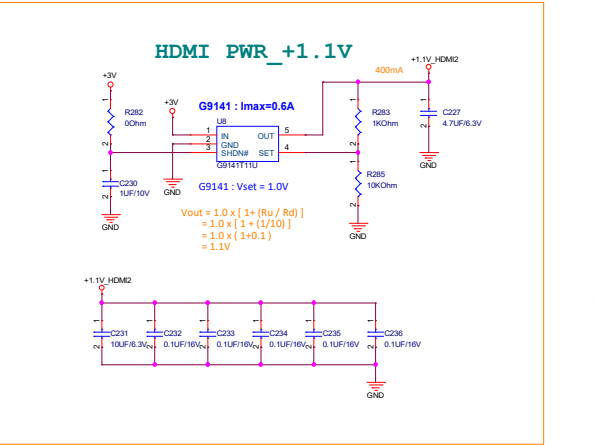
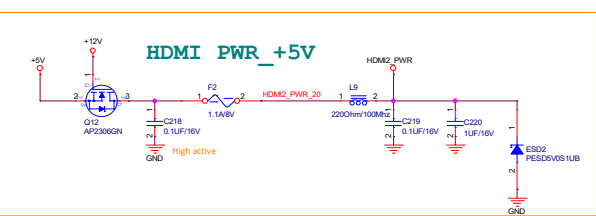
LVDS2

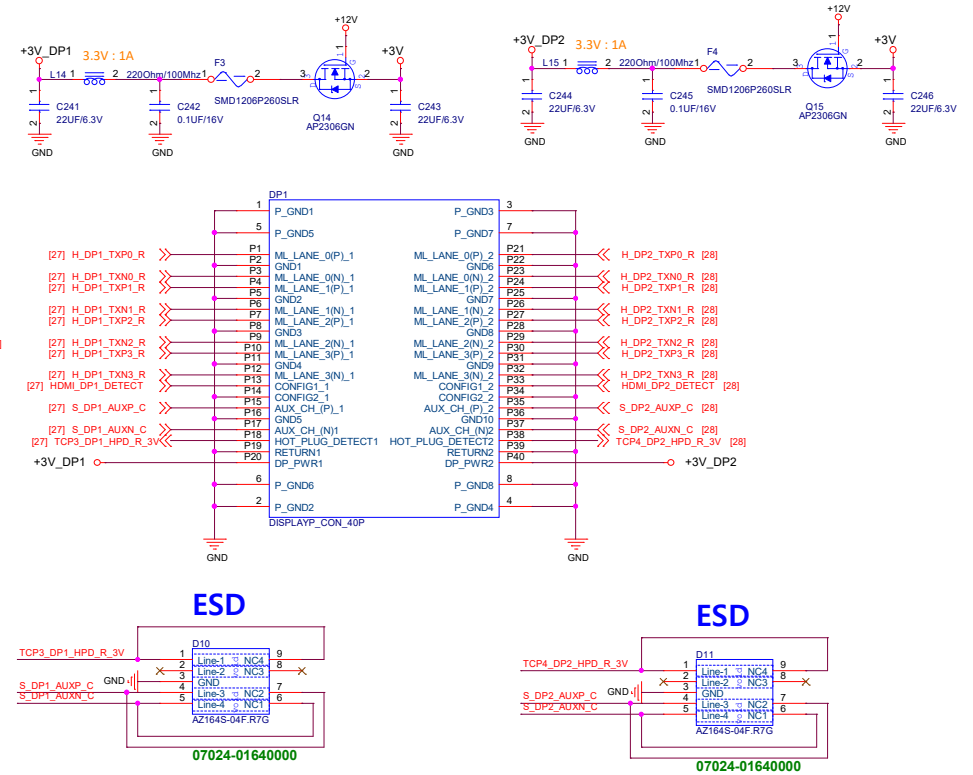
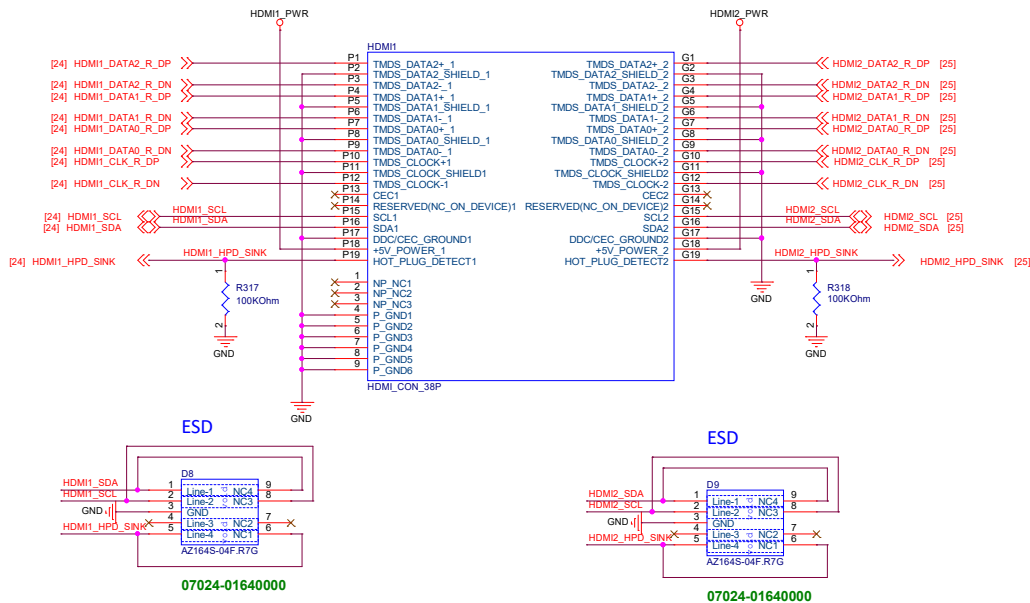


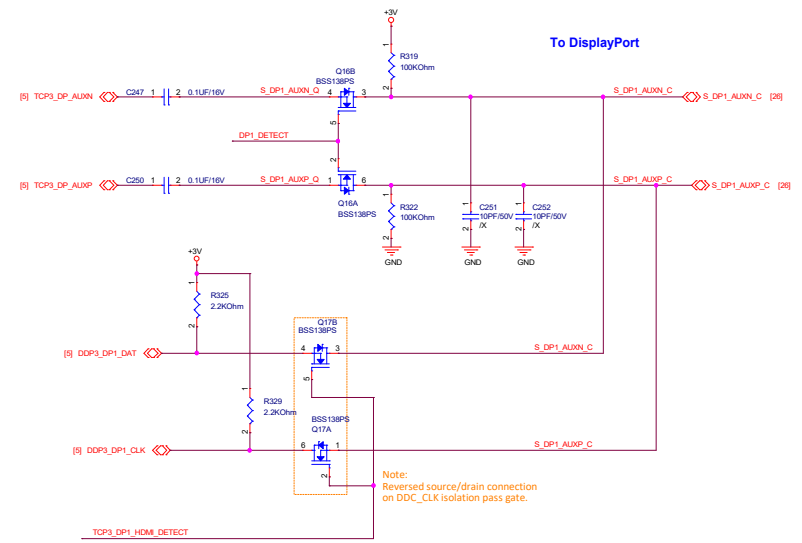
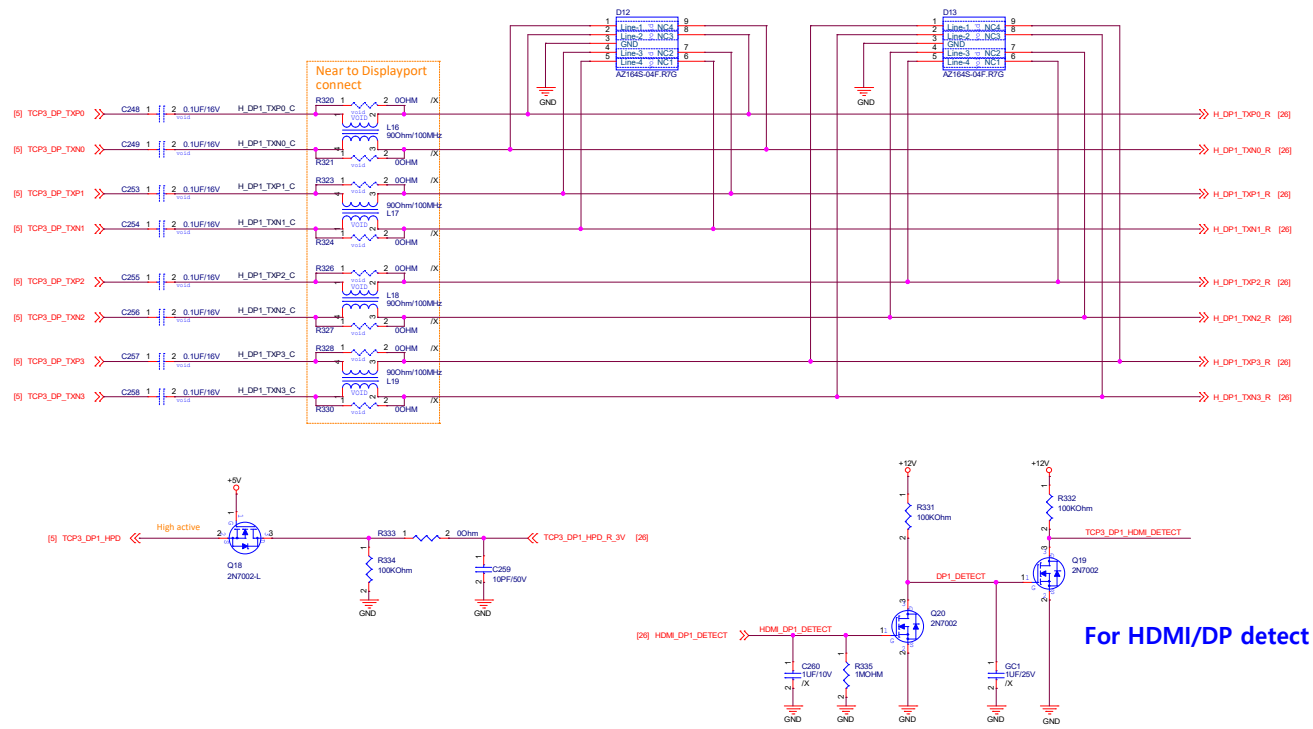
LVDS2	LVDS2
1-2	LVDS2
2-3	LVDS2

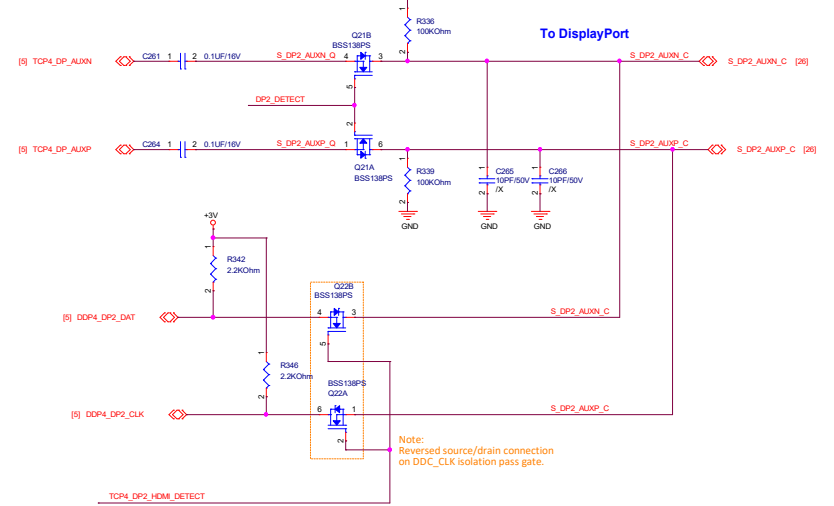
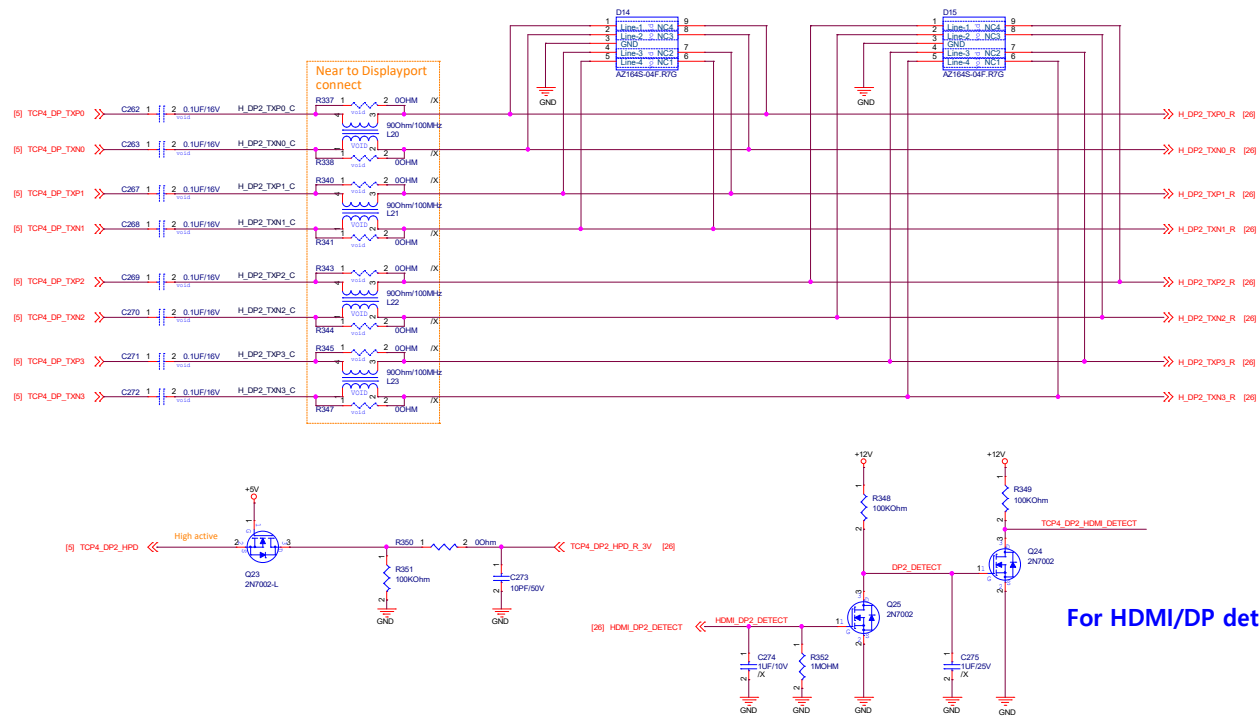


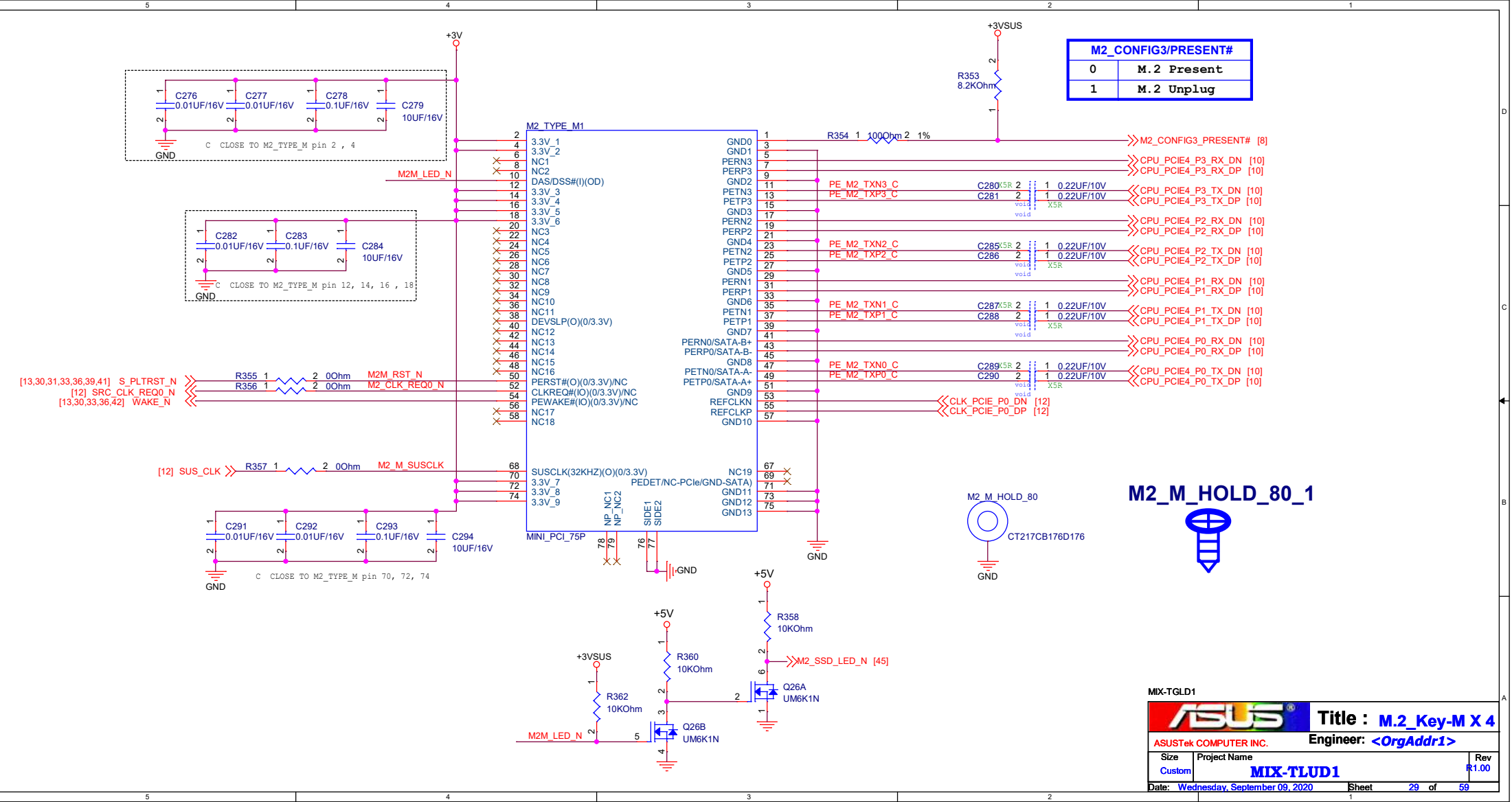


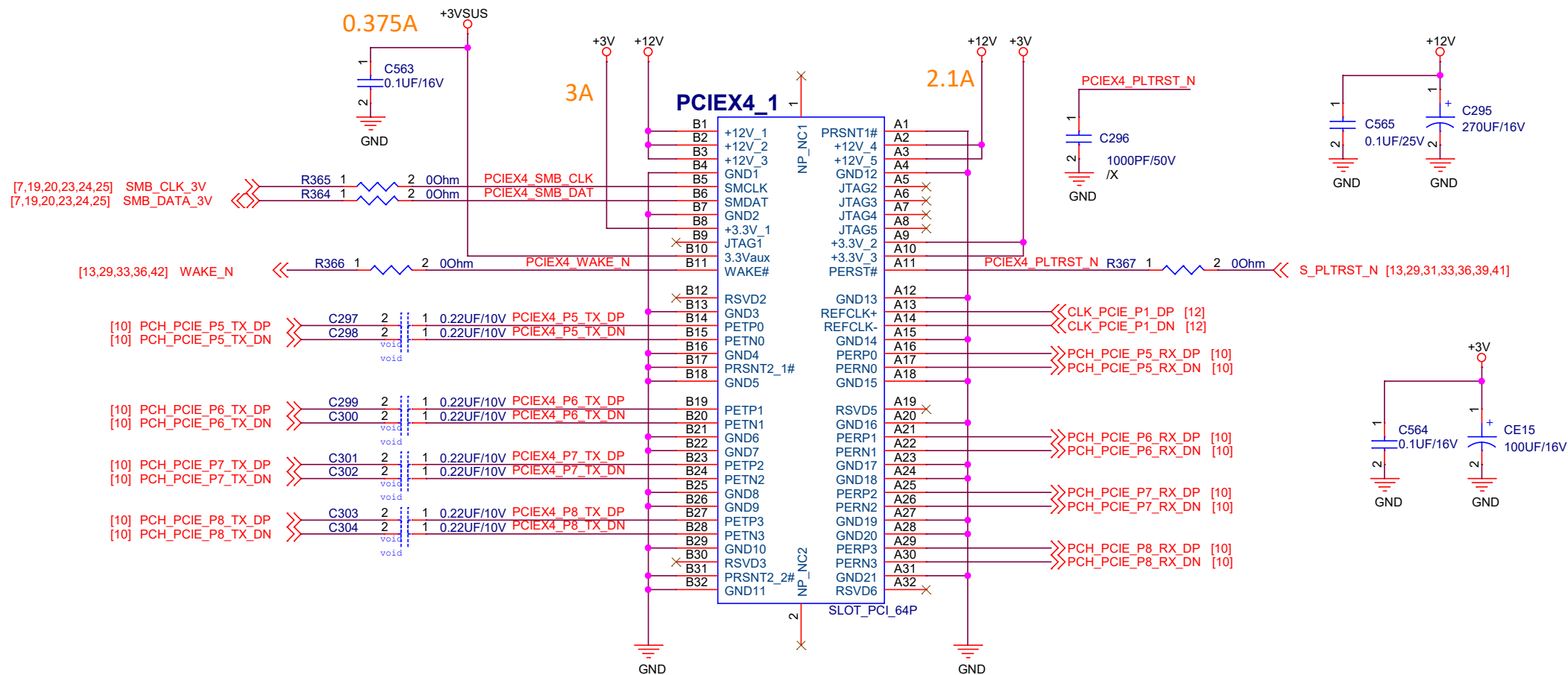




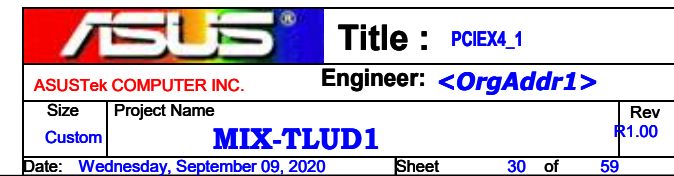


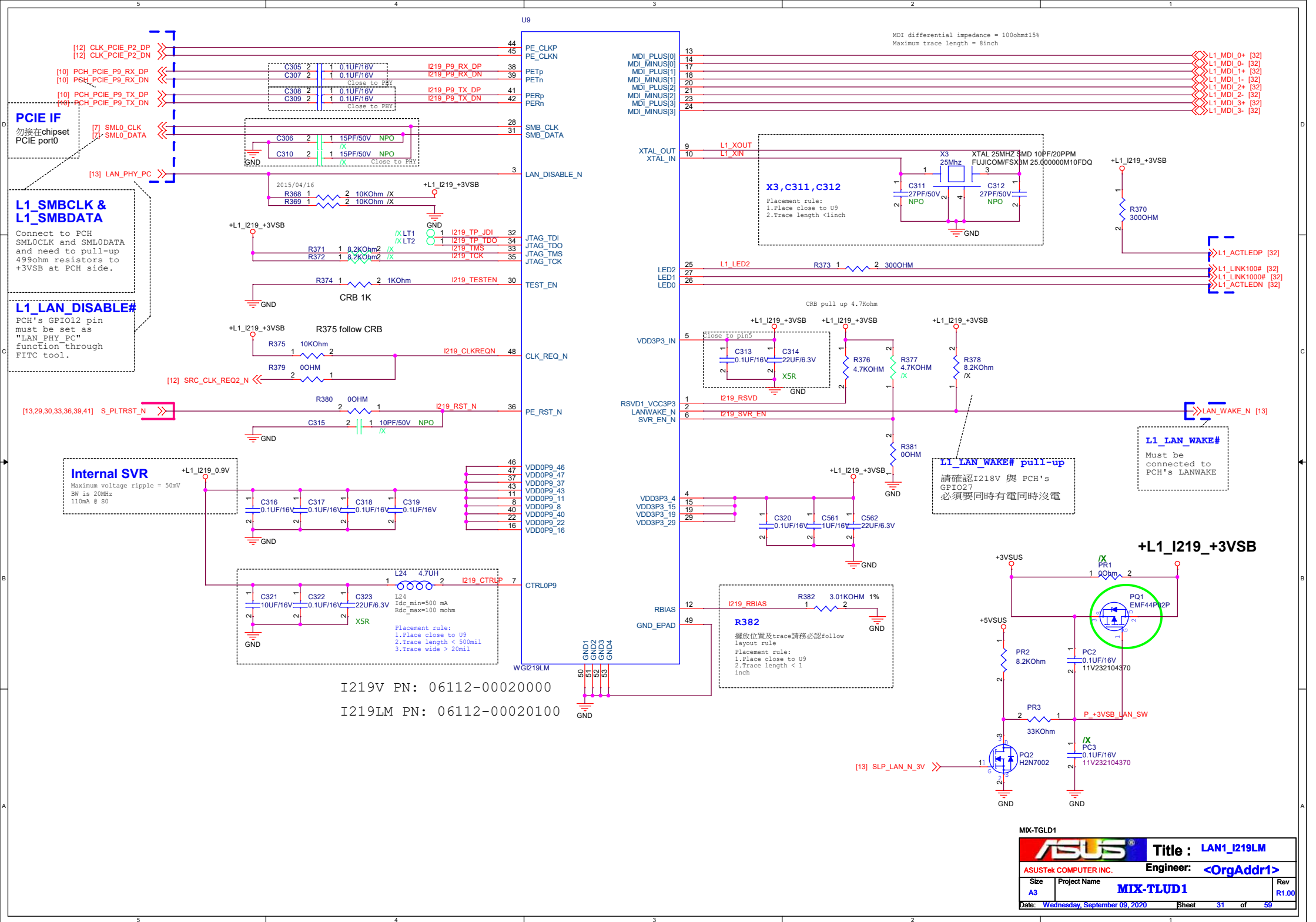


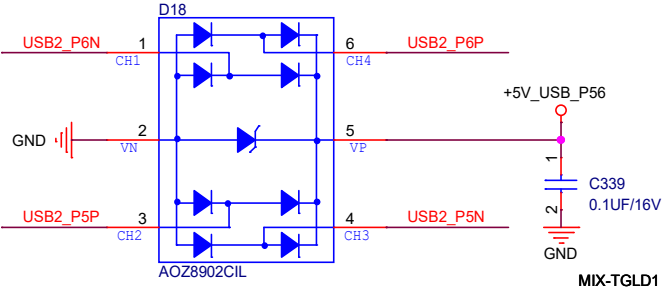
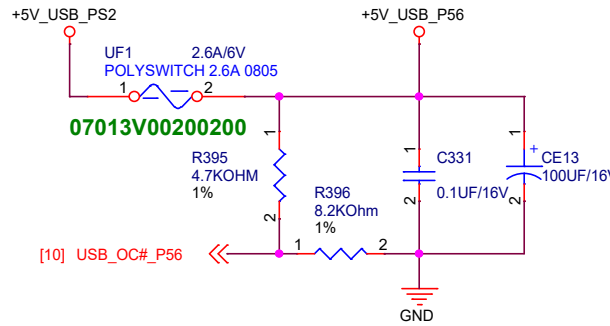
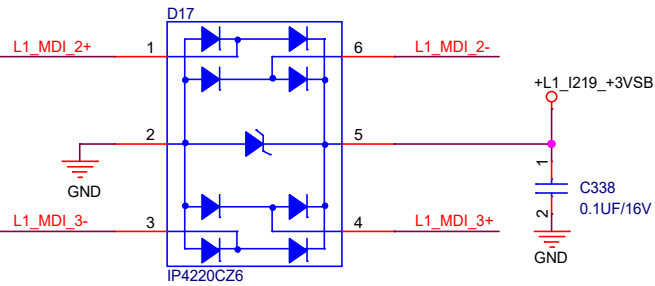
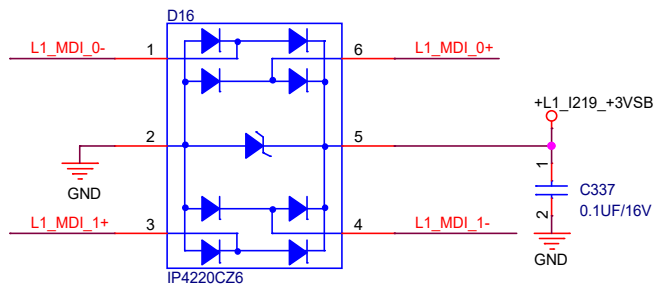
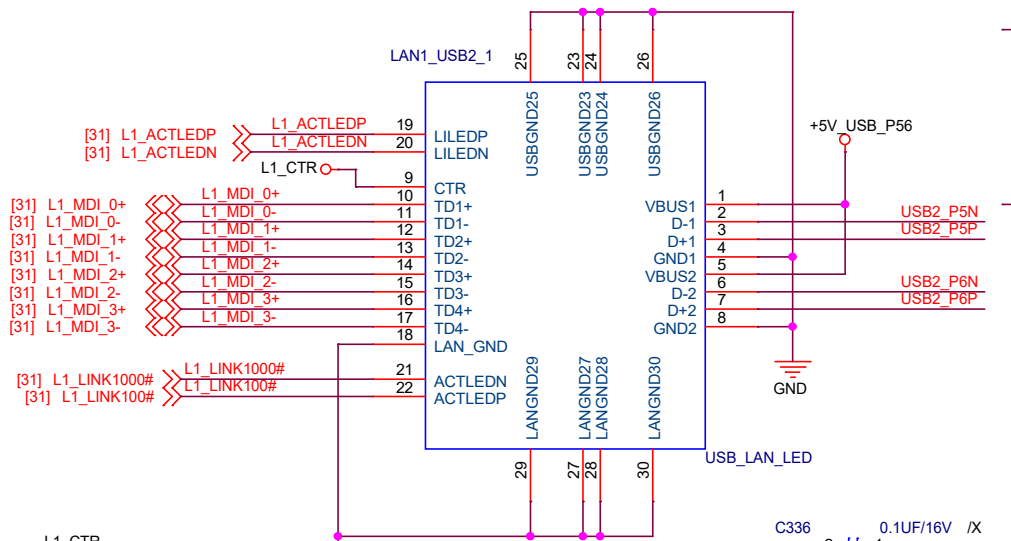
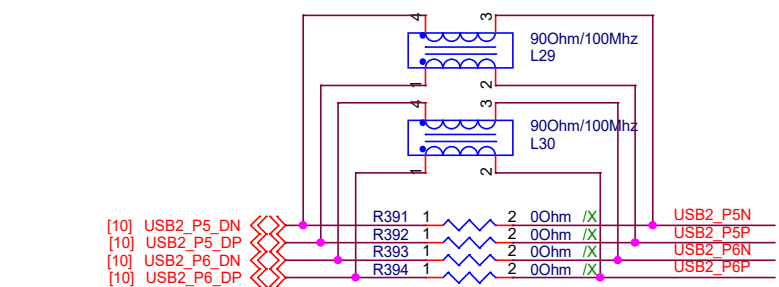




MIX-TGLD1



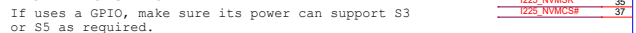
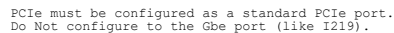




MIX-TGLD1

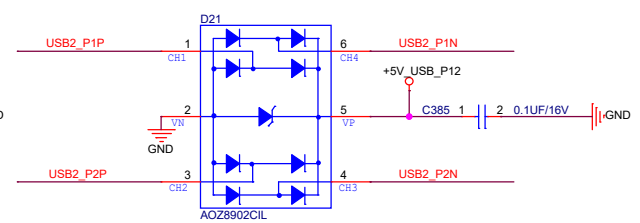
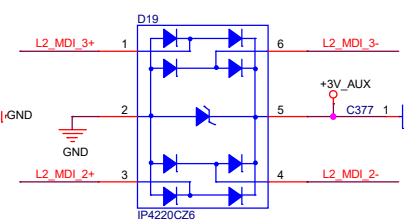
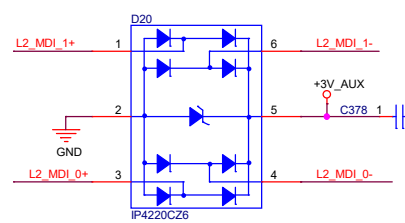
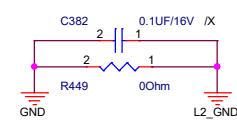
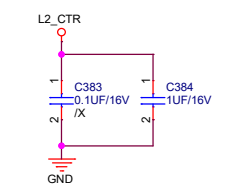
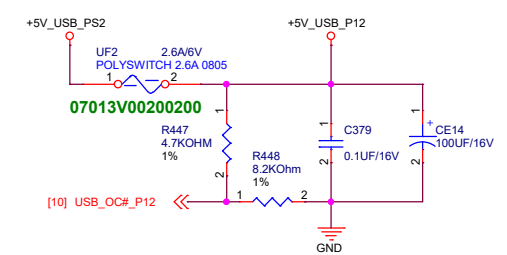
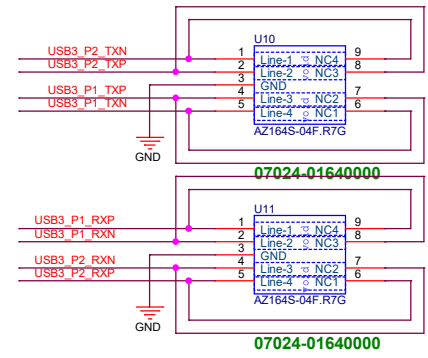
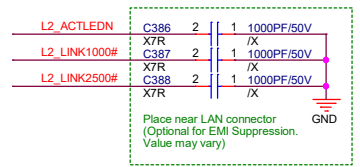
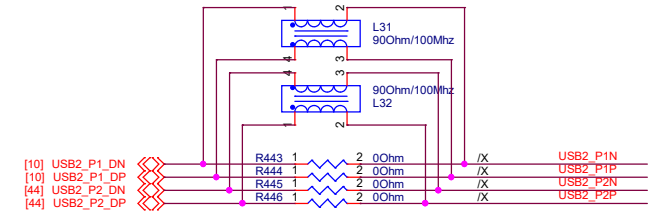
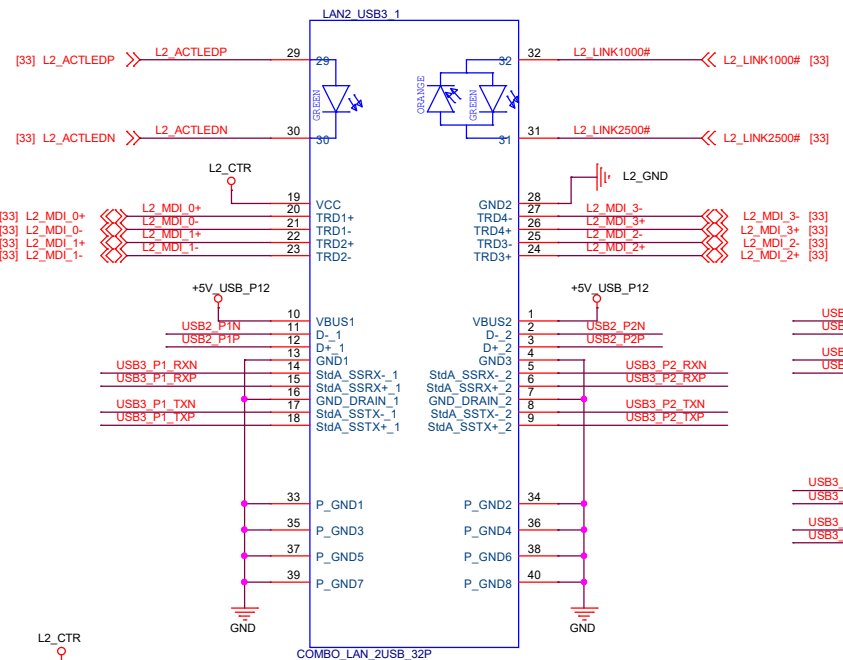
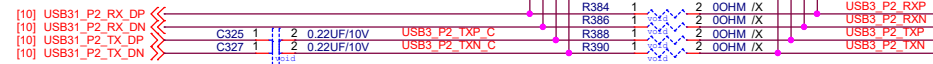
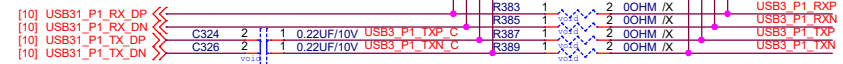
ASUS		Title : LAN1_USB2_56 CON	
ASUSTek COMPUTER INC.		Engineer: <OrgAddr1>	
Size	Project Name	Rev	
Custom	MIX-TLUD1	R1.00	
Date: Wednesday, September 09, 2020		Sheet	32 of 59

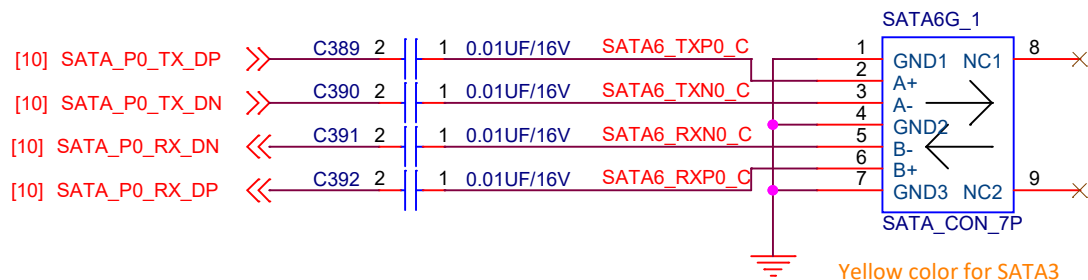
```
> For non-vPro platforms: standard PCIe device: SMBUS is not required (2.2K-10K pull-ups to +3.3V_LAN).
> For vPro platforms: I225 SMBUS must connect to PCH's SMLINK0
> The pull-up power rail should be same with PCH's SMLINK0 power rail (to avoid leakage current)
> Foxville SMBUS speed default is 1MHz. The pull-ups should be 499ohm for 1MHz.
(Use 2.2Kohm if running 400KHz speed and 10Kohm if running 100KHz speed).
> I225 default SMBUS Address is 0x49.
```



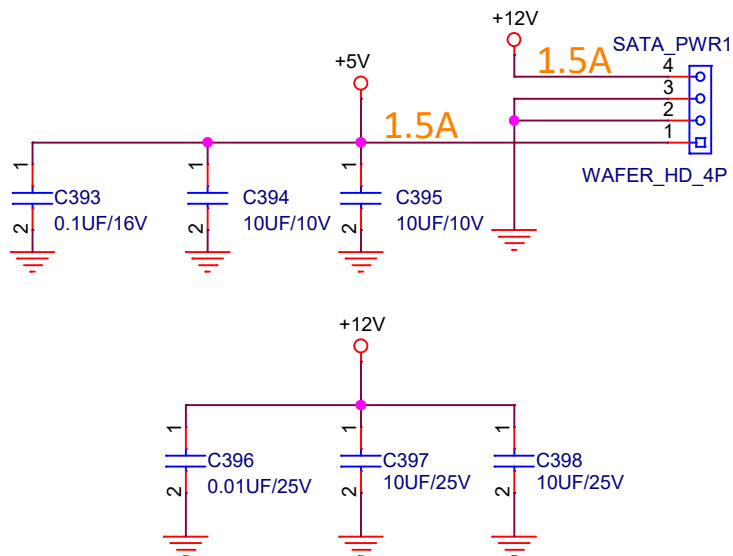
There is no specific industrial standard for Ethernet LEDs.
This schematic just shows the most common SPEED LED configuration:
Highest Speed = Green
2nd Highest Speed = Yellow
All other lower Speeds = OFF
No Cable/Link = OFF
All LED pins are set active low. See Datasheet for additional info.

Connect I225's LAN_DISABLE_N to PCH's GPIO output is optional.
(Do not config as PCH's LANPHYPC, which is I219 specific).

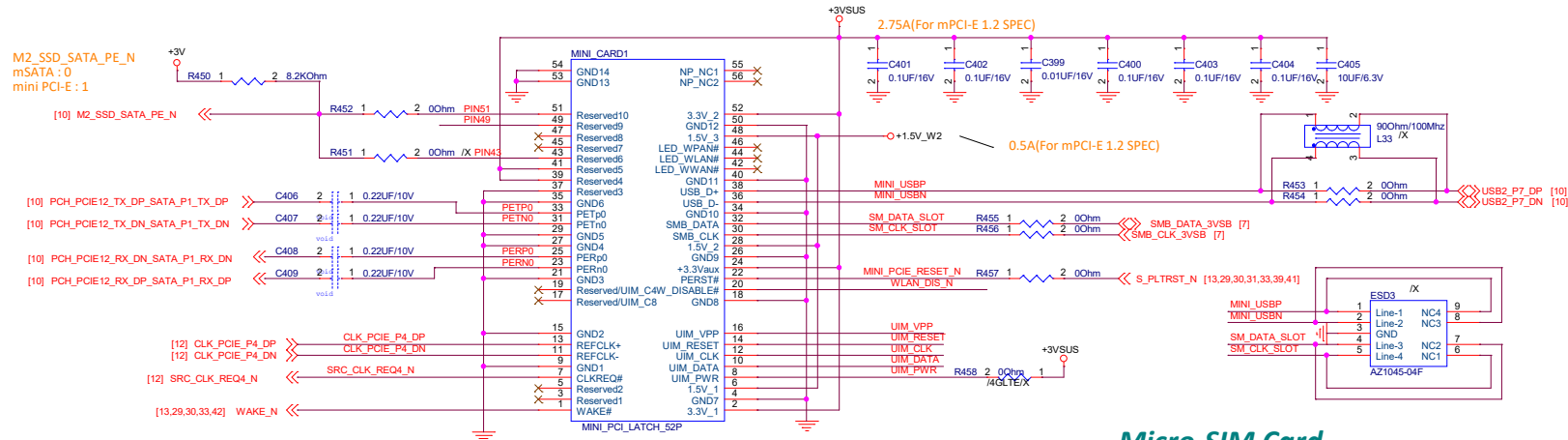




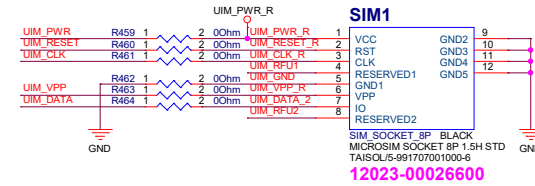
For SATA PWR



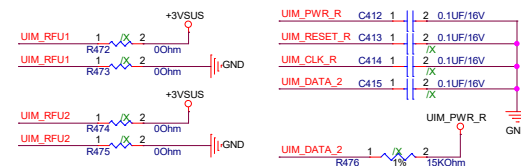
Mini PCI-E Card (Full size)



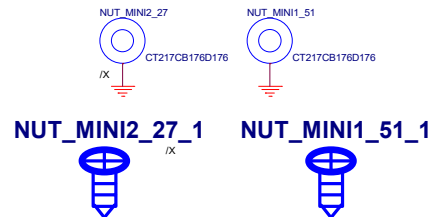
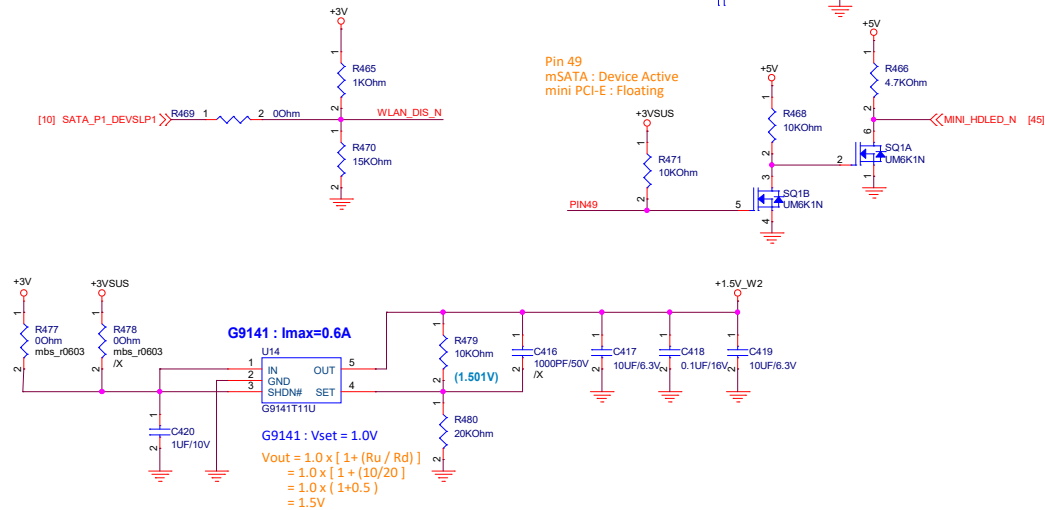
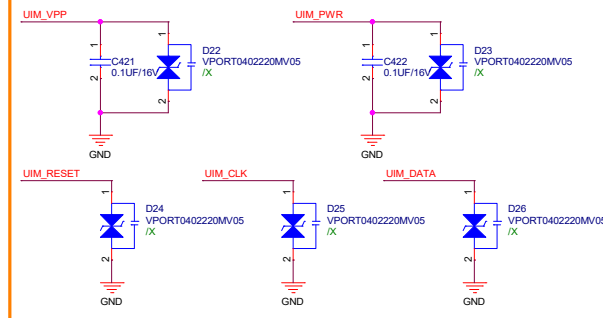
Micro-SIM Card

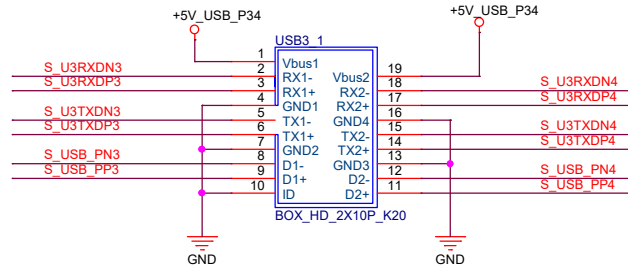
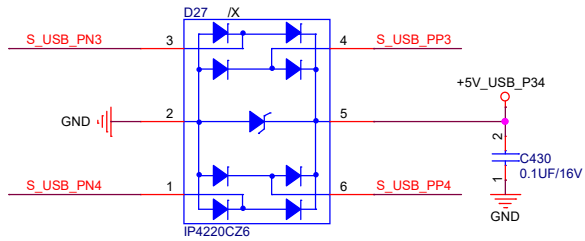
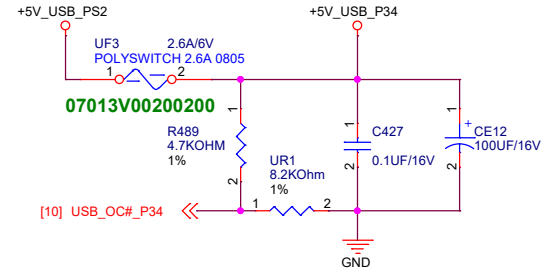
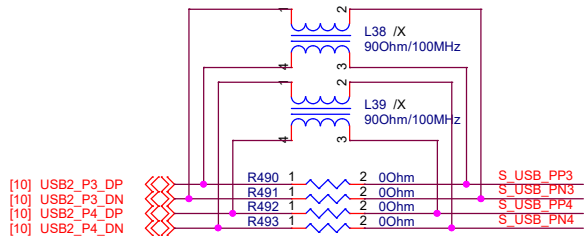
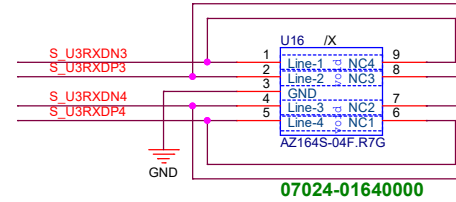
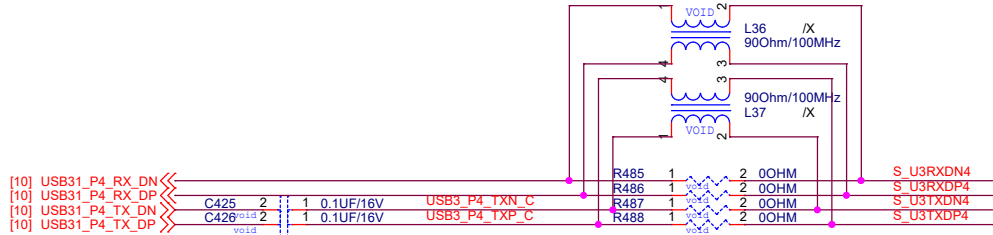
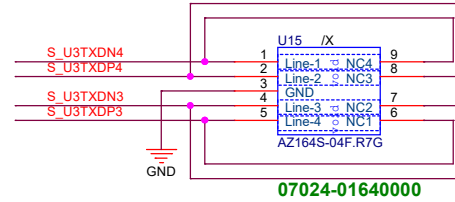
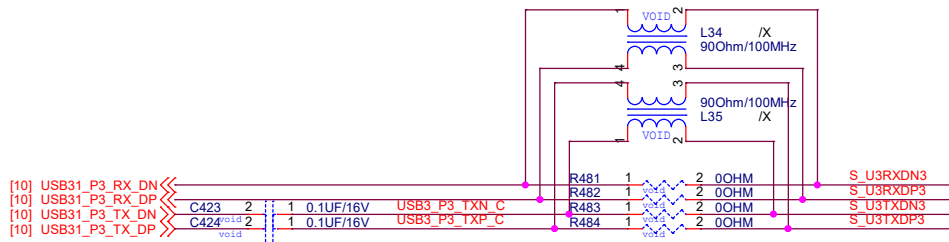


Micro-SIM Card - Reserved Pin for Signal Quality



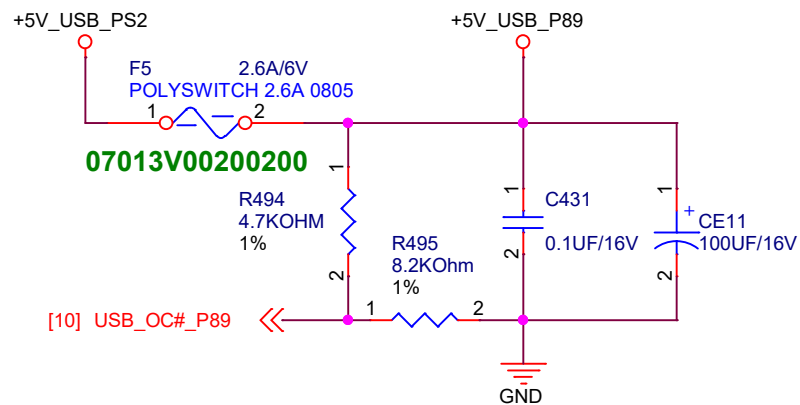
Micro-SIM Card - ESD Protection



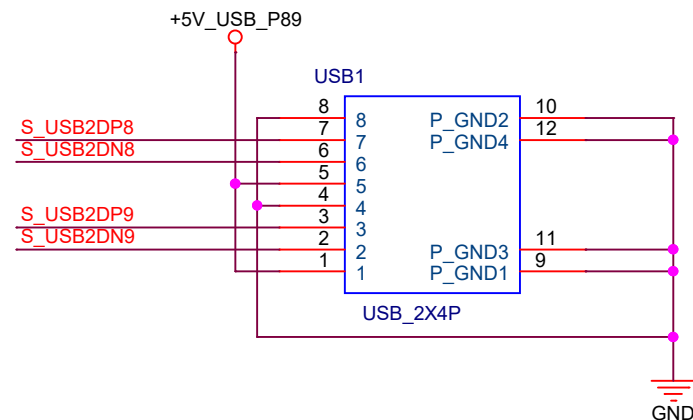
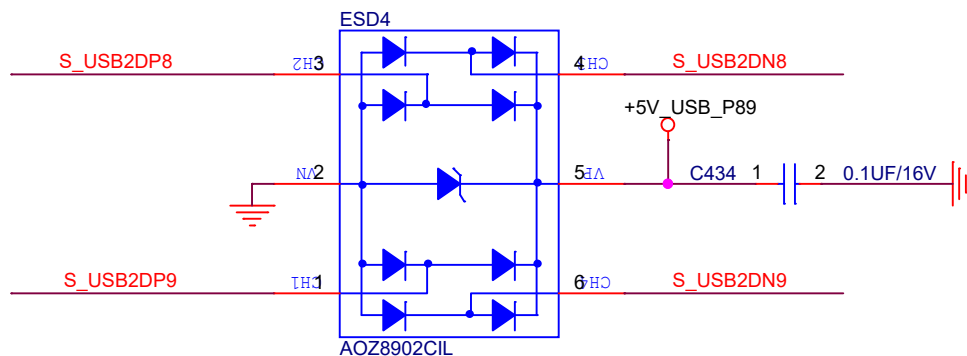
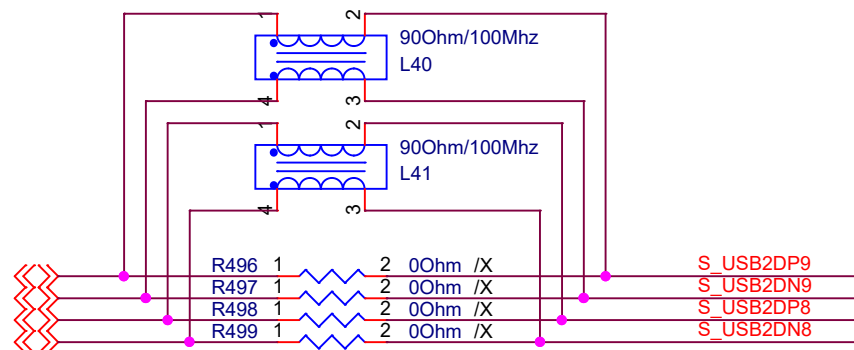


MIX-TGLD1

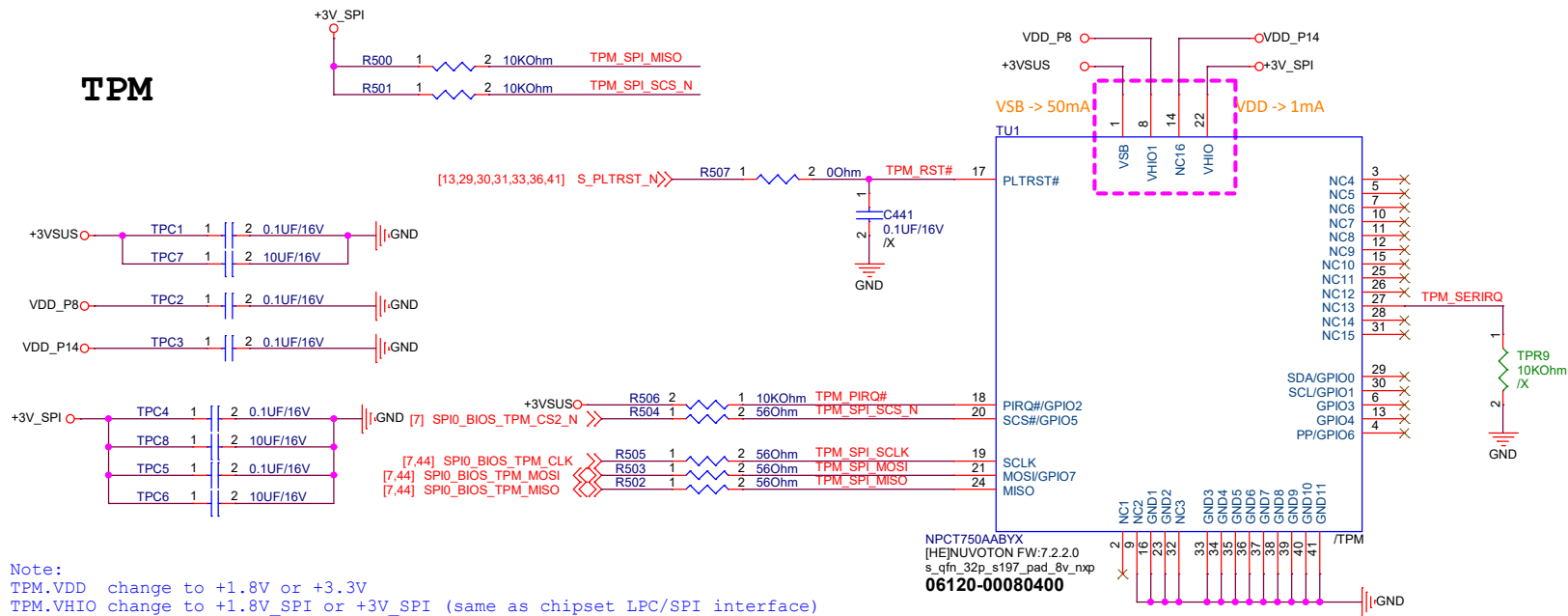
ASUS		Title : USB3_34 BUS HEADER	
ASUSTek COMPUTER INC.		Engineer: <OrgAddr1>	
Size B	Project Name MIX-TLUD1		Rev R1.00
Date: Wednesday, September 09, 2020		Sheet 37 of 59	



[10] USB2_P9_DP
[10] USB2_P9_DN
[10] USB2_P8_DP
[10] USB2_P8_DN

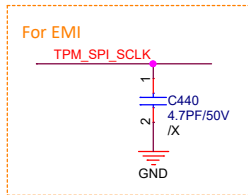


TPM



Note:
 TPM.VDD change to +1.8V or +3.3V
 TPM.VHIO change to +1.8V_SPI or +3V_SPI (same as chipset LPC/SPI interface)

TPM 2.0



(Pin.18) PIRQ#
It should be connected to one of PIRQ[A:D]# of Chipset inputs

(Pin.27) SERIRQ
for LPC interface use only

```
(Pin.17) SPI_RST#
        PCI_system_reset used for LPC/SPI bus (Hardware reset)
```

(Pin.4) PP (Physical Presense Input)
By default the PP functionality is disabled.

GPIO[0:6] and PP are optional.
Leave them open if not used.

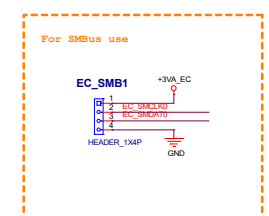
GPIO[0] contact to SLP_S0# for Connected Standby, if supported.

Windows10 Hardware Compatibility Specifications for RS3

Mandatory: The TPM interrupt pin must be connected to an interrupt controller.

	NPCT650	NPCT750
TPR6	X	V
TPR7	V	X
TPR8	V	X
TPR9	V	X

```
06120-00010800  NPCT650ABBYX  TPM2.0  F/W:1.3.1.0
06120-00080200  NPCT750AABYX  TPM2.0  F/W:7.2.1.0
06120-00080400  NPCT750AABYX  TPM2.0  F/W:7.2.2.0
```

Maximum Slew rate control		
SLEW	RS-232	RS-485/RS-422
0	1Mbps	10Mbps
1	250Kbps	250Kbps

The diagram illustrates the wiring for the COM1_V1 (5-6) module. It shows two pin headers: COM1_V1 (5-6) and HEADER_X3P. The COM1_V1 (5-6) header has pins 1 through 6. The HEADER_X3P header has pins 1 through 3. The connections are as follows:

- +5V is connected to pin 1 of COM1_V1 (5-6).
- +12V is connected to pin 2 of COM1_V1 (5-6).
- C494 (0.1uF/16V) is connected to pin 3 of COM1_V1 (5-6).
- C495 (1uF/25V) is connected to pin 4 of COM1_V1 (5-6).
- GND is connected to pin 5 of COM1_V1 (5-6).

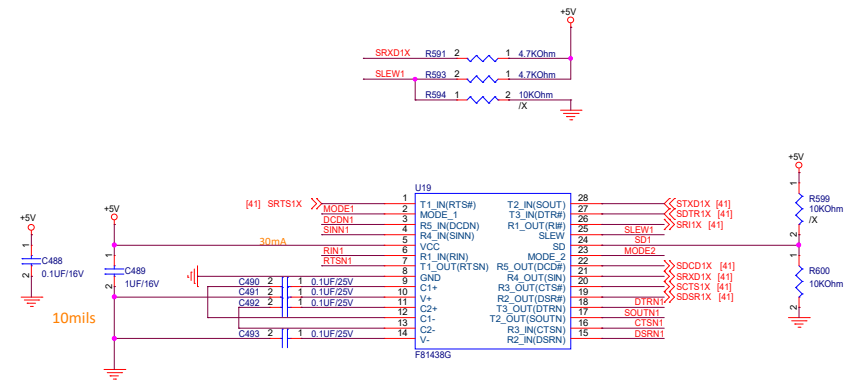
The HEADER_X3P header is connected to the COM1_V1 (5-6) header via a ribbon cable. The ribbon cable has pins 1 through 6. The connections are as follows:

- +5V is connected to pin 1 of the ribbon cable.
- +12V is connected to pin 2 of the ribbon cable.
- R11_VCC_20 is connected to pin 3 of the ribbon cable.
- F7 (1.1A/16V) is connected to pin 4 of the ribbon cable.
- GND is connected to pin 6 of the ribbon cable.

The ribbon cable is labeled COM1_V1 and has a pin 6 connection to GND.

The diagram illustrates the pin connections for the TRS2130BR chip (U28). The chip has 28 pins. The connections are as follows:

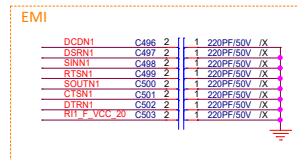
- Pin 1:** CS0# (Chip Select 0) connected to +5V.
- Pin 2:** TXD2 (Transmit Data) connected to RTS2 (Receiver Transmitter Select 2).
- Pin 3:** RTS2 (Receiver Transmitter Select 2) connected to DSR2 (Data Set Ready 2).
- Pin 4:** SDR2X (Serial Data Ready 2) connected to SRTS2X (Serial Receiver Transmitter Select 2).
- Pin 5:** SRTS2X (Serial Receiver Transmitter Select 2) connected to DCD2 (Data Carrier Detect 2).
- Pin 6:** DCD2 (Data Carrier Detect 2) connected to RXD2 (Receive Data 2).
- Pin 7:** RXD2 (Receive Data 2) connected to DTR2 (Data Terminal Ready 2).
- Pin 8:** DTR2 (Data Terminal Ready 2) connected to TXD2 (Transmit Data 2).
- Pin 9:** TXD2 (Transmit Data 2) connected to RTS2 (Receiver Transmitter Select 2).
- Pin 10:** RTS2 (Receiver Transmitter Select 2) connected to DSR2 (Data Set Ready 2).
- Pin 11:** DSR2 (Data Set Ready 2) connected to RI2 (Ring Indicator 2).
- Pin 12:** RI2 (Ring Indicator 2) connected to DCD2 (Data Carrier Detect 2).
- Pin 13:** DCD2 (Data Carrier Detect 2) connected to RXD2 (Receive Data 2).
- Pin 14:** C1+ (Chip Select 1) connected to +5V.
- Pin 15:** C2+ (Chip Select 2) connected to +5V.
- Pin 16:** C1- (Chip Select 1) connected to +5V.
- Pin 17:** C2- (Chip Select 2) connected to +5V.
- Pin 18:** RNS (Receive Noise Sense) connected to CS14 (Chip Select 14).
- Pin 19:** CS14 (Chip Select 14) connected to +5V.
- Pin 20:** CS15 (Chip Select 15) connected to +5V.
- Pin 21:** CS16 (Chip Select 16) connected to +5V.
- Pin 22:** CS17 (Chip Select 17) connected to +5V.
- Pin 23:** CS18 (Chip Select 18) connected to +5V.
- Pin 24:** CS19 (Chip Select 19) connected to +5V.
- Pin 25:** CS20 (Chip Select 20) connected to +5V.
- Pin 26:** CS21 (Chip Select 21) connected to +5V.
- Pin 27:** CS22 (Chip Select 22) connected to +5V.
- Pin 28:** CS23 (Chip Select 23) connected to +5V.



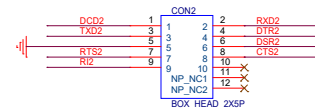
[8] COM1_MODE1 >> R609 1 2 0Ohm MODE1

[8] COM1_MODE2 >> R610 1 2 0Ohm MODE2

Mode_1 and Mode_2 pin. Internal pull high $\approx 625K\Omega$. As the current is very small ($\approx 15\mu A$), please use the hardware strapping or GPIO (BIOS) to select the modes.

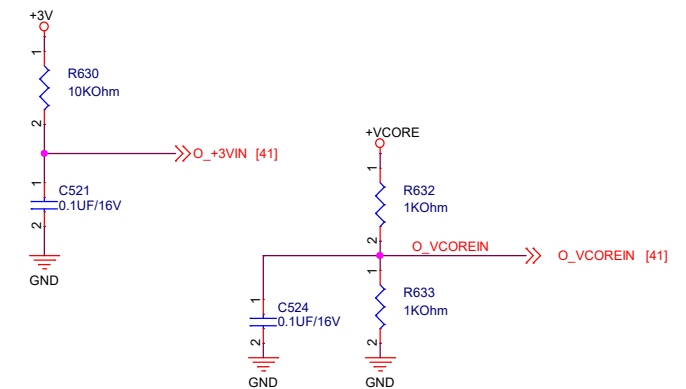
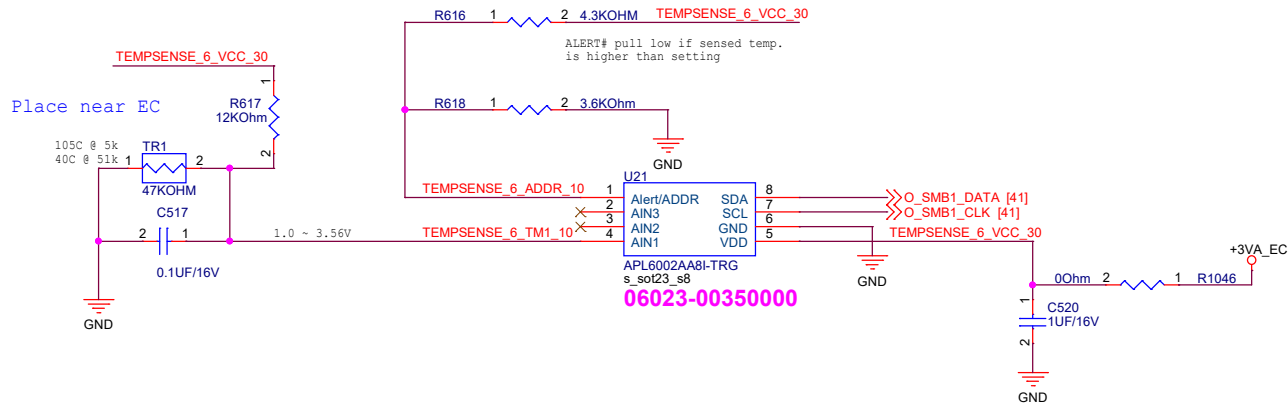


The schematic diagram illustrates the Wake-up circuit for the ATmega328P. It features a +3V supply connected to a 19KOhm resistor (R1004). The other end of R1004 is connected to a node labeled 'w'. This node is also connected to a 100nF capacitor (C1001) to ground and a 47KOhm resistor (R1005) to a node labeled '2'. Node '2' is connected to the anode of diode Q50A (505A UM8K-1N). The cathode of Q50A is connected to ground. The anode of diode Q50B (505A UM8K-1N) is connected to a node labeled '5', which is also connected to a 47KOhm resistor (R1007) to ground. The cathode of Q50B is connected to ground. The output of the circuit is labeled WAKE_N [13,29,30,33,36].

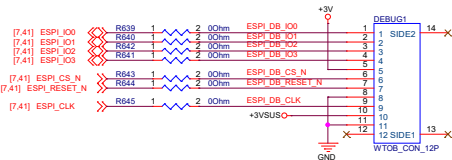


Thermal Sensor

Address	0x7E	0x7C	0x7A	0x78	0x76	0x74	0x72	0x70
0R172	10k	1.5k	2k	3.6k	3.9k	4.3k	5.1k	6k
0R173	Open	8.2k	6.2k	6.8k	4.7k	3.6k	2.7k	2k



DEBUG PORT

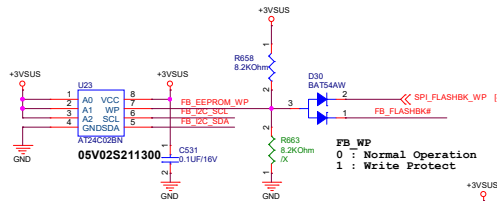


SPI Interface

Strapping table

PWRSUS#	SW1#	BCS1	BCS0	Function
0	0 (3 sec)	x	x	Flash back-up
0	1	0	0	SB USB function
0	1	0	1	BCD port
0	1	1	0	Short D+/D- (<200 ohm)
SS State	0	1	1	Apple charger
1	x	0	0	SB USB function
1	x	0	1	BCD port
1	x	1	0	Short D+/D- (<200 ohm)
SD State	1	x	1	Apple charger

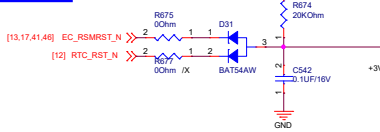
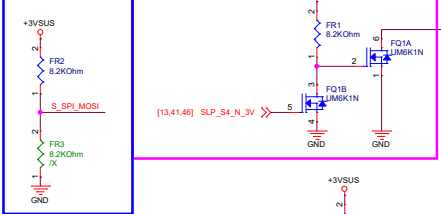
Strapping pin	Function
TESTN	0: Test mode; 1: Functional mode
SPI_CS#	0: Test mode; 1: Normal update mode; 2: Normal update mode
S_SPI_MOSI	0: 4byte address mode; 1: 3byte address mode
UART_TX, S_SPI_MISO	0: 3bit SI mode
UART_TX, S_SPI_MISO	2700, 2800, 2900: Flashback mode



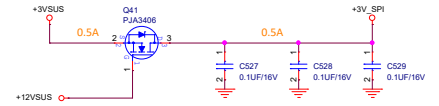
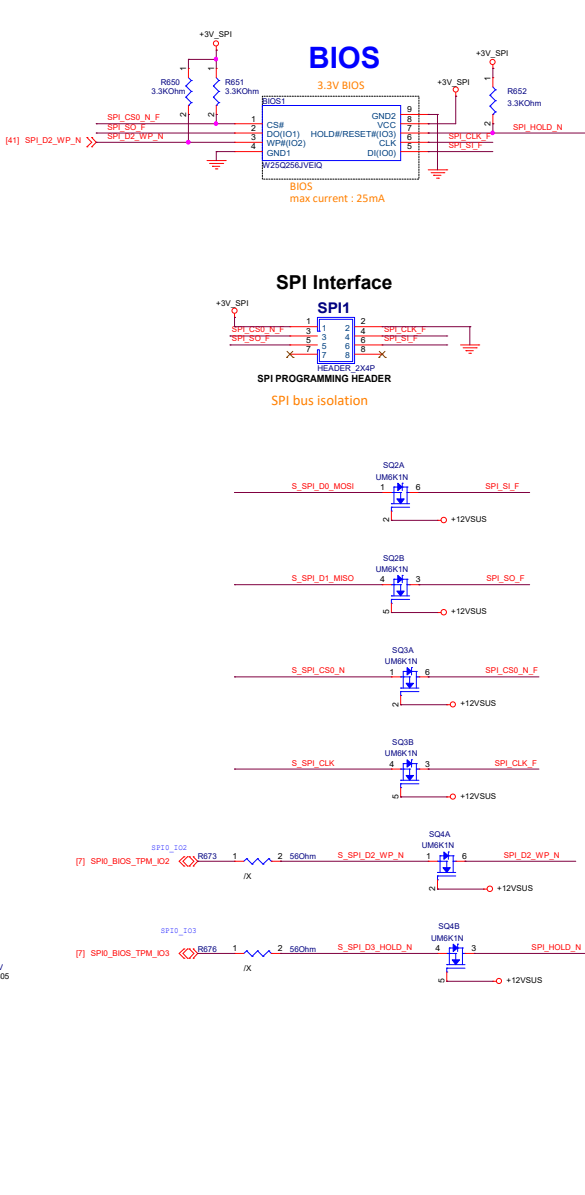
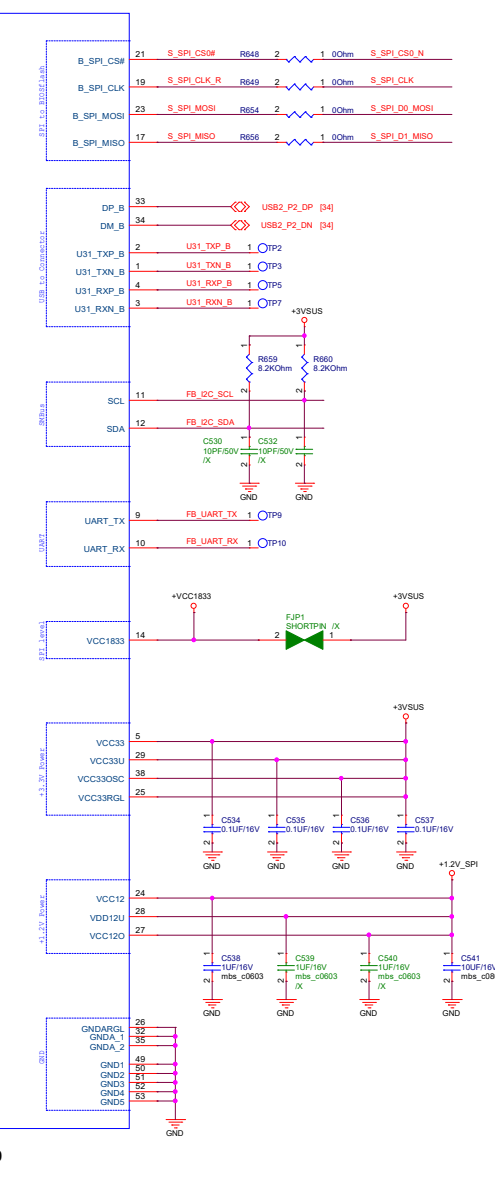
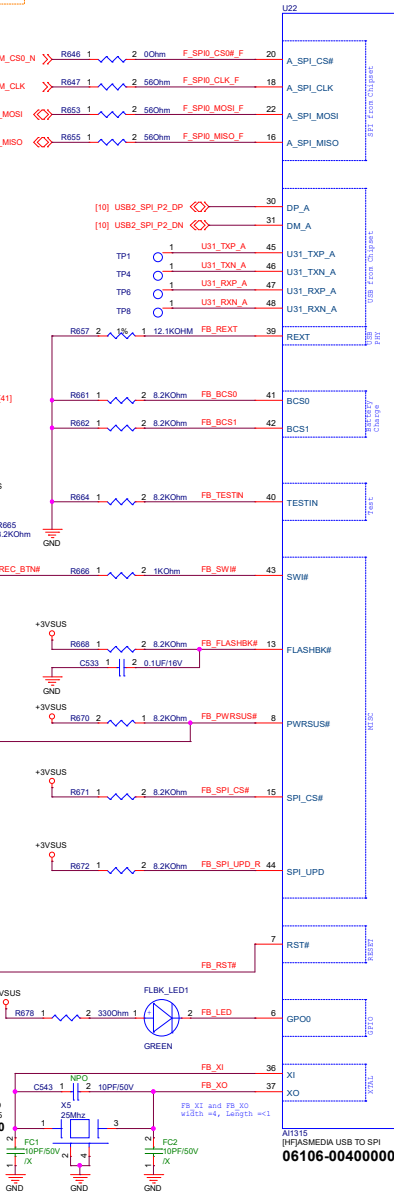
USB pattern strapping

選A1H315 USB眼罩
FR40 + FR41上件
再按flashback按鈕3秒
即會發pattern.

address mode

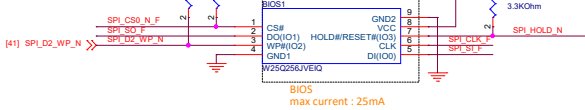


SWARDXLT51150-A180-259 SMD
XTAL 25MHz 16PF/10PPM 3.2*2.5
07009-00024900

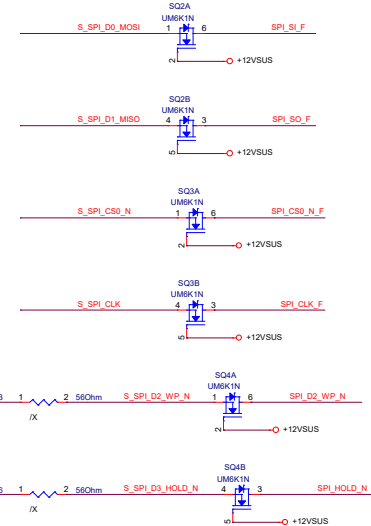
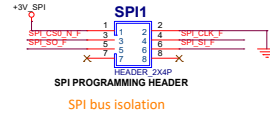


BIOS

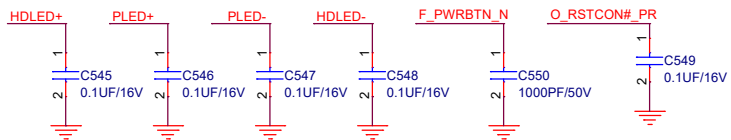
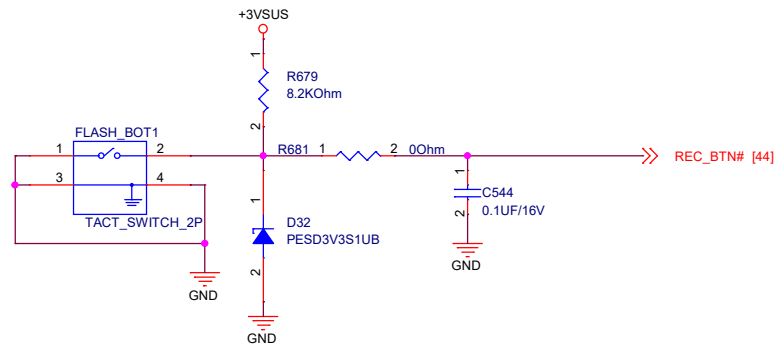
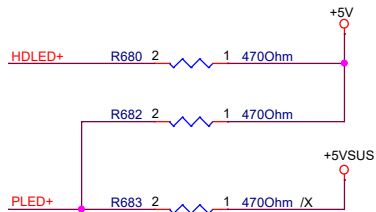
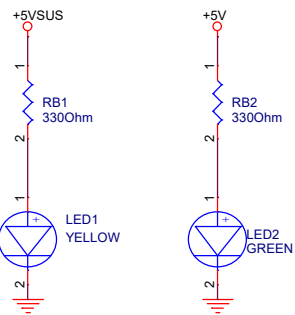
3.3V BIOS



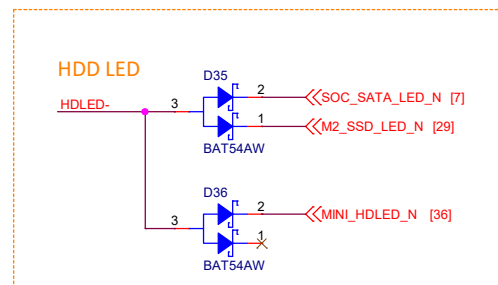
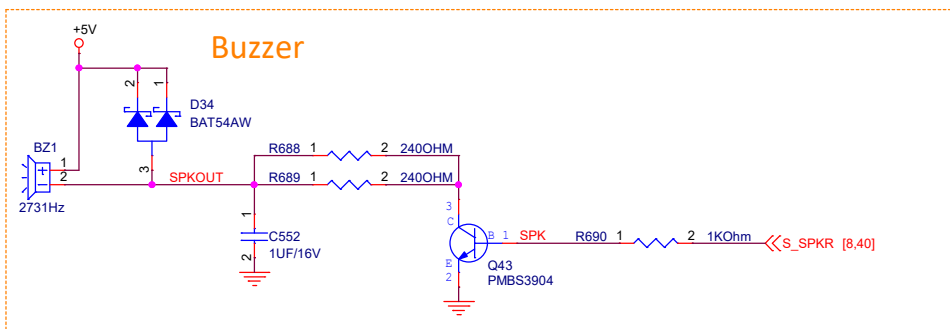
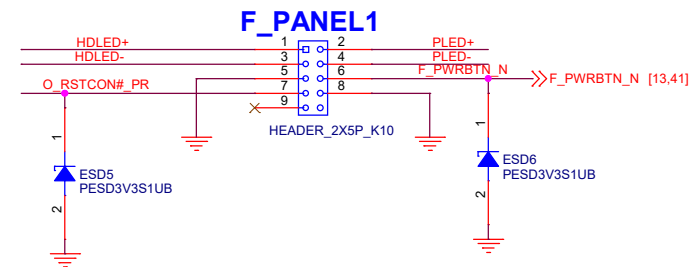
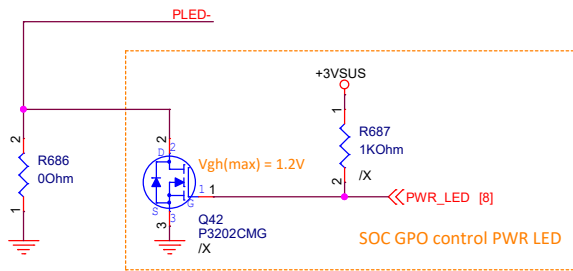
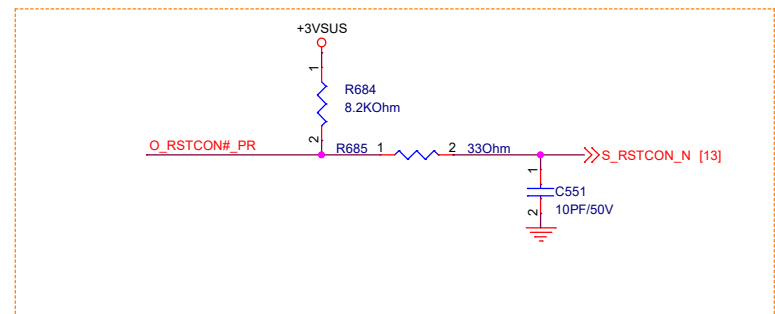
SPI Interface



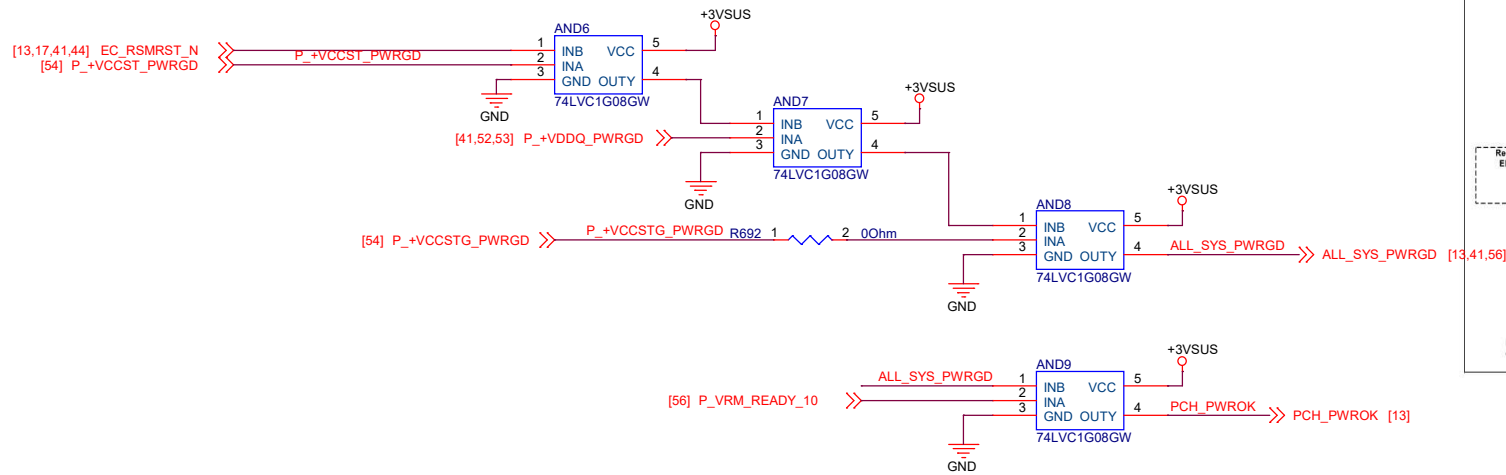
MIX-TLUD1



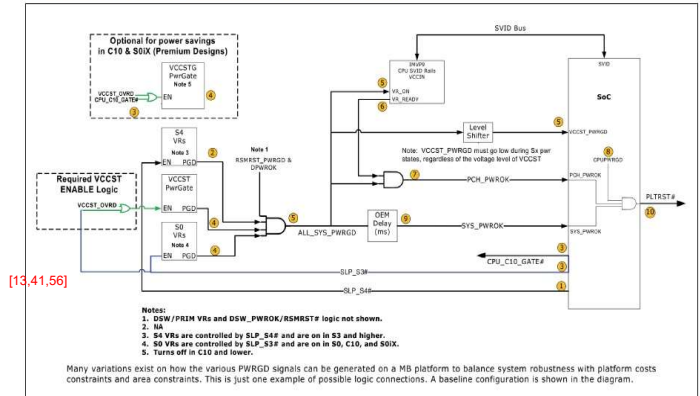
PLACE NEAR PANEL or FPANEL



Tiger Lake PWROK Sequence

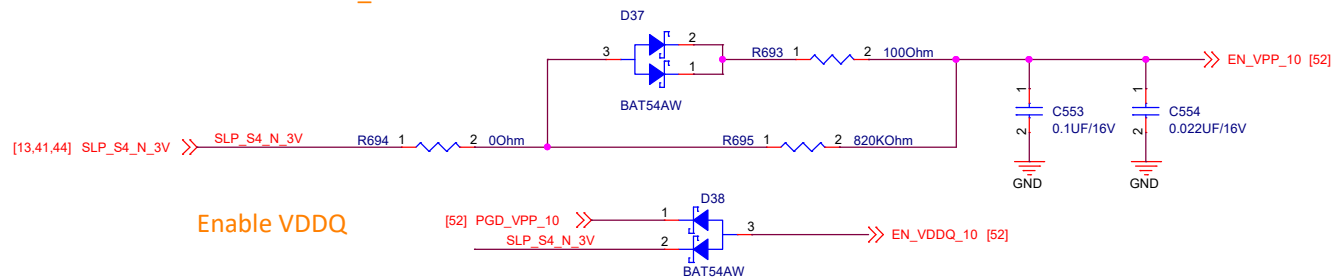


Premium PWROK Generation Flow Diagram



PWR DDR4 Power Sequence

VPP_EN

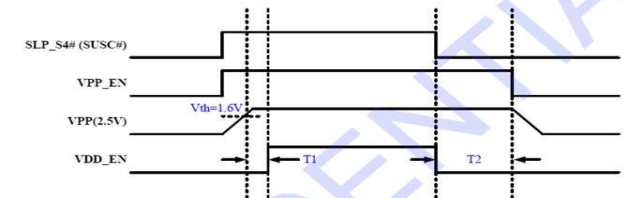


11.21 DDR4 Power Control Specification

Table 11-5. DDR4Timings Parameter

Symbol	Typ.	Description
T ₁	5ms	The rising edge of VPP(2.5V) to rising edge of VDD_EN
T ₂	50ms	The falling edge of VDD_EN to rising edge of VPP(2.5V)

Figure11-27. DDR4 Power Control Timings

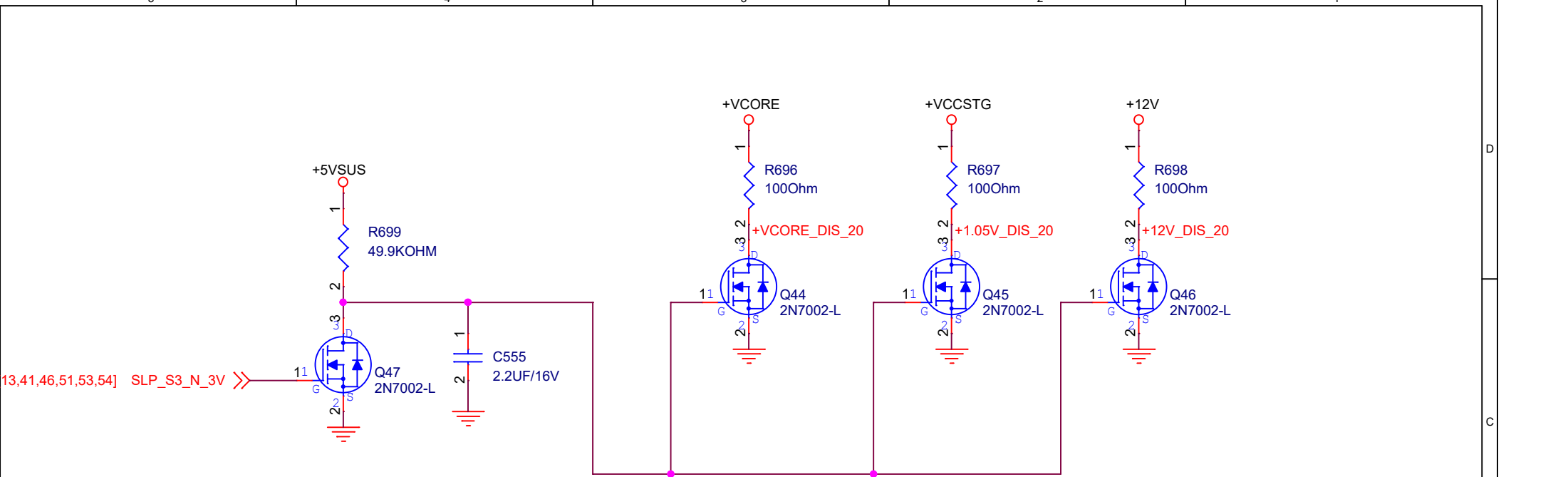


Power Down Sequence



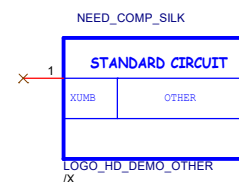
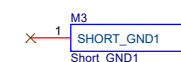
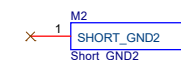
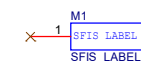
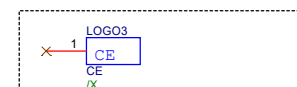
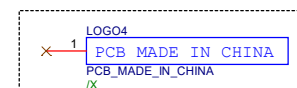
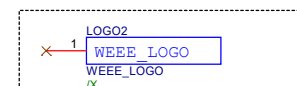
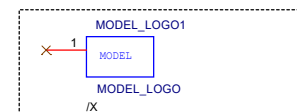
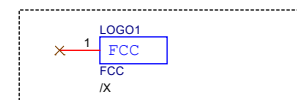
MIX-TGLD1

ASUS		Title : DDR4/PWROK_SEQUENCE	
ASUSTek COMPUTER INC.		Engineer: <OrgAddr1>	
Size B	Project Name MIX-TLUD1	Rev R1.10	
Date: Wednesday, September 09, 2020		Sheet	46 of 59



Logo

common Logo for all projects

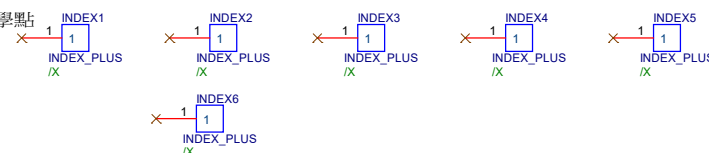


Fiducial Mask (光學點)

光學點需要 6 ~ 10 顆,
LayoutRD會依空間大小及版本需求
擺放所需的光學點
所以兩種光學點都需畫入線路中,
最後再做刪除.

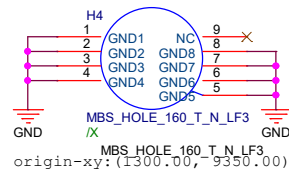
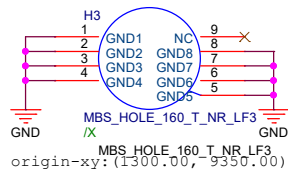
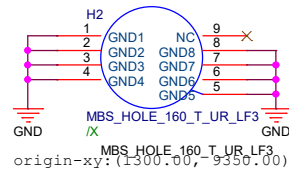
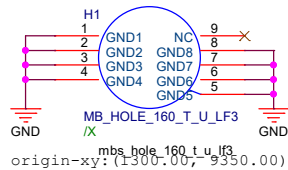
大顆十字光學點

小顆十字光學點



MIX-TGLD1

ASUS		Title : Selling Point Logo	
ASUSTek COMPUTER INC.		Engineer: <OrgAddr1>	
Size A3	Project Name MIX-TLUD1	Rev R1.00	
Date: Wednesday, September 09, 2020		Sheet 48	of 59



m-ATX Screw Select

	Standard (9.6 x 9.6)	Scale down (9.6 x <9.6)
H1	V	V
H2	V	V
H3	V	V
H4	V	V
H5	V	V
H6	V	V
H7	V	X
H8	V	X
H20	V	V

MB SCREW FOOTPRINT

MB_HOLE_160_T_LF3



MB_HOLE_160_T_U_LF3



MB_HOLE_160_T_R_LF3



MB_HOLE_160_T_UR_LF3

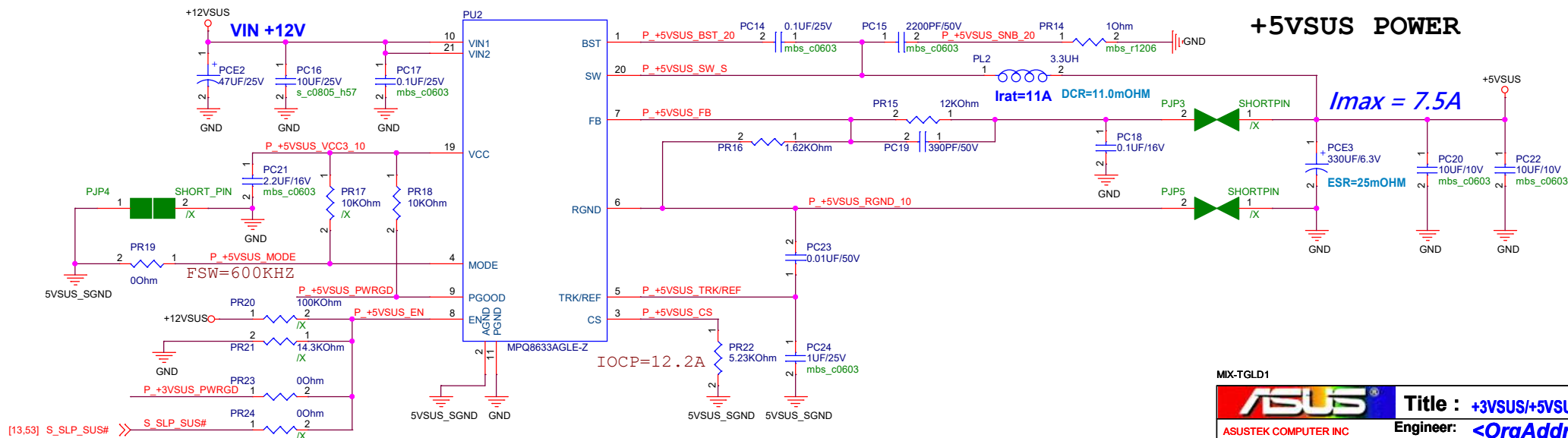
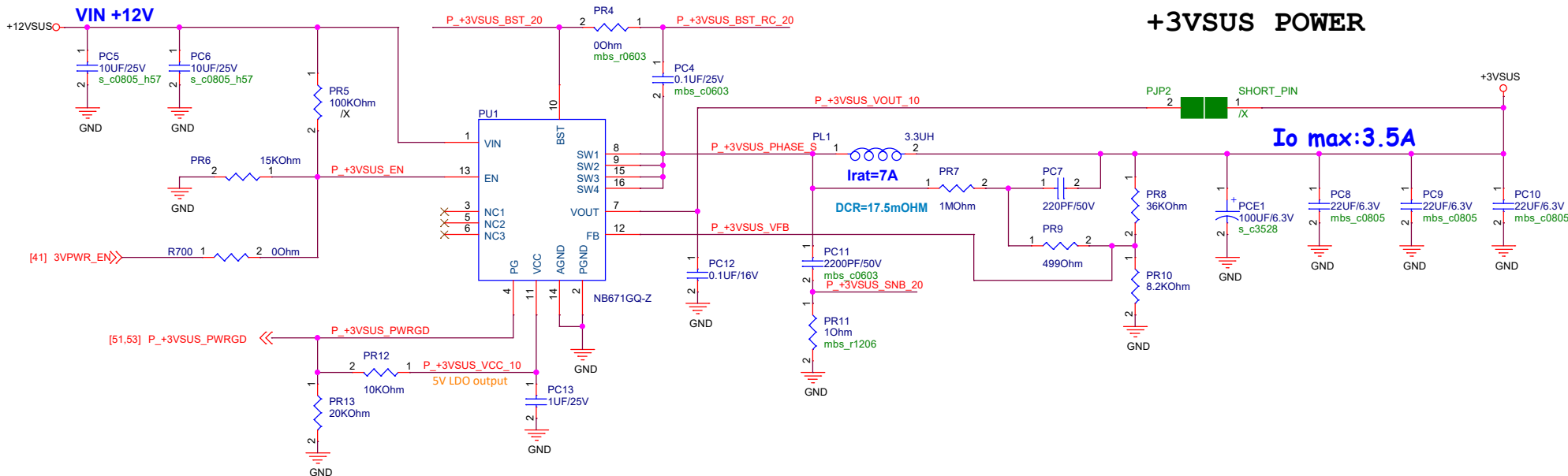


PCB1



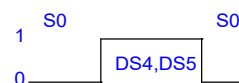
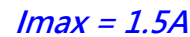
MIX-TLUD1

08001-16030000



MIX-TGLD1

		Title : +3VSUS/+5VSUS	
ASUSTEK COMPUTER INC		Engineer: <OrgAddr1>	
Size B	Project Name MIX-TLUD1		Rev R1.00
Date: Wednesday, September 09, 2020		Sheet	50 of 59

$$I_{max} = 3.5A$$


[50,53] P_+3VSUS_PWRGD >> P_+3VSUS_PWRGD



+12V Power Good



Engineer: **<OrgAddr1>**

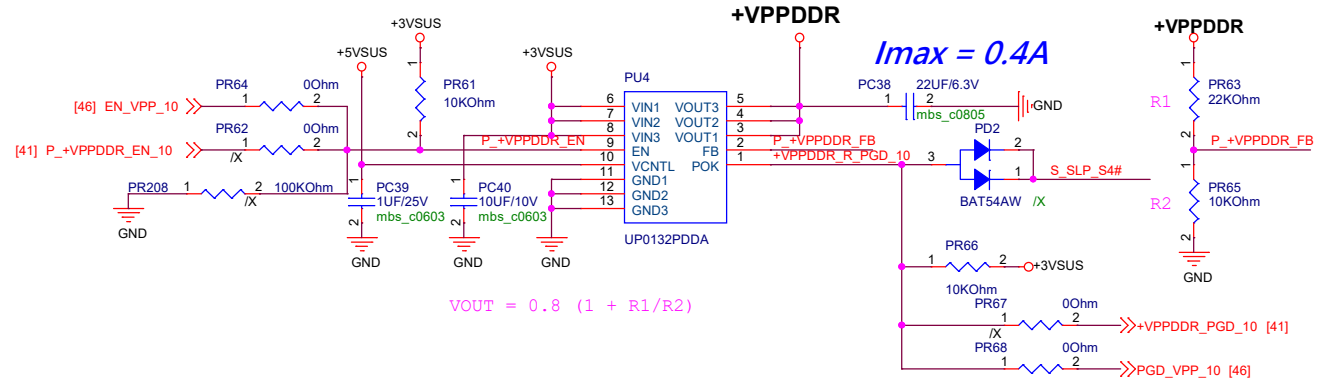
Author Name	Rev
-------------	-----

Custom	MIX-TLUD1	R1.00
--------	------------------	-------

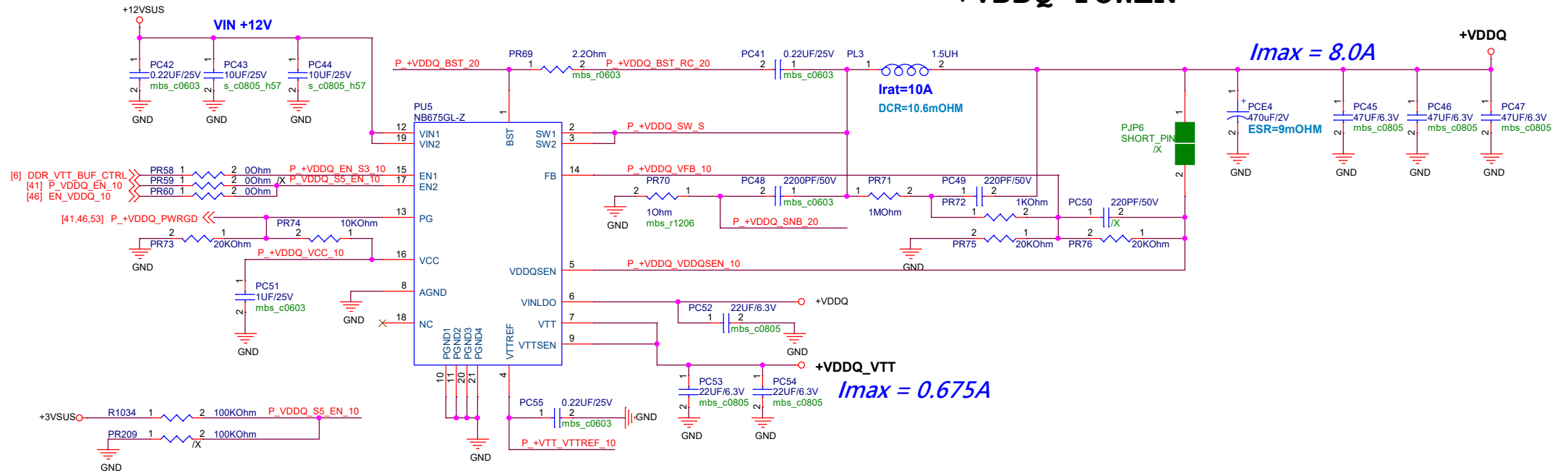
Date: **Wednesday, September 09, 2020** Sheet **51** of **59**

S3 And S5 Truth Table

State	EN1	EN2	VDDQ	VTTREF	VTT
S0	Hi	Hi	On	On	On
S3	Low	Hi	On	On	Off (Hi-Z)
S4/S5	Low	Low	Off	Off	Off
OTHERS	Hi	Low	Off	Off	Off

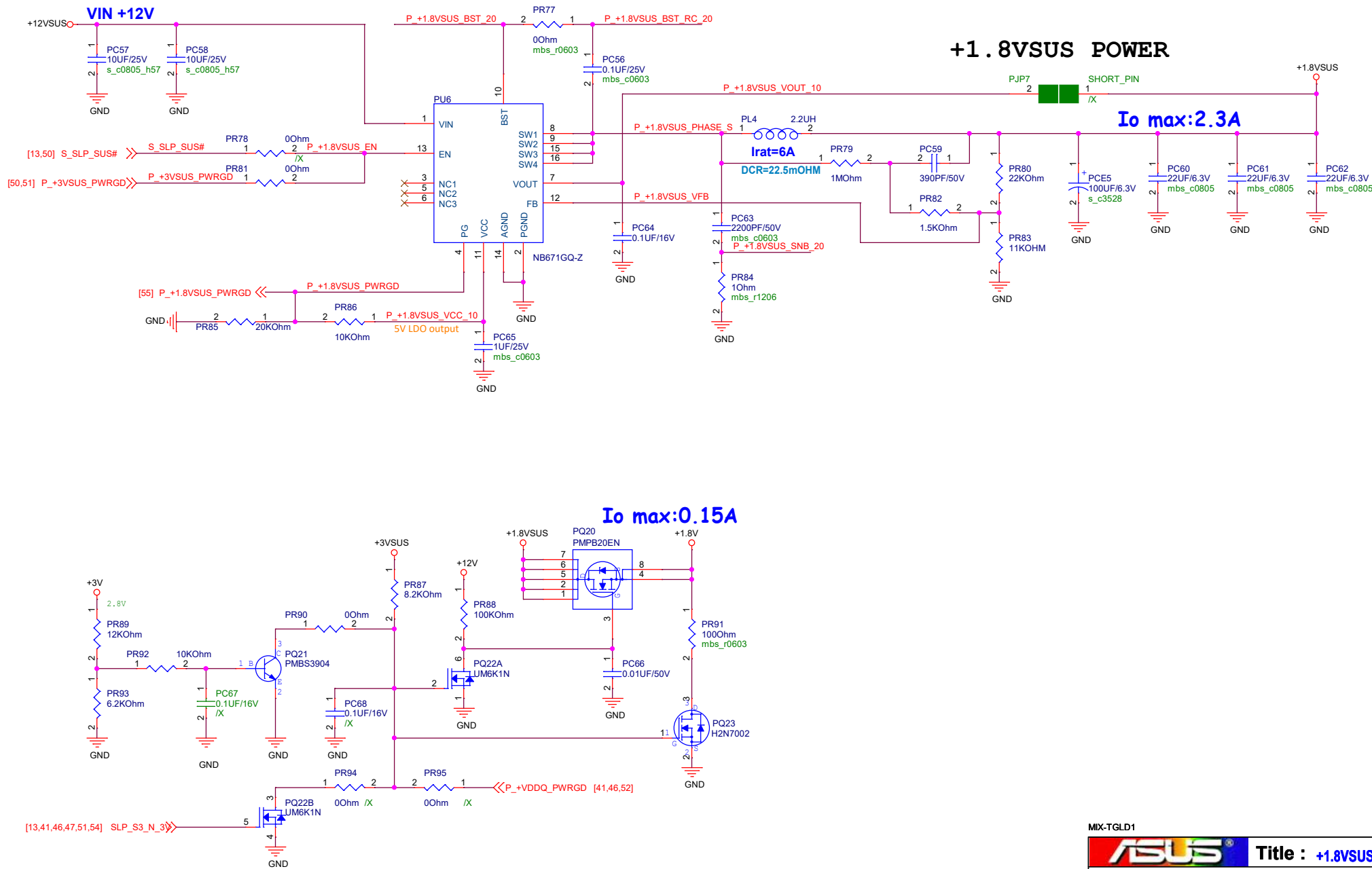


+VDDQ POWER



MIX-TGLD1

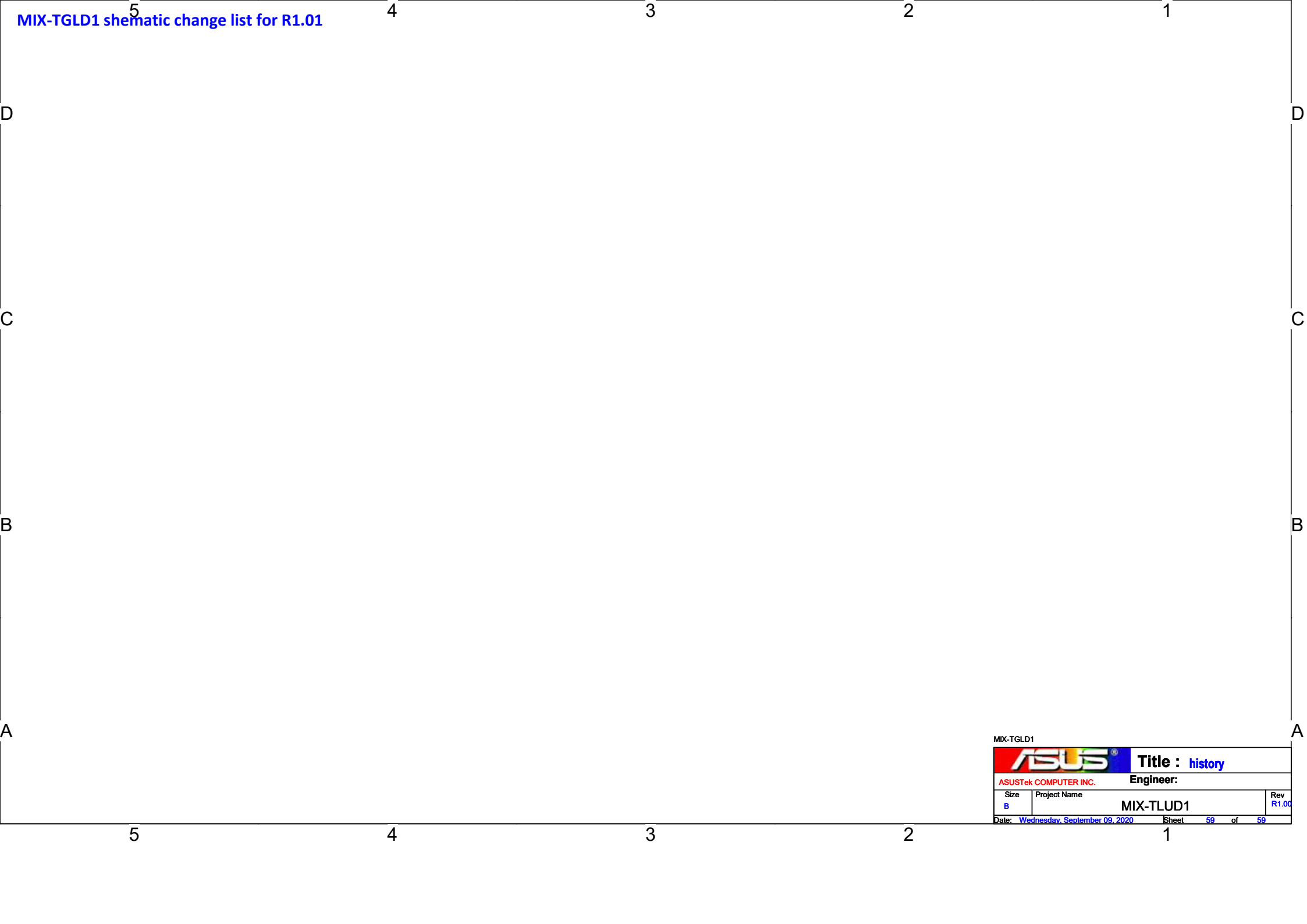
ASUS		Title : +VDDQ/+VPPDDR	
ASUSTEK COMPUTER INC		Engineer: <OrgAddr1>	
Size B	Project Name MIX-TLUD1	Rev R1.00	
Date: Wednesday, September 09, 2020		Sheet 52 of 59	




MIX-TGLD1

ASUS		Title : +1.8VSUS/+1.8V	
ASUSTEK COMPUTER INC		Engineer: <OrgAddr1>	
Size	Project Name	Rev	Rev
B	MIX-TLUD1	R1.00	R1.00
Date: Wednesday, September 09, 2020		Sheet 53 of 59	

Name	VccIN	VccIN_AUX	VDD2	VTT	VccST	VccSTG	VCCPRIM_1P8	VCCPRIM_3P3	VCCDSW_3P3	5V_USB_PS2	3VSUS	12V	5V	3V	+1.1V_HDMI1	1.5V
Power Voltage	2V	1.8V	1.2V	0.6V	1.05V	1.05V	1.8V	3.3V	3.3V	5V	3V	12V	5V	3V	1.1V	1.5V
TGL PUS+PCH	65	27	1.5		0.3	0.5	1.3	0.202	0.008							
DDR4 (SO-DIMM)			5.2	0.4												
DIMM_A1																
DDR3 (SO-DIMM)			5.2	0.4												
DIMM_B1																
LAN E219											0.3					
LAN E210/E211											1.3					
USB2.0 x9										4.5						
USB3.0 x4										6						
HDMI (SN75DP159) x2														0.084	0.46	
FAN x2												2				
PCIe x4 slot											0.375	2.1		3		
M.2 M-key (2280)														0.4		
Mini PCIe Card											2.75					0.5
STAT Power												1.5	1.5			
AUDIO ALC887														0.012		
SPI (AH1315)											0.086					
EC (T5121E)																
TPM 2.0 (NPCT58AAAYD)											0.05					
Voltage (UNIT:V)	2	1.8	1.2	0.6	1.05	1.05	1.8	3.3	3.3	5	3	12	5	3	1.1	1.5
TOTAL CURRENT (UNIT:A)	65	27	11.9	0.8	0.3	0.5	1.3	0.202	0.008	10.5	4.811	5.6	1.5	3.446	0.46	0.5
TOTAL WATT (UNIT : W)	130	48.6	14.28	0.48	0.315	0.525	2.34	0.6666	0.0099	52.5	14.493	67.2	7.5	10.338	0.506	0.75
TRANSFER VOLTAGE	+12VSUS	+12VSUS	+12VSUS	+12VSUS	SOC	SOC	+1.8VSUS	+3VSUS	+3VSUS	+5VSUS	+12VSUS	+12VSUS	+5VSUS	+3VSUS	+3VSUS	+3VSUS
	12VSUS	5VSUS	3VSUS	1.8VSUS												
	275 W	60 W	12.27 W	2.34 W												
Power supply must consumed watts and currents																
Power Type	DC IN (12V)															
Consumed watts (Item: W)	349.61 W															
Consumed currents (Item A)	29.13 A															
Actually required currents (Item A/0.8)	36.4 A															



MIX-TGLD1		
		Title : history
ASUSTek COMPUTER INC. Engineer:		
Size B	Project Name MIX-TLUD1	Rev R1.00
Date: Wednesday, September 09, 2020 Sheet 59 of 59		